

SM-G781V (R8)

2020. 07. 06

sheet01 :

sheet02 : RF (2/2)

sheet03 : BT/WIFI, SIM

sheet04 : OVP LS, NFC , SENSORS

sheet05 : SM8250

sheet06 : SM8250 POWER/GND, JTAG, UFS

sheet07 : PM8250, PM8150C, PMK8002, IF PMIC

sheet08 : AUDIO

sheet09 : CAMERA

sheet10 : DISPLAY

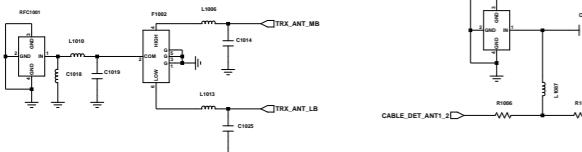
sheet11 : SDX55M(5G MODEM)

sheet12 : PMX55M(5G POWER)

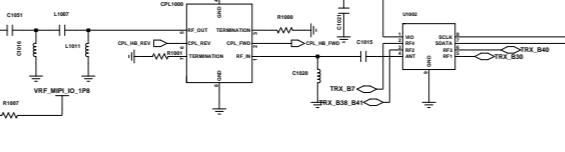
Engineer:	
Drawn by:	
REQ CHK:	
DOC CTRL CHK:	
MPG ENGR CHK:	

RF PART 1

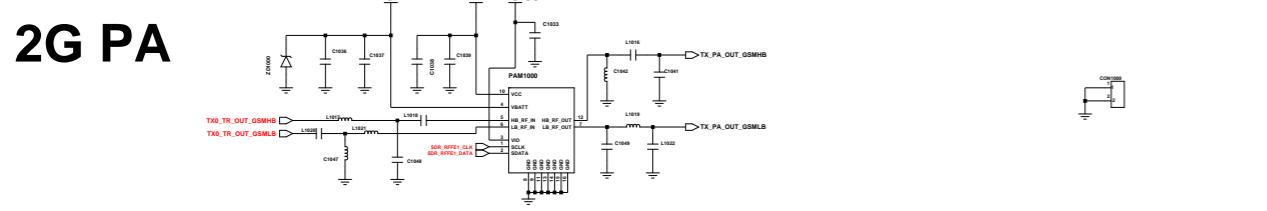
MAIN ANT1 LMB



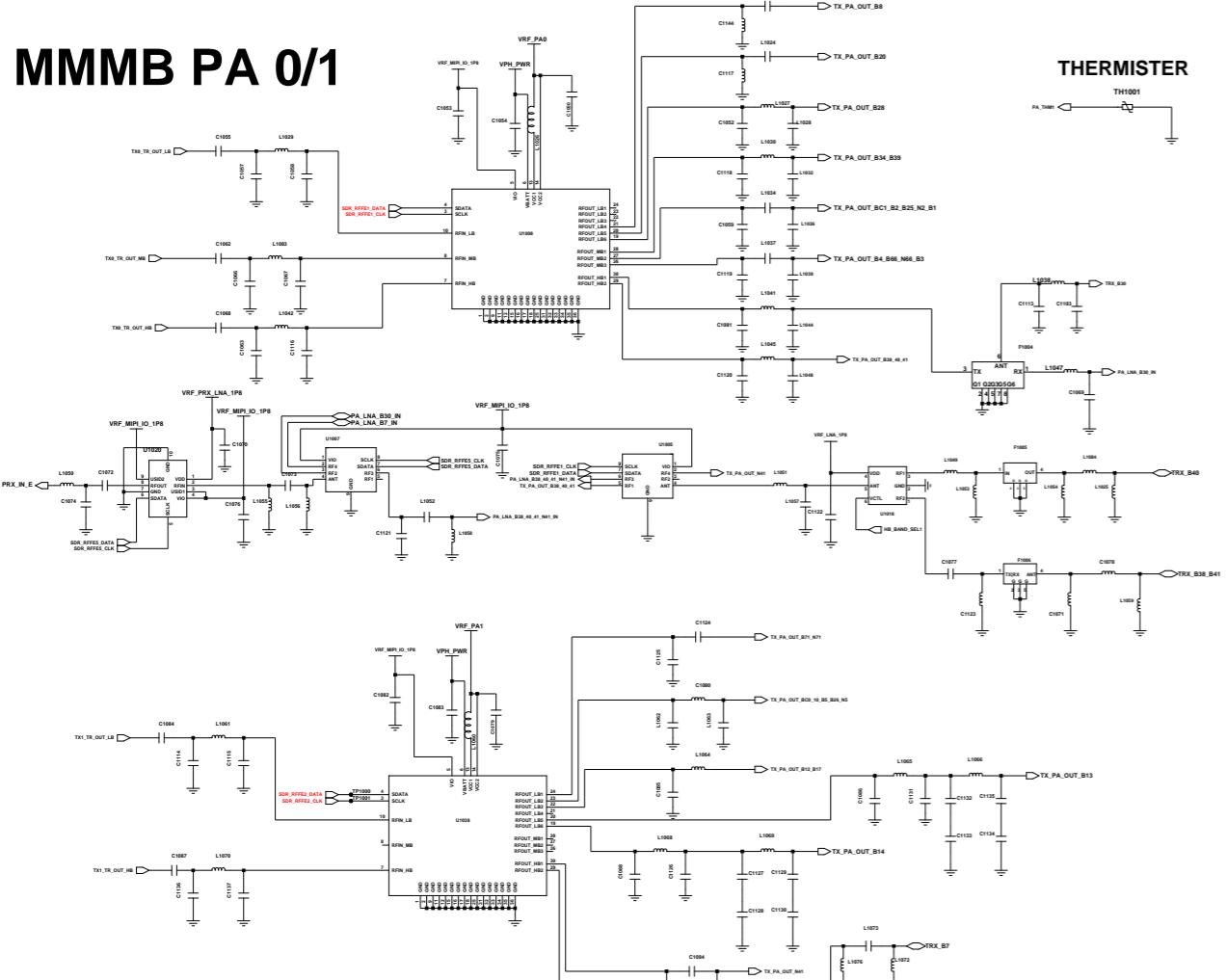
MAIN ANT2 HB



2G PA



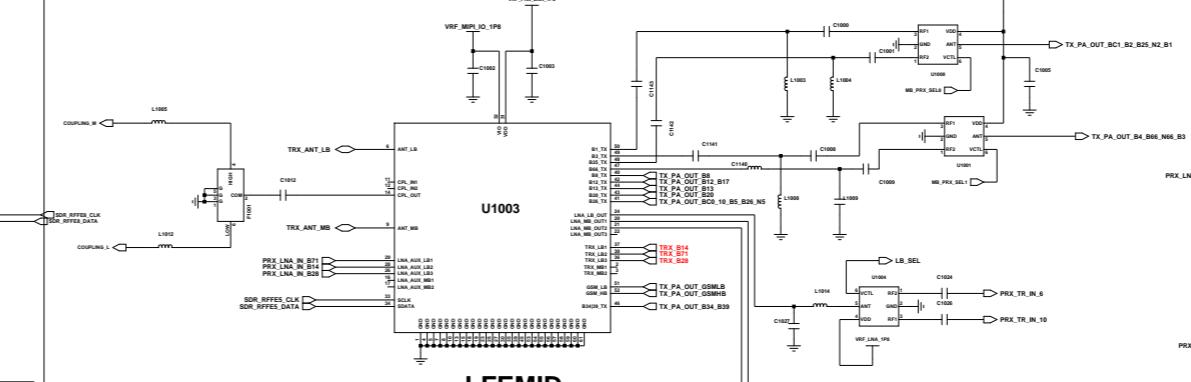
MMMB PA 0/1



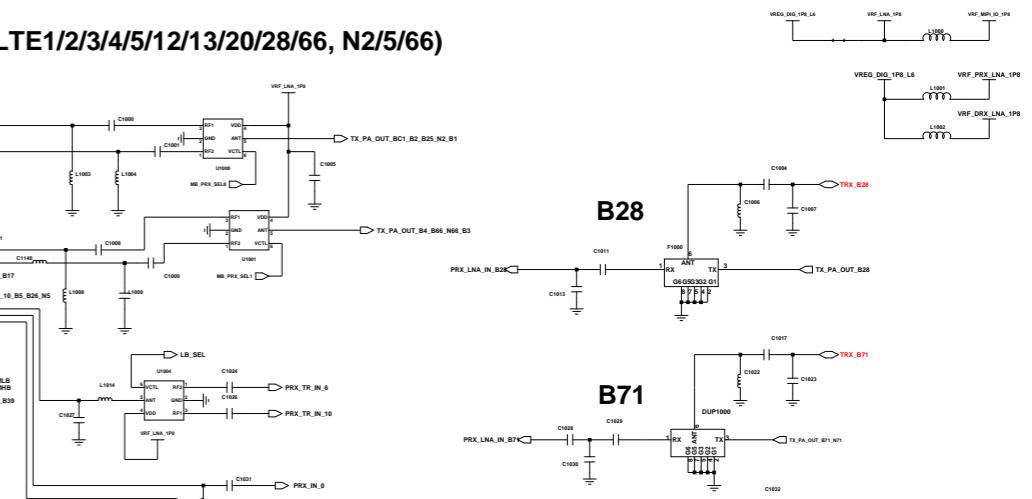
THERMISTER

TH1000

FEMID (GSM_W1/2/5/8,LTE1/2/3/4/5/12/13/20/28/66, N2/5/66)



LFEMID

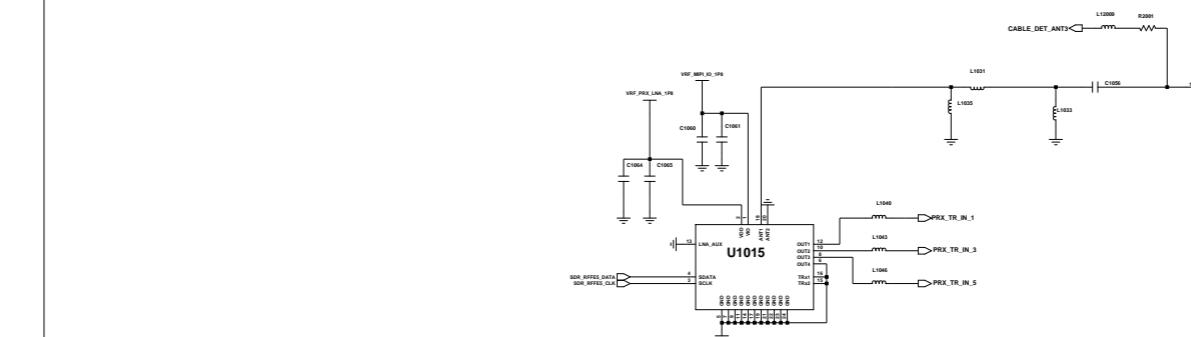


B28

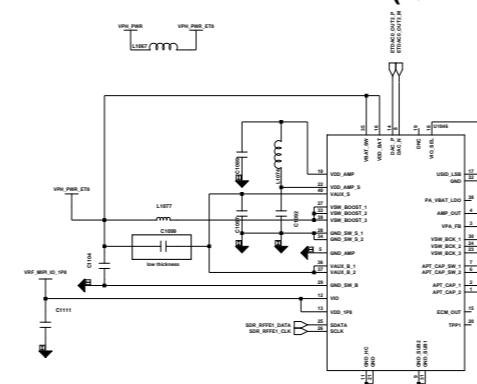
B71

B14

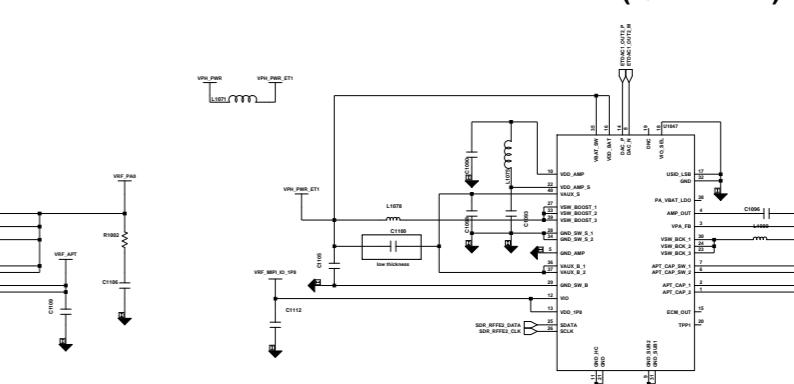
MAIN ANT3 N2_4_41 PRX MIMO



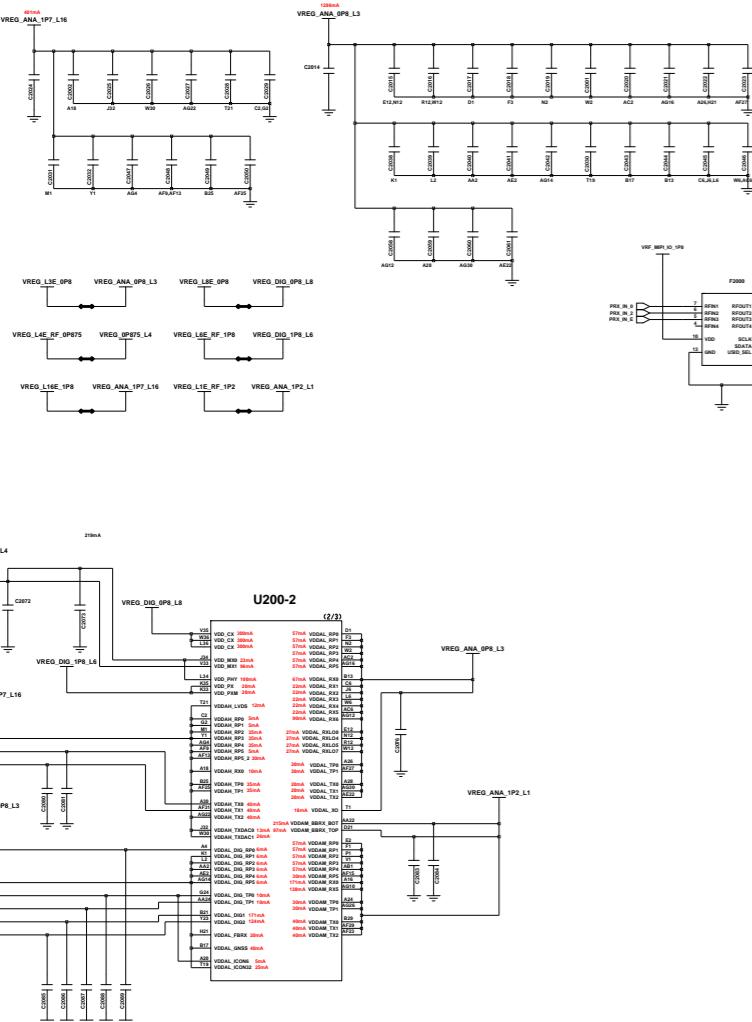
ET Modulator(QET5100#0)



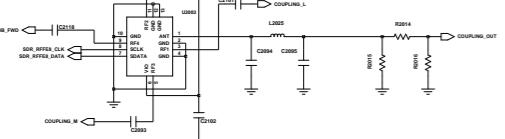
ET Modulator(QET5100#1)



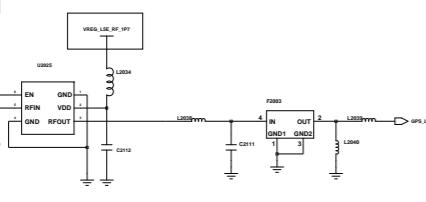
TRANSCEIVER(SDR865)



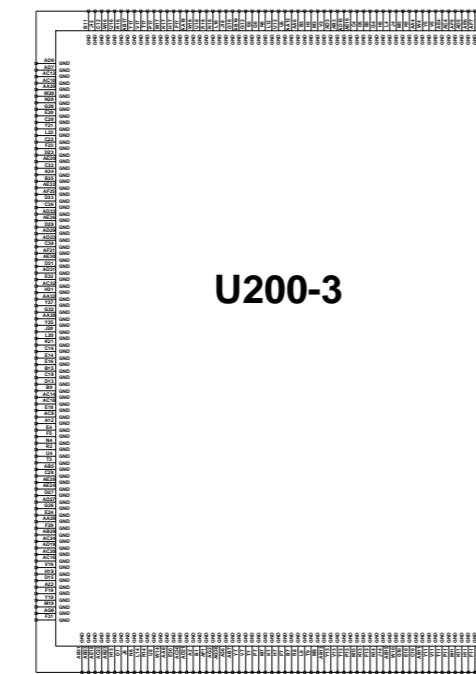
FBRX



GPS_L1



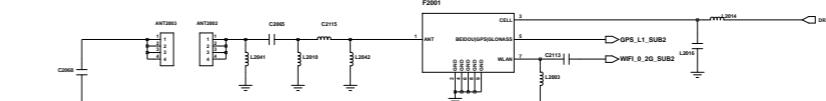
U200-3



SUB ANT SUB ANT1 (LB / N41 DRX MIMO)

DRX_LB
(B5/8/12/13/17/20/26/28_G850/900)

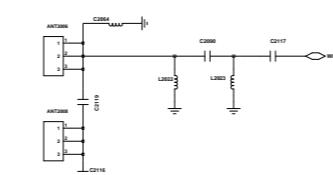
SUB ANT2 (MHB / GPS L1 / N41 / WIFI1 2G)



DRX_MHB

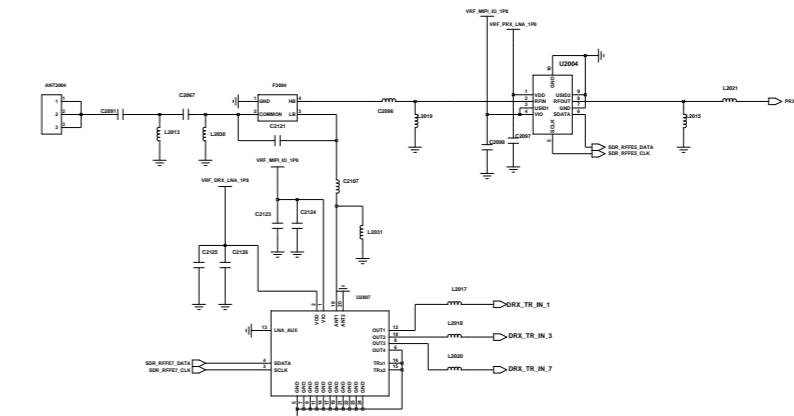
(B1/2/3/4/7/38/40/41/66_DCS/PCS)

SUB ANT3



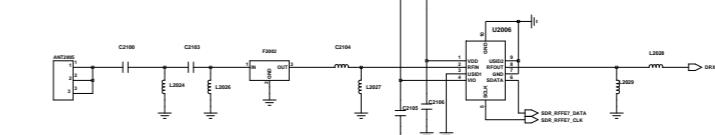
SUB ANT5

(N2_4 DRX MIMO_B46 PRX)



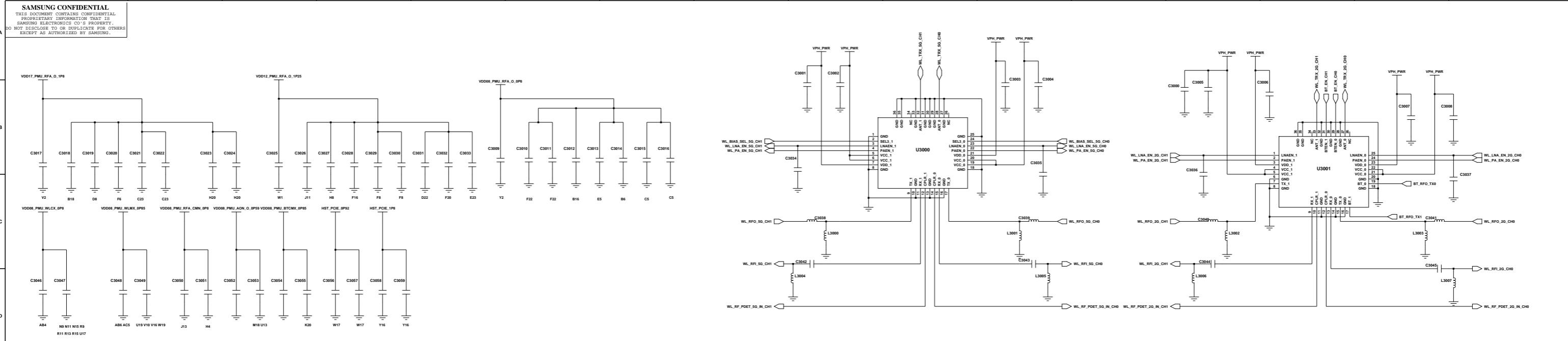
SUB ANT6

(B46 DRX)

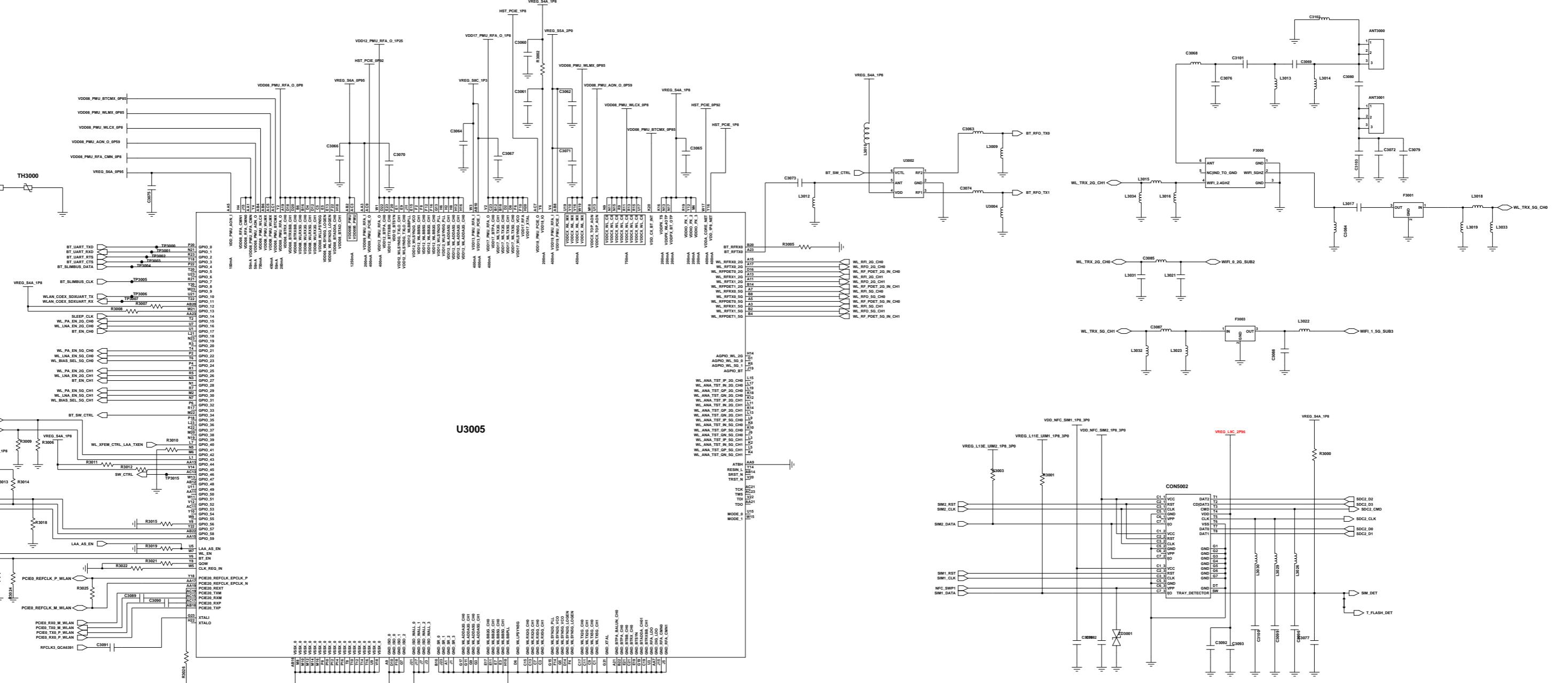


Engineer:	SEC
Review:	SEC
Design:	SEC
Test:	SEC
Date:	SEC
Page:	SEC
Rev:	SEC
Drawing Number:	SEC

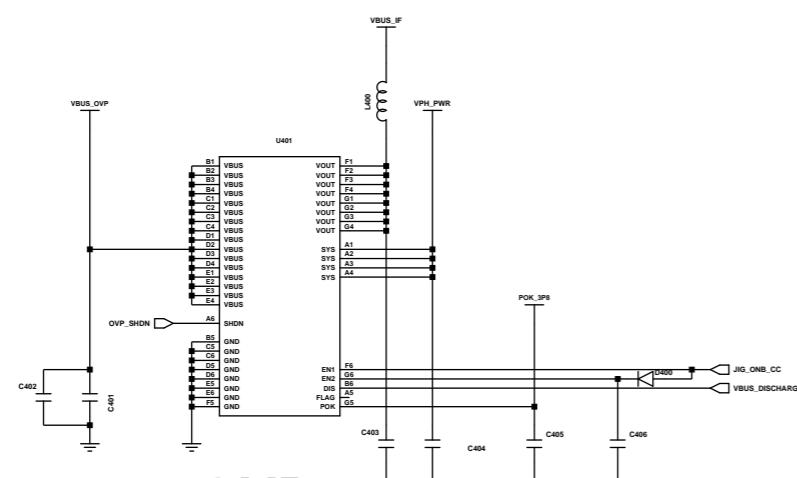
SM8250 + SDX55M



SUB ANT4

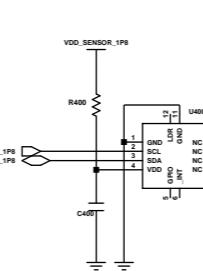


Power

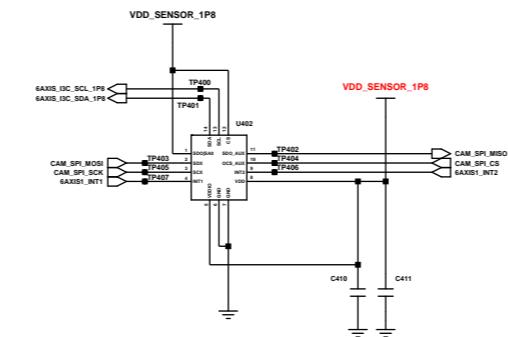


OVP

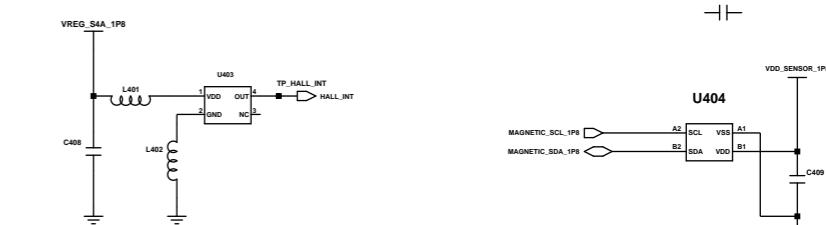
SENSORS



AMBIENT

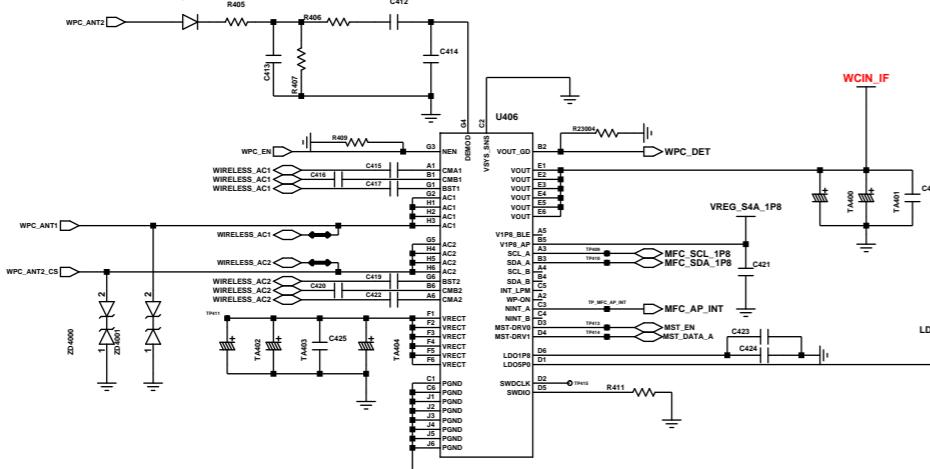


6 AXIS SENSOR
(GYRO,ACCEL)



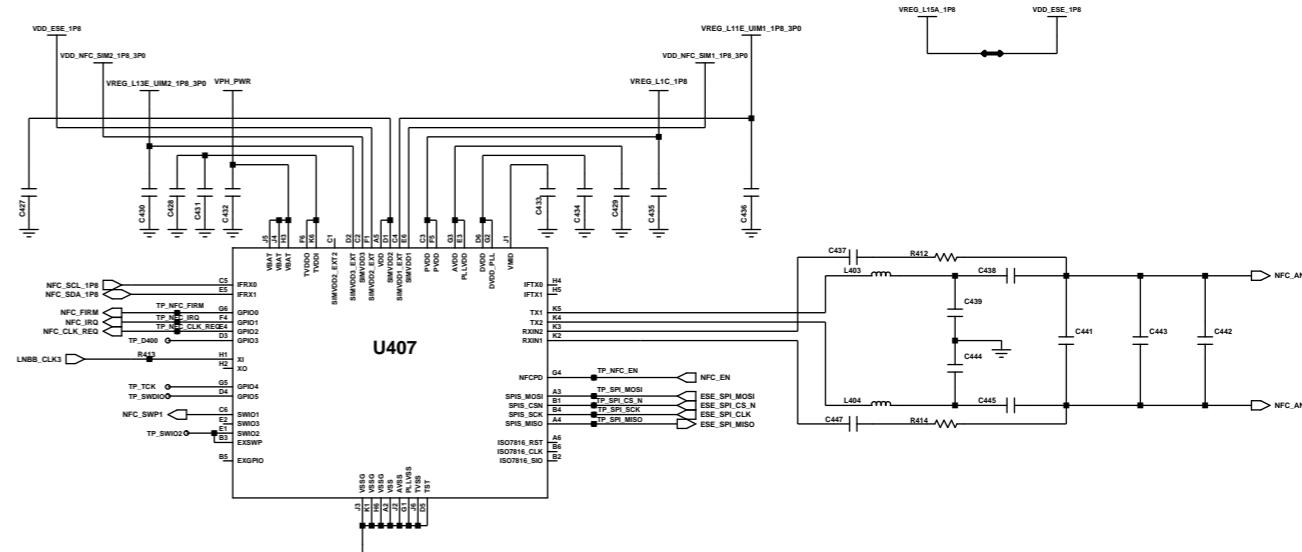
HALL_IC

MAGNETIC SENSOR

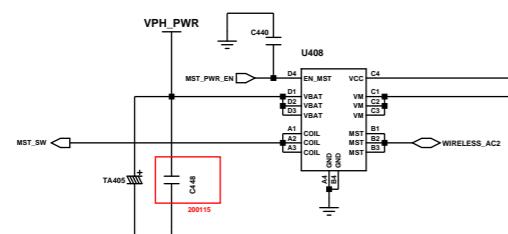


MFC IC(IDT)

NFC



MST Switch

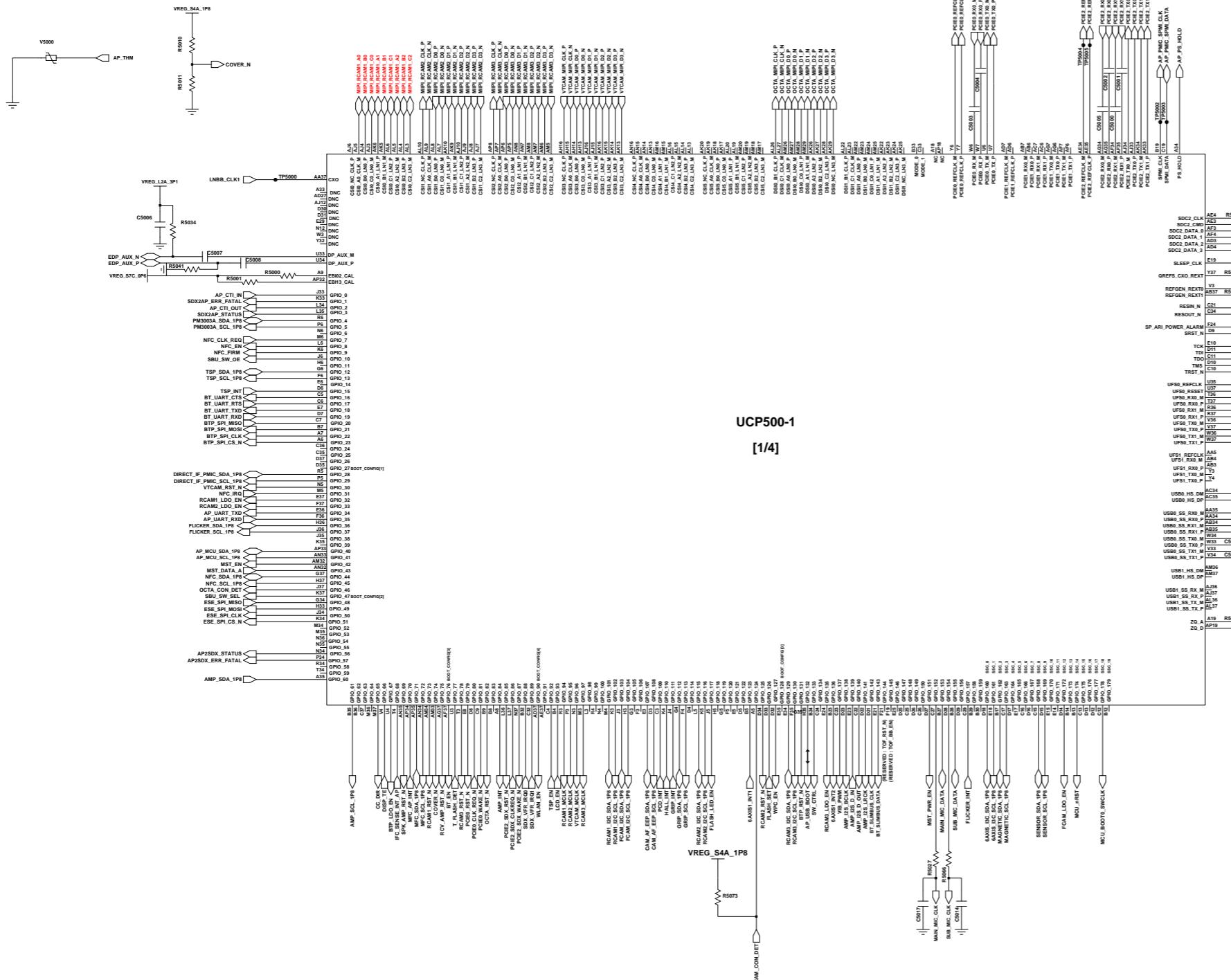


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SM8250

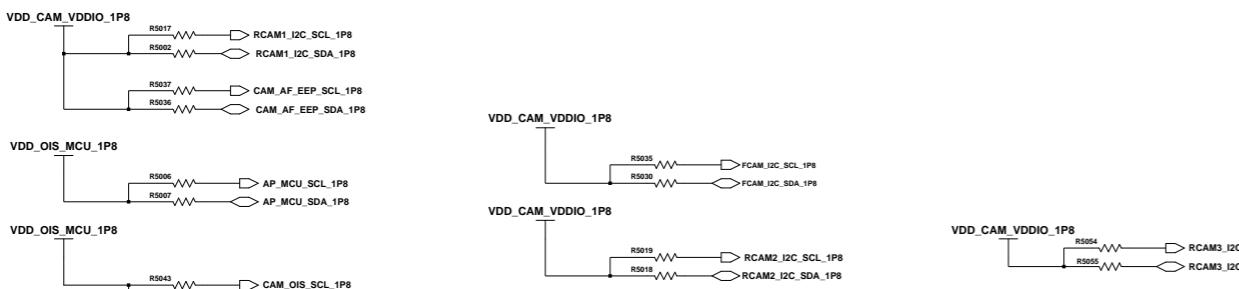
(INTERFACE, GPIO, GND)

System

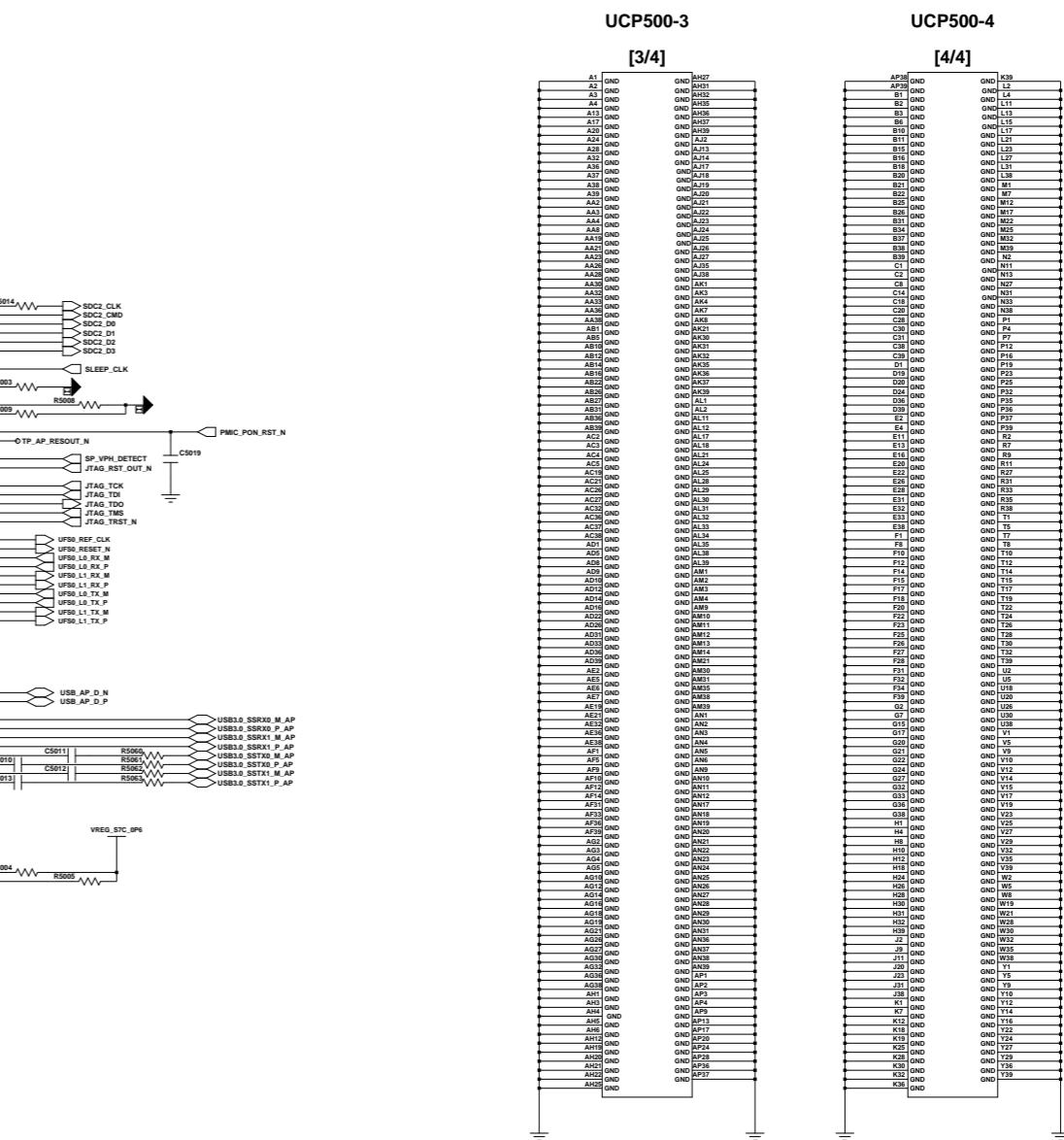


UCP5

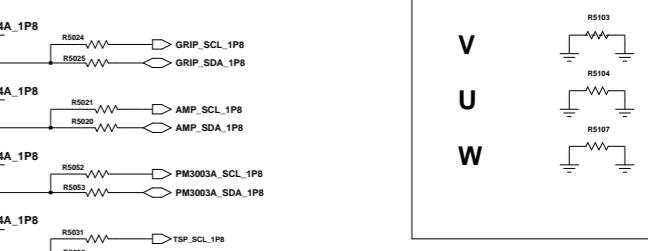
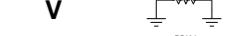
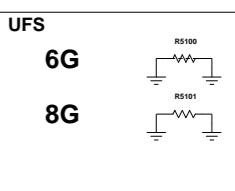
1



I2C PULL U

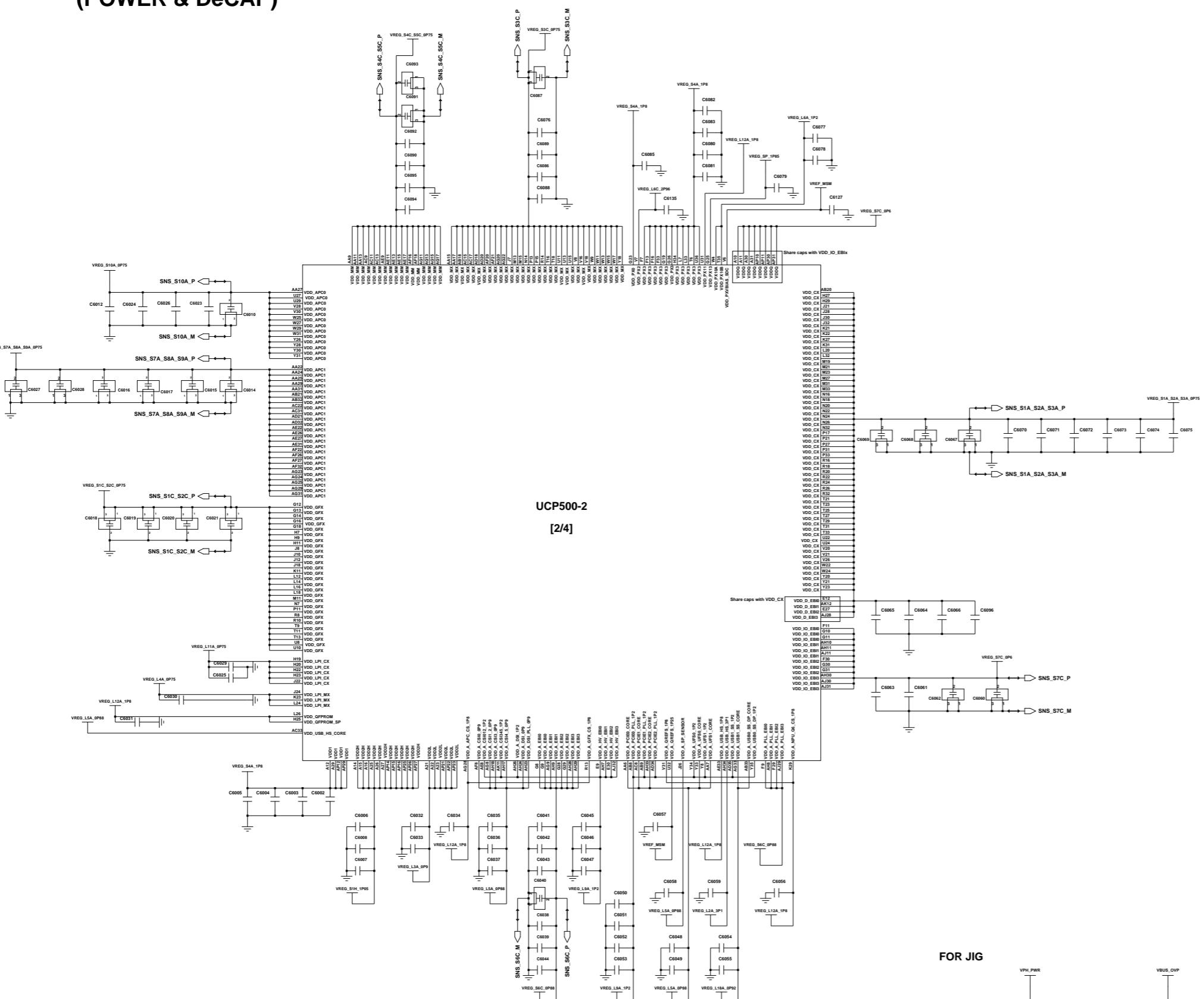


A rectangular label with two barcode symbols. The left barcode is labeled 'CON5000' above it. The right barcode is labeled 'CON5001' above it. Below the barcodes, the text '2D BARCODE' is printed in large, bold, black capital letters.

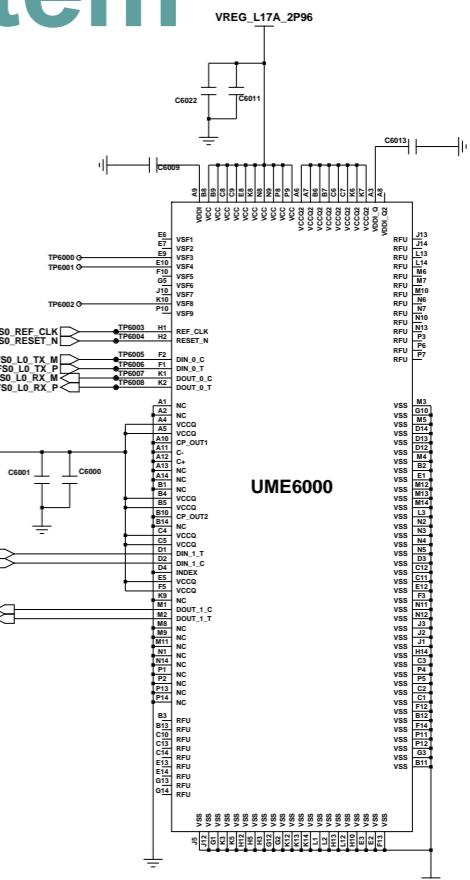


SM8250

(POWER & DeCAP)

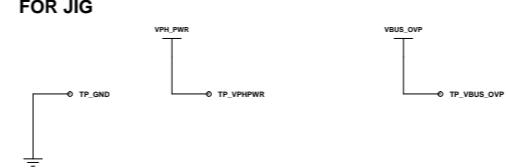
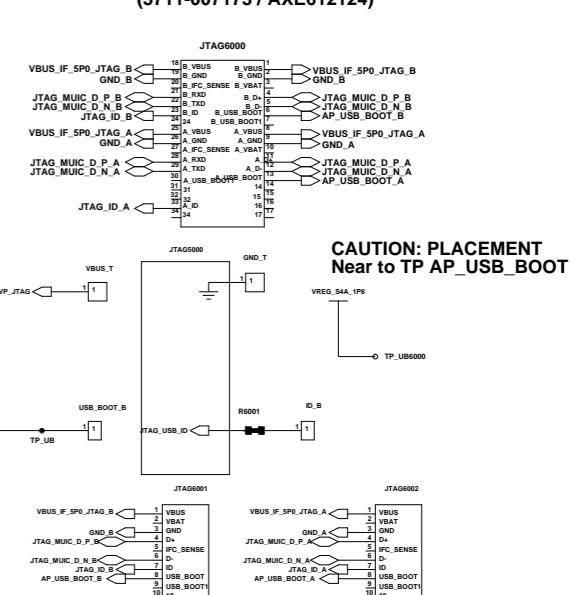


Power System



UFS3.1 128GB / 512GB

AP JTAG CONNECTOR

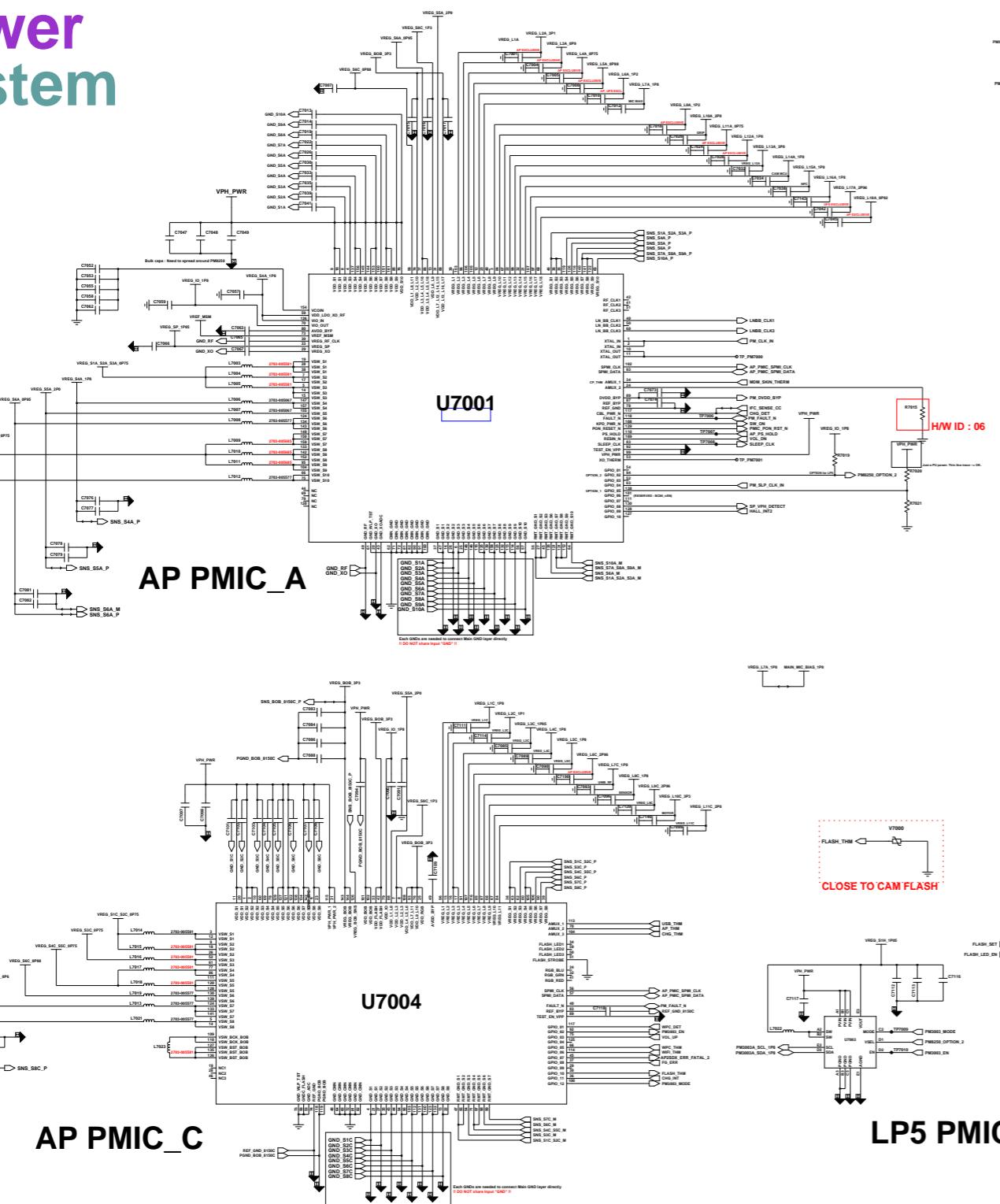


PCB array JTAG

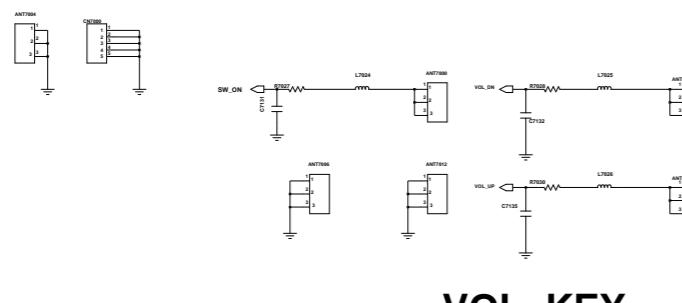
Engineer:	SEC	
Drawn by:	SEC	
R&D CHK:	TITLE:	Size:
DOC CTRL CHK:	L	
MFG ENGR CHK:	SM8250 + SDX55M	

AP PMIC set & CLK Generator

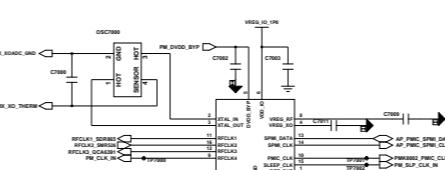
Power System



SystemRadiation

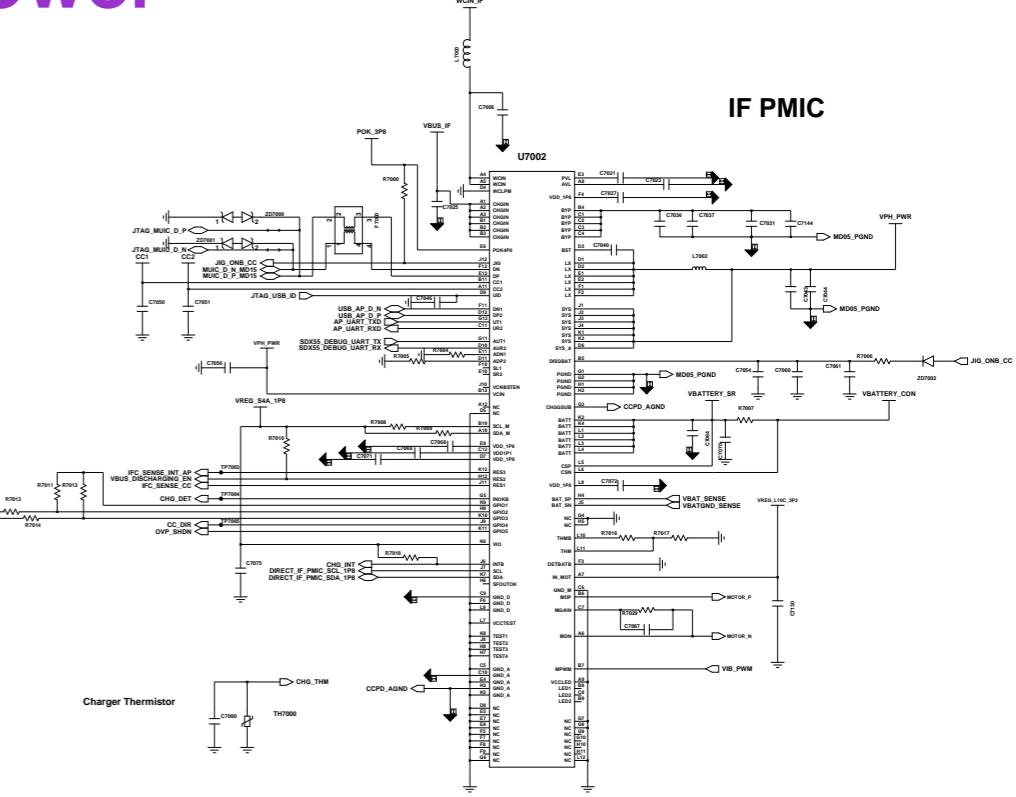


• [About](#) | [Tours](#)



Clock Generator

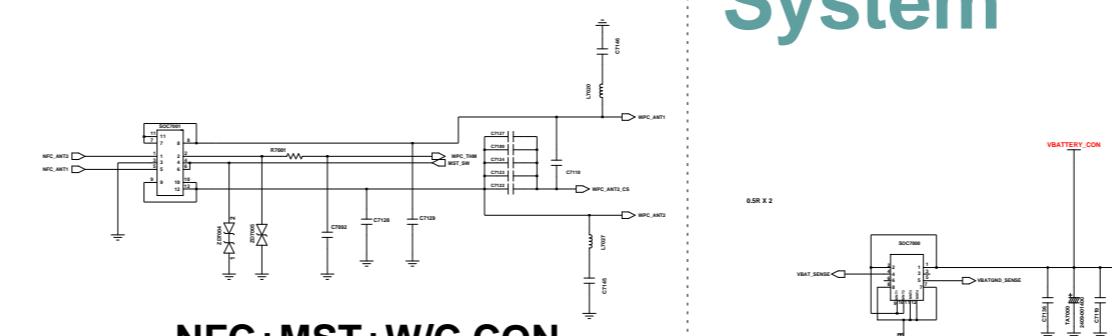
H/W ID table(PM8250 AMUX_2)		
HW ID	BOARD REVISION	Value
00	R8 BRINGUP	6.04K
01	R8 DV1	9.1K
02	R8 DV2	12.4K
03	R8 PV1	18K
04		22K
05		30K
06	R8 PV2	39K
07		47K
08		56K
09		68K
10		82K
11		100K
12		120K
13		150K
14		180K
15		200K
16		240K
17		280K
18		330K
19		430K
20		560K
21		750K
22		1000K
23		1500K
24		3000K



This diagram illustrates the connection of the **VBUS_SF** line to various internal components. The **VBUS_SF** line is connected to:

- U7096**: Through a diode (D1) and a resistor (R1).
- U7095**: Through a diode (D2) and a resistor (R2).
- U7094**: Through a diode (D3) and a resistor (R3).
- C7126** and **C7105**: These components are connected in parallel between **VBUS_SF** and ground.
- TS_NTC**: A temperature sensor connected to **VBUS_SF**.
- DC_THM**: A thermal sensor connected to **VBUS_SF**.
- AVDD**: A voltage reference connected to **VBUS_SF**.
- C7150**: A capacitor connected to **VBUS_SF**.
- U7094**: The **VOUT** pins of **U7094** are connected to **VBUS_SF**.
- C7154**: A capacitor connected to **VBUS_SF**.
- 20V050**: A diode connected to **VBUS_SF**.
- VEAT SENSE** and **VEATONDE SENSE**: These sense lines are connected to **VBUS_SF**.
- C7132** and **C7115**: These components are connected in parallel between **VBUS_SF** and ground.
- C7137**: A capacitor connected to **VBUS_SF**.
- C7142**: A capacitor connected to **VBUS_SF**.
- U7094**: The **GND** pins of **U7094** are connected to **VBUS_SF**.
- C7151**: A capacitor connected to **VBUS_SF**.
- 20V050**: A diode connected to **VBUS_SF**.

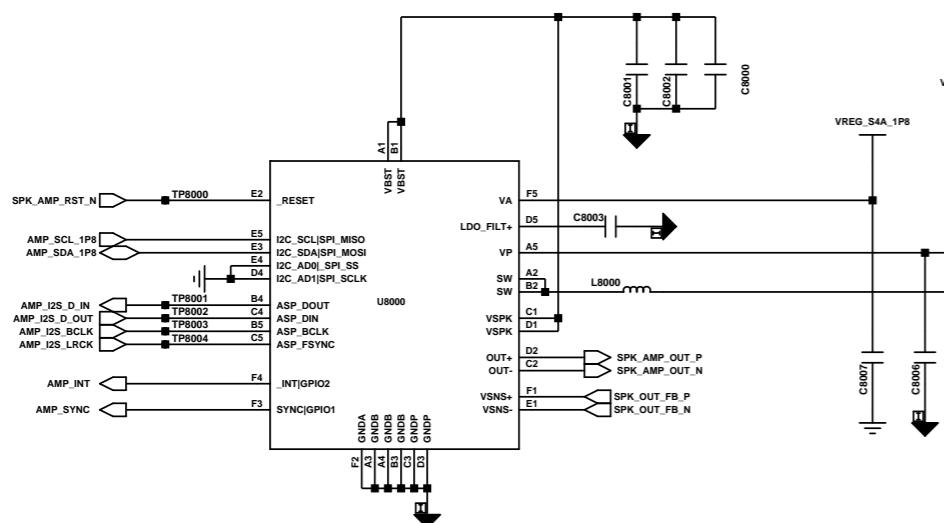
System



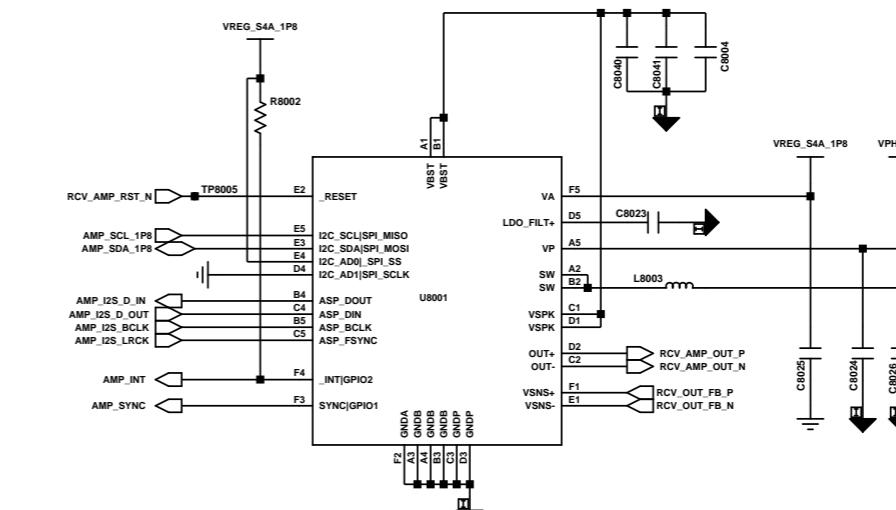
AUDIO PART

AUDIO

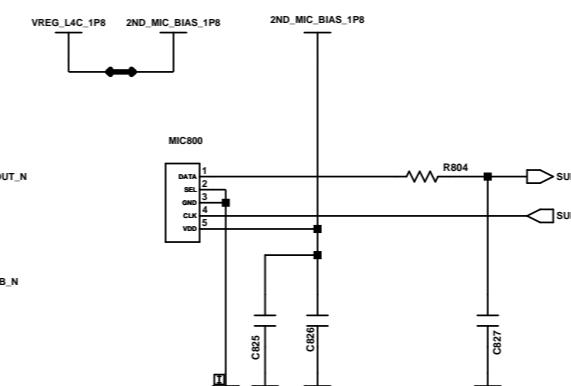
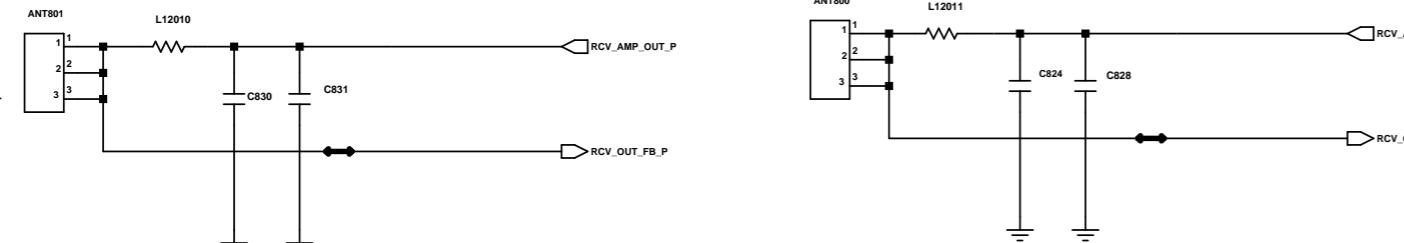
SPK AMP



RCV AMP



RCV CONTACT



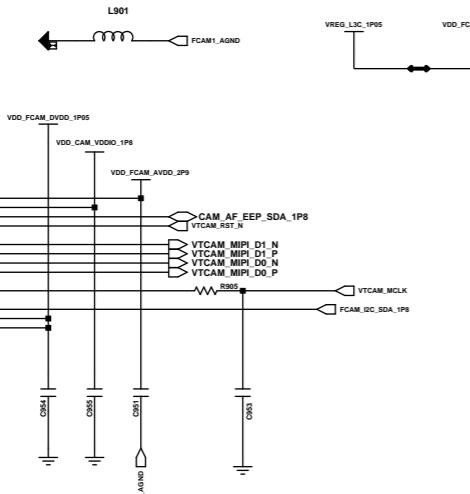
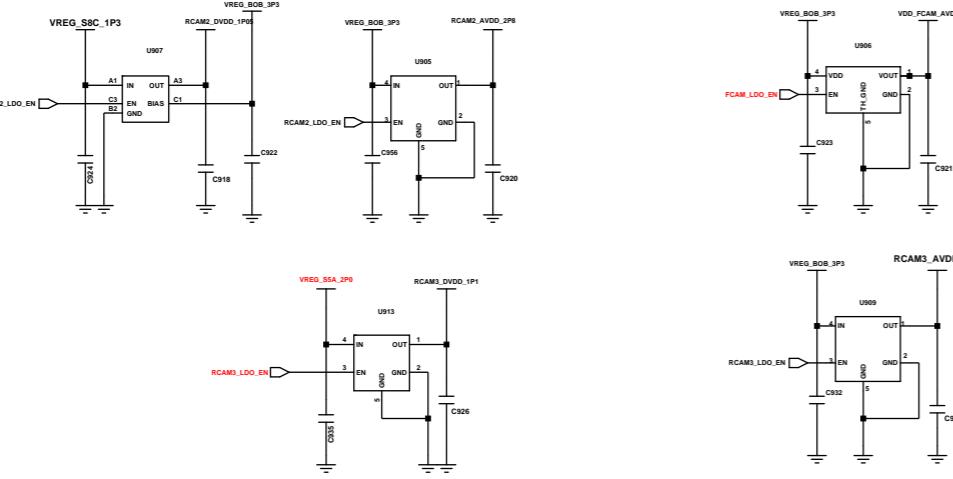
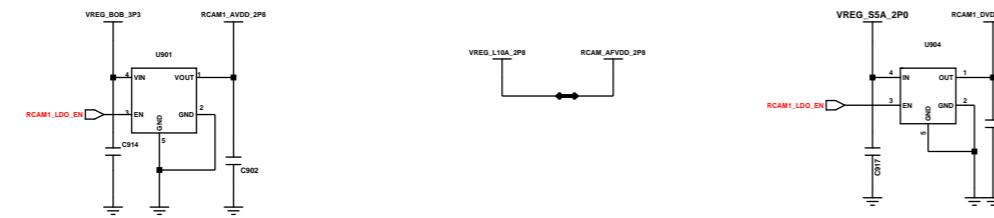
2nd MIC

Engineer:	SEC	SAMSUNG ELECTRONICS			
Drawn by:	SEC				
R&D CHK:	TITLE: SM8250 + SDX55M				
DOC CTRL CHK:				Size:	
MFG ENGR CHK:					
ed:	QA CHK:	REV:	Drawing Number:		
			Page: 8		

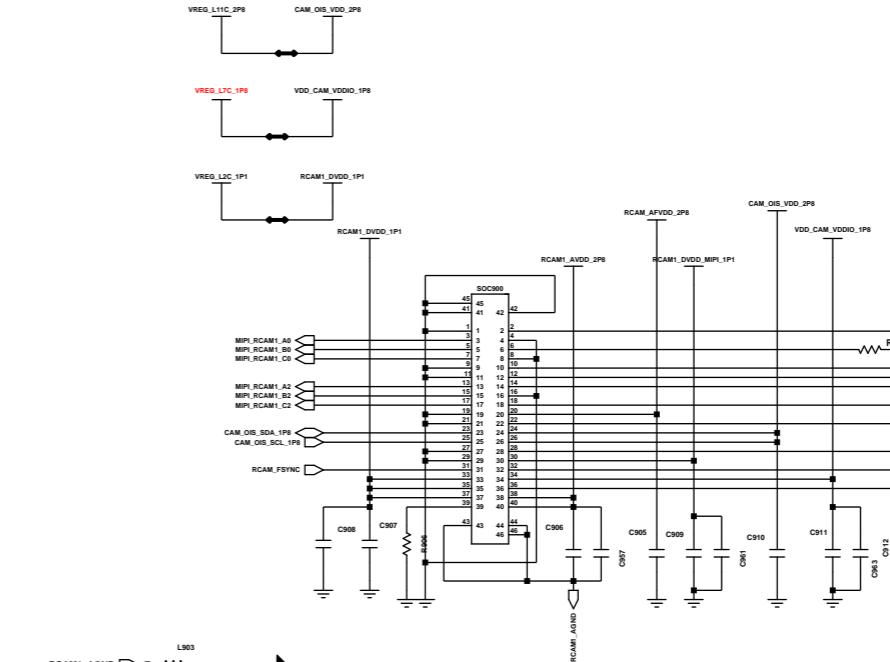
CAMERA

Visual

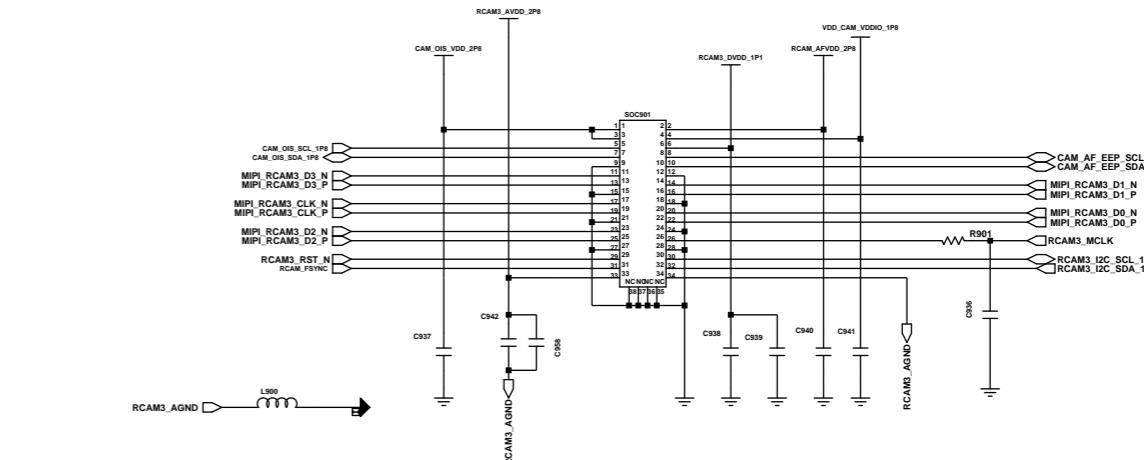
CAM_PMIC



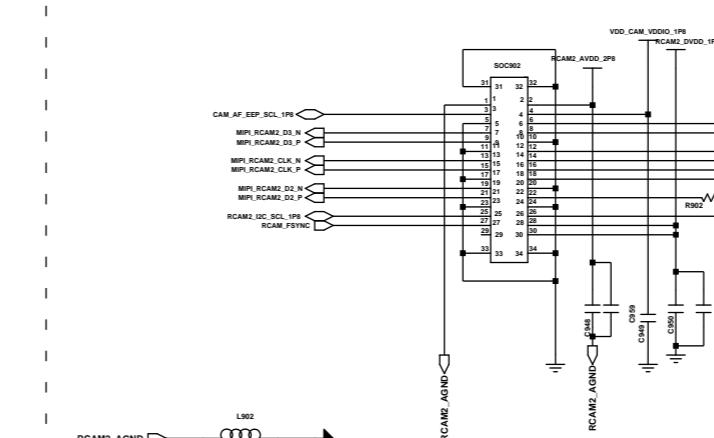
32M FRONT CAM



12M 2PD OIS WIDE CAM



8M TELE CAM

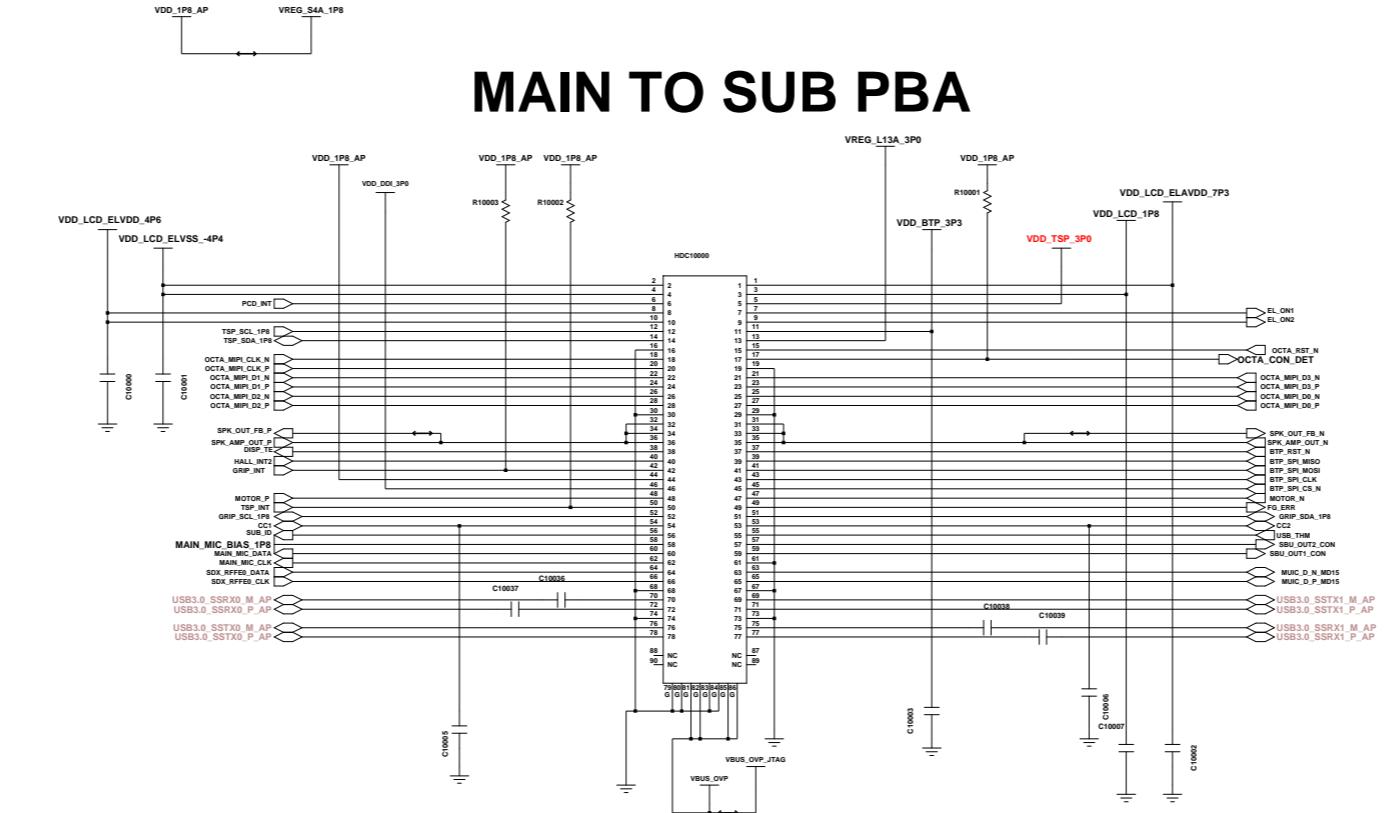


12M SUPER WIDE CAM

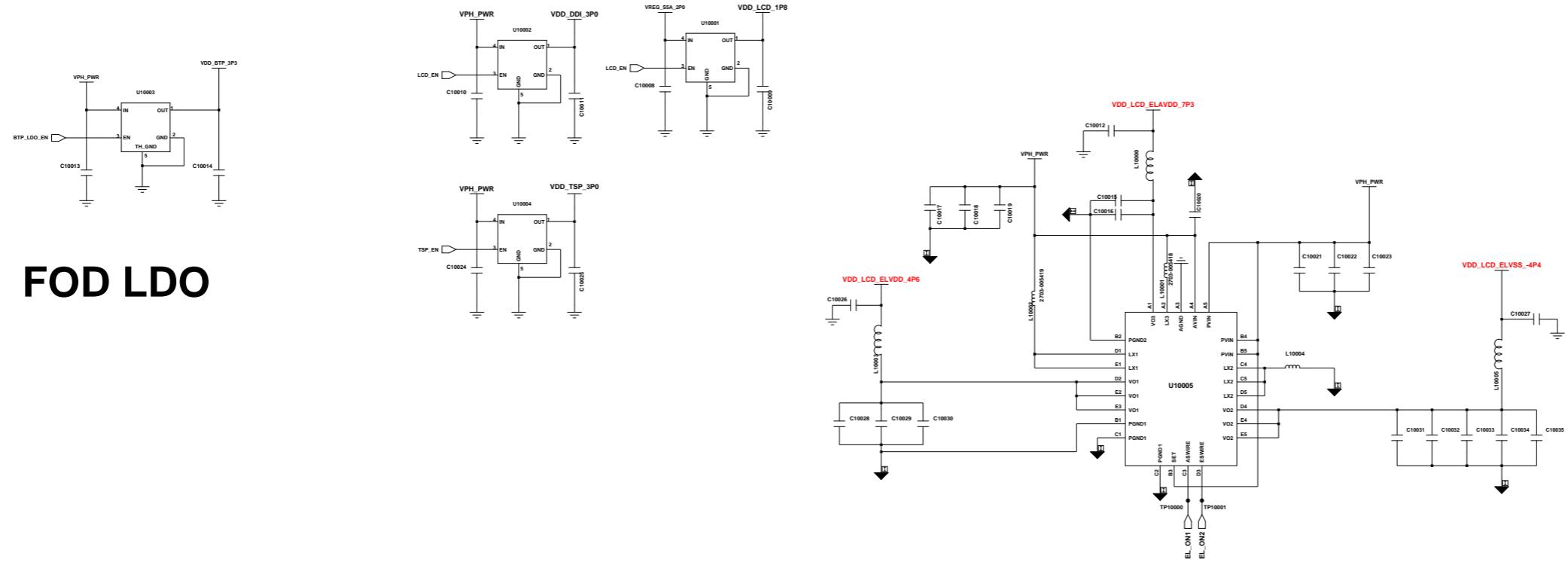
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Drawn by:	SEC	
REV CHK:		
DOC CHK:		
DOC CTL CHK:		
MPG ENGR CHK:		

SM8250 + SDX55M

DISPLAY



DISPLAY



Visual

Engineer: SEC	
Drawn by: SEC	
R&D CHK: SEC	
DOC CTRL CHK: SEC	
MFG ENGR CHK: SEC	

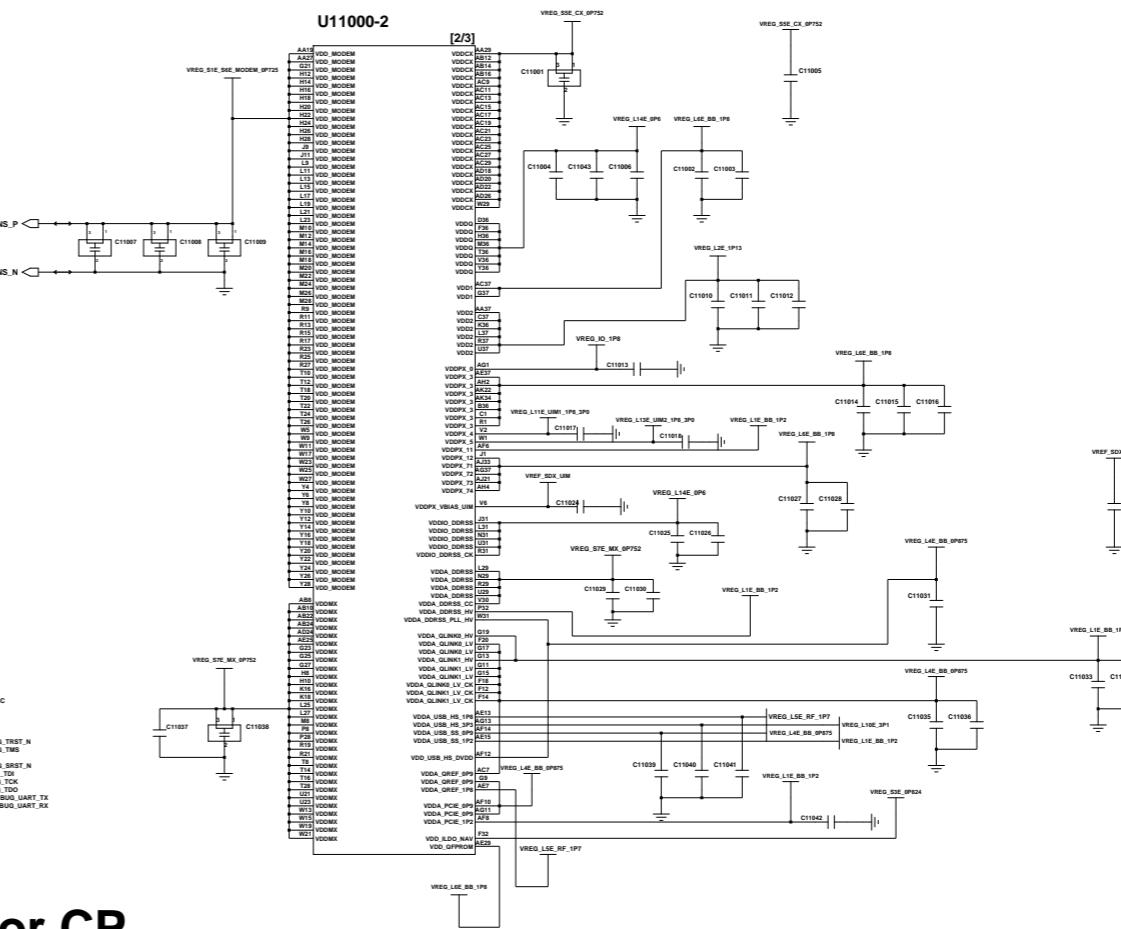
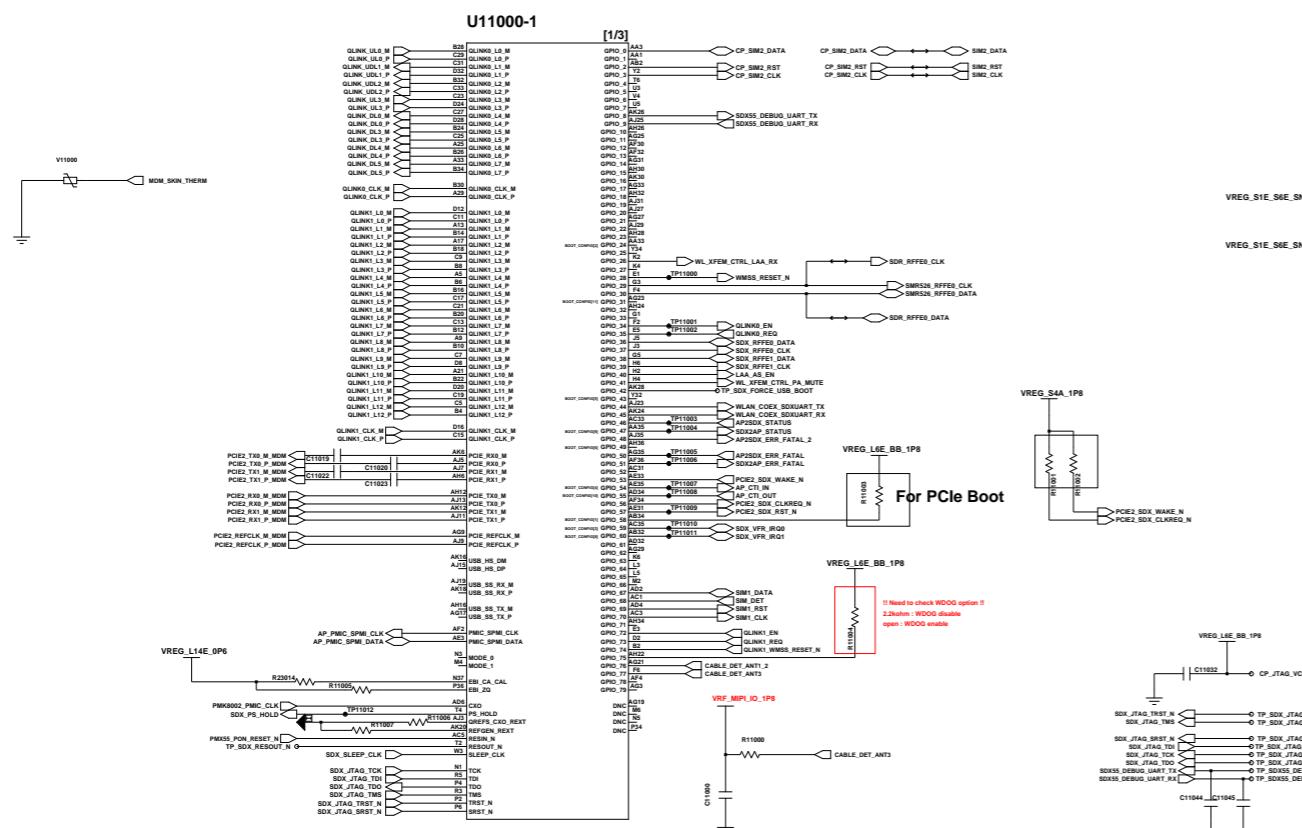
SM8250 + SDX55M

Changed by: Date Changed: Time Changed: QA CHK: REV Drawing Number: Page: 9

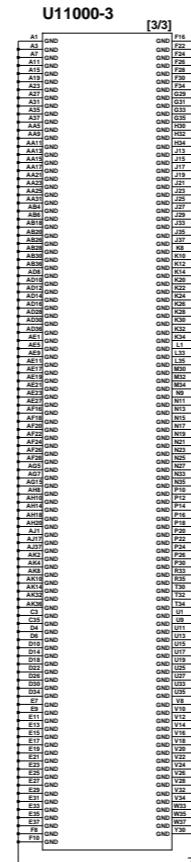
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SDX55M

System



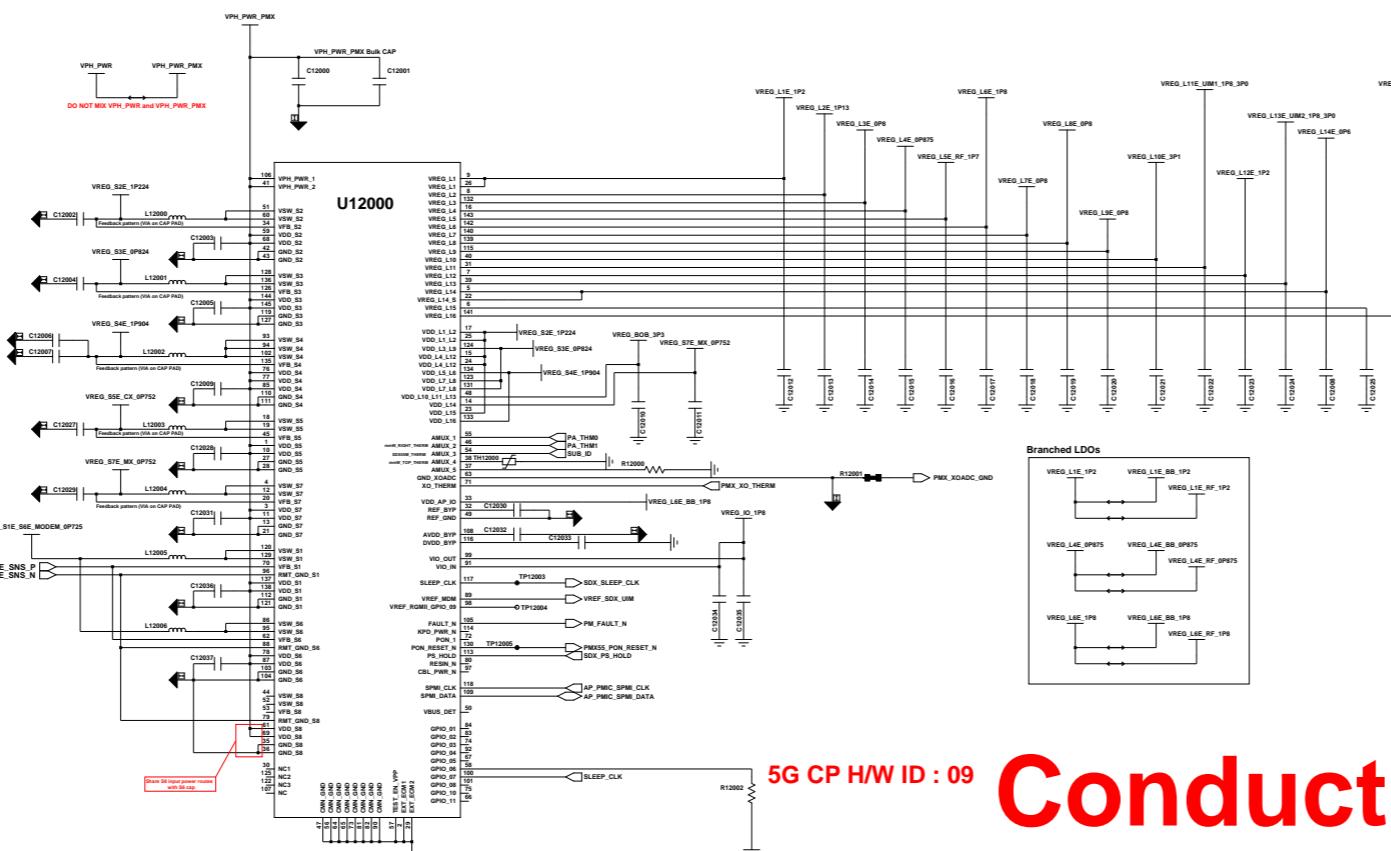
JTAG connector for CP



Engineer:	SEC	SAMSUNG ELECTRONICS	
Drawn by:	SEC		
R&D CHK:	TITLE:		Size: <input type="checkbox"/>
DOC CTRL CHK:			
MFG ENGR CHK:			
ed:	QA CHK:	REV:	Drawing Number:
			Page: 11

CP PMIC

Power



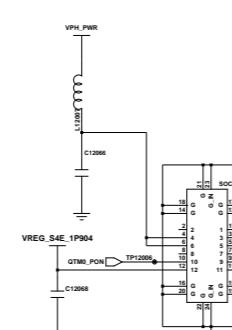
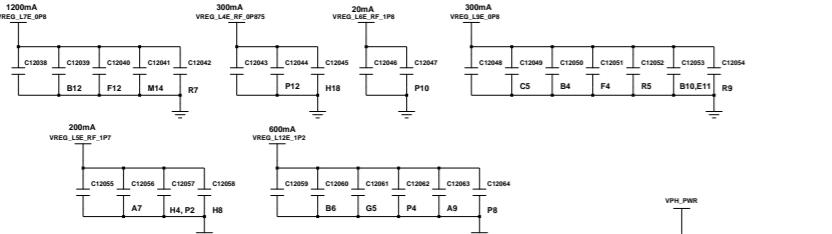
5G CP H/W ID : 09

Conduction

PMX55

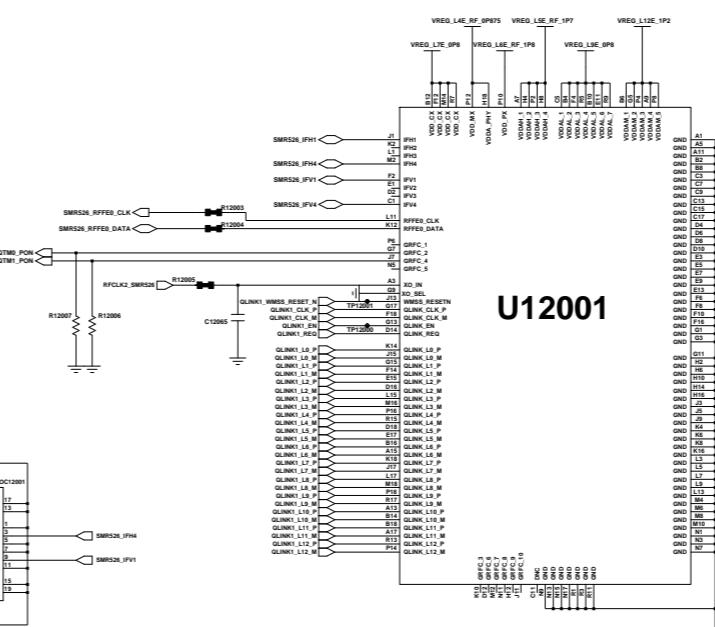
CP H/W ID table (PMX55 GPIO_06)			
HW ID	BOARD REVISION	Value	Mech
00	R8 BRINGUP	6.04K	
01	R8 DV1	9.1K	
02	R8 DV2	12.4K	KI10
03	R8 PV1	18K	KI10
04		22K	KI20
05		30K	
06	SM-G781W_REV03	39K	KI30
07	SM-G781V_REV03	47K	KI30
08	SM-G781U_REV03	56K	KI40
09	SM-G781V_REV03+B46	68K	KI40
10	SM-G781U_REV03+B46	82K	KI40
11		100K	KI50
12		120K	VY60
13		150K	VY60
14		180K	VY70
15		200K	VY70
16		240K	VY75
17		280K	VY75
18		330K	
19		430K	
20		560K	
21		750K	
22		1000K	
23		1500K	
24		3000K	

5G IFIC



mmW ANT CONN (RIGHT)

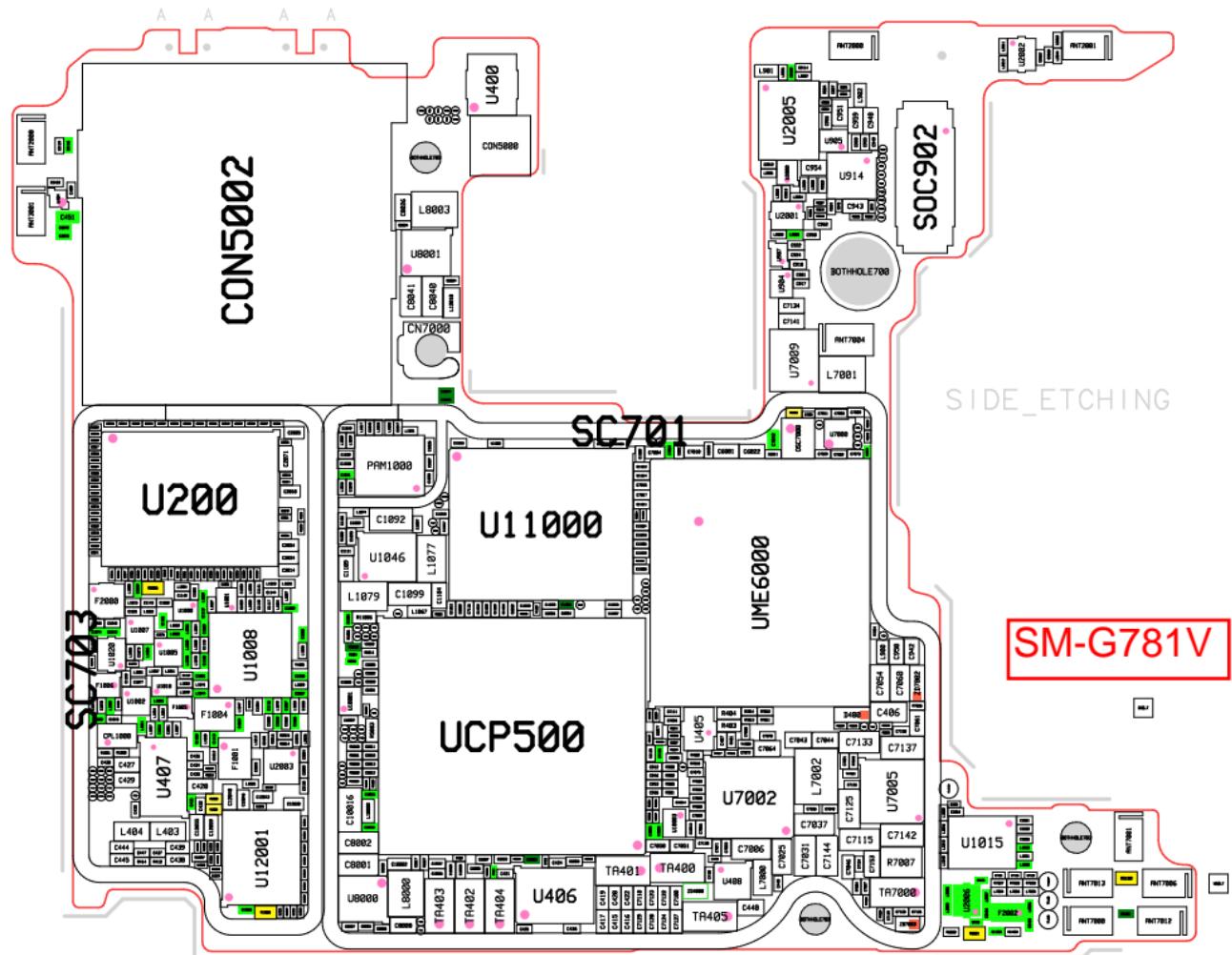
mmW ANT CONN (LEFT)

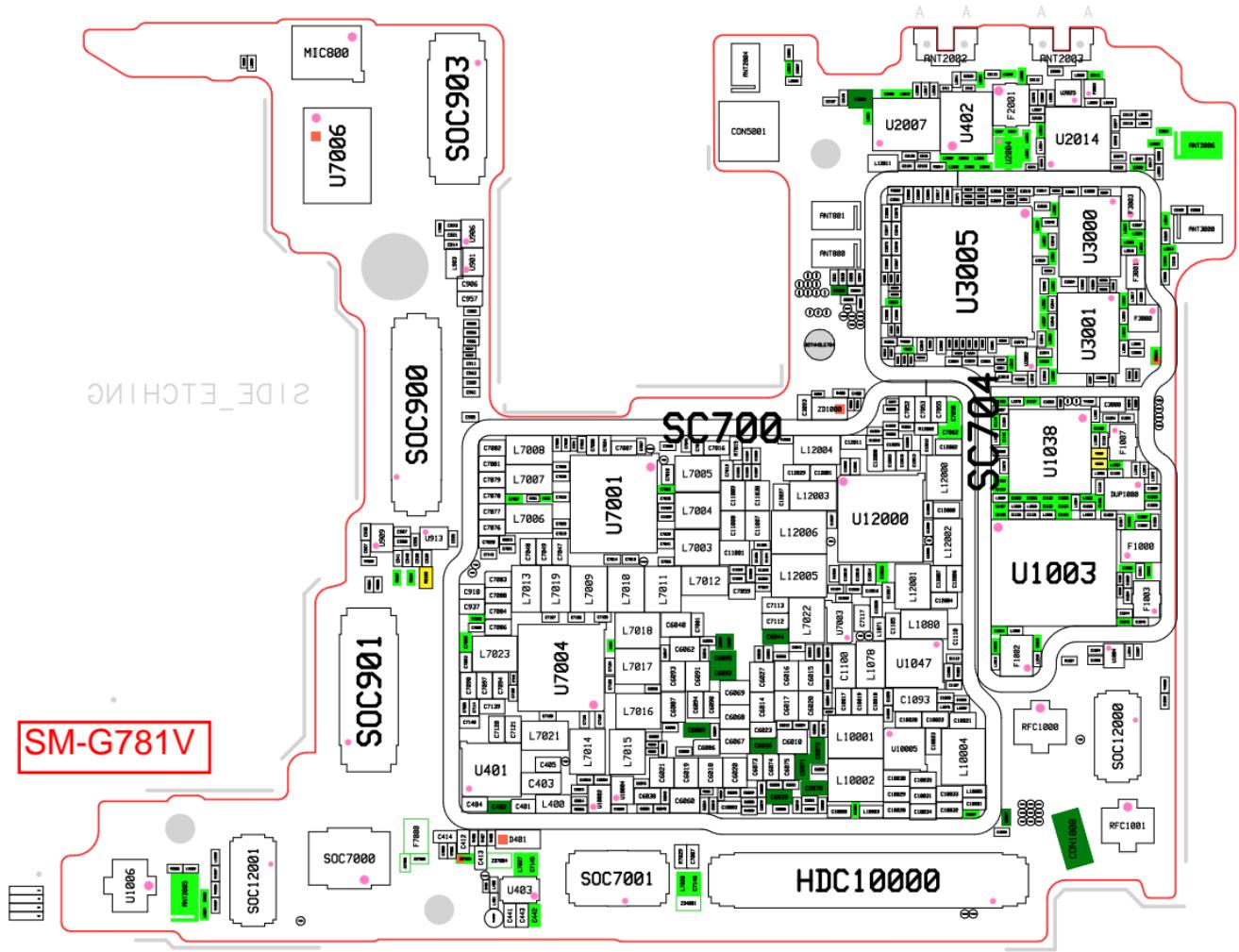


U12001

Radiation

Engineer:	SEC	SAMSUNG ELECTRONICS	
Drawn by:	SEC		
R&D CHK:	TITLE:		Size:
DOC CTRL CHK:			
MFG ENGR CHK:			
ged:	QA CHK:	REV:	Drawing Number:
			Page:





SM-G781I ｼ ﾂ(R8)

2020. 07. 06

sheet01 :

sheet02 : RF (2/2)

sheet03 : BT/WIFI, SIM

sheet04 : OVP LS, NFC , SENSORS

sheet05 : SM8250

sheet06 : SM8250 POWER/GND, JTAG, UFS

sheet07 : PM8250, PM8150C, PMK8002, IF PMIC

sheet08 : AUDIO

sheet09 : CAMERA

sheet10 : DISPLAY

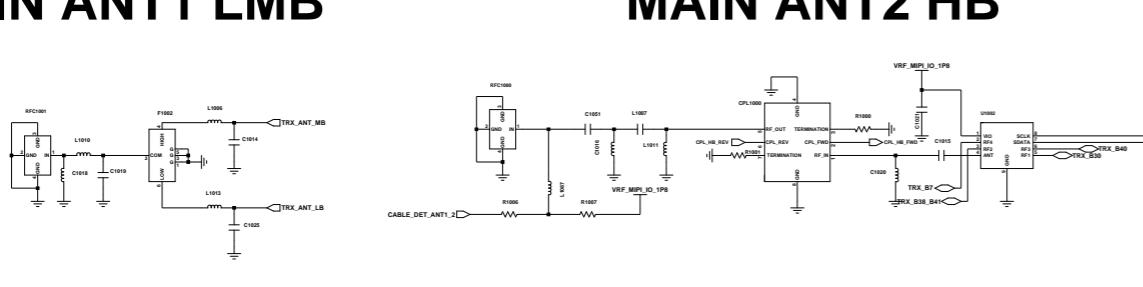
sheet11 : SDX55M(5G MODEM)

sheet12 : PMX55M(5G POWER)

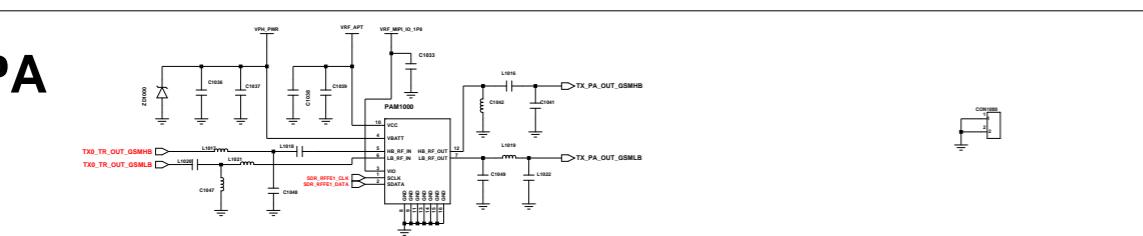
Engineer:	
Drawn by:	
REQ CHK:	
DOC CTRL CHK:	
MPG ENGR CHK:	

RF PART 1

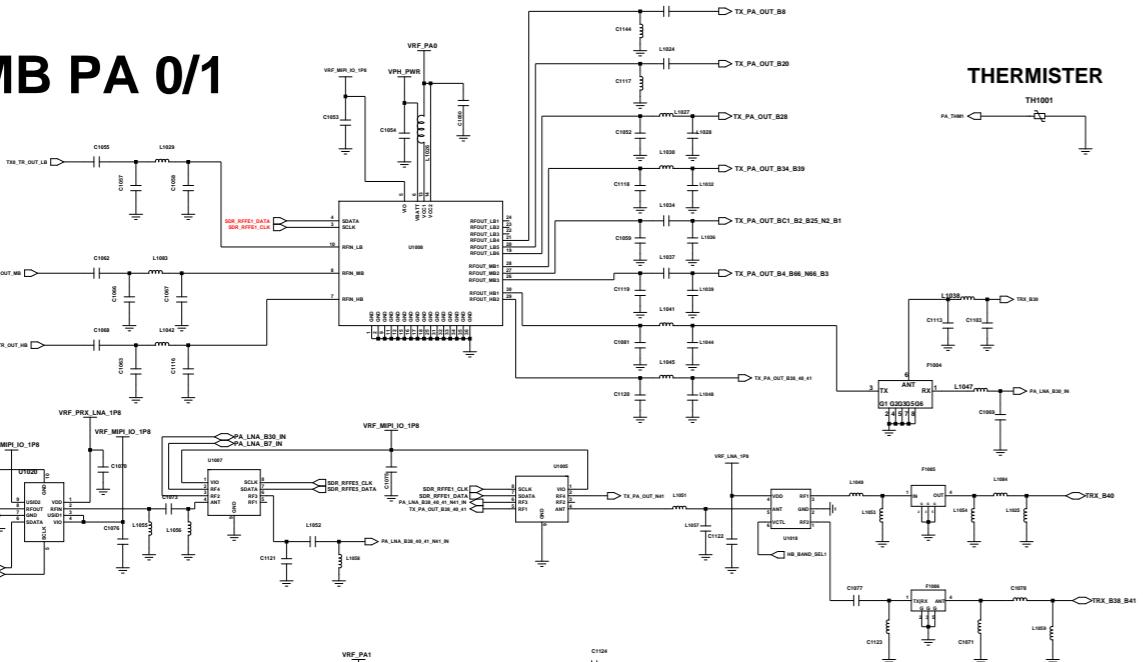
MAIN ANT1 LMB



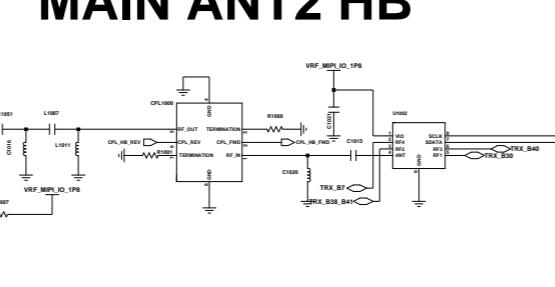
2G PA



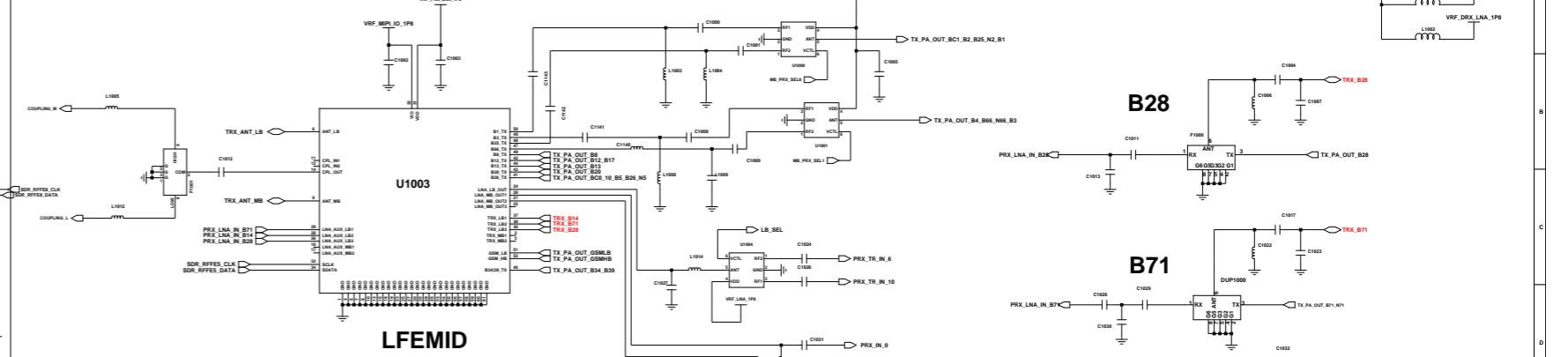
MMMB PA 0/1



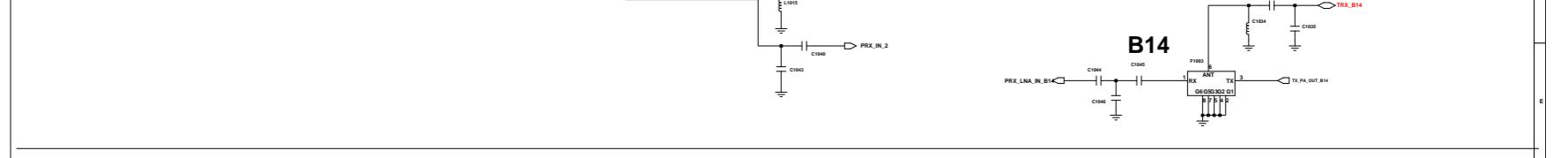
AIN ANT2 HE



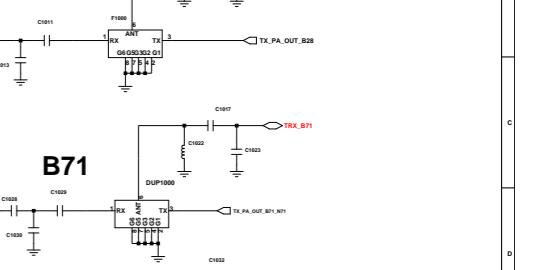
FEMID (GSM_W1/2/5/8,LTE1/2/3/4/5/12/13/20/28/66, N2/5/66)



LFEMI



B28



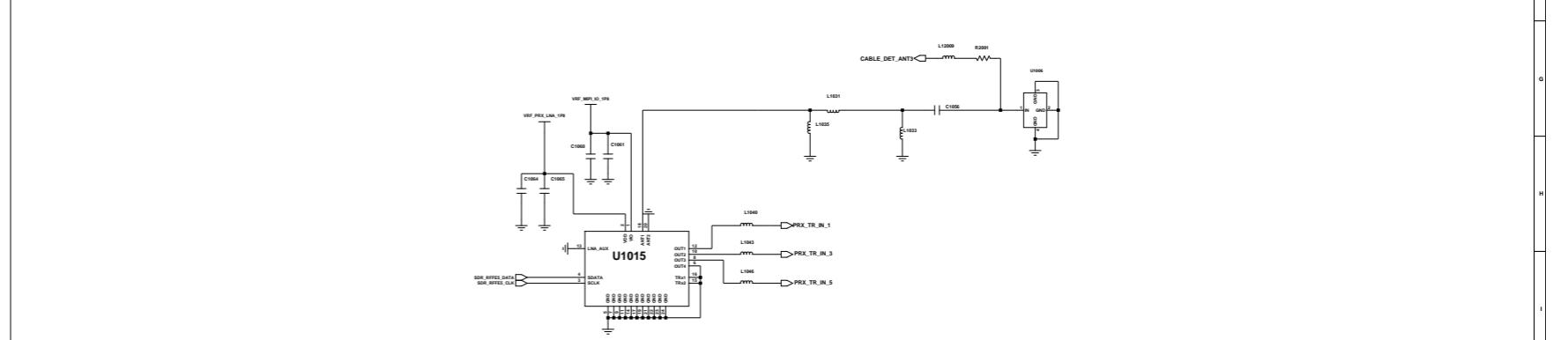
B71



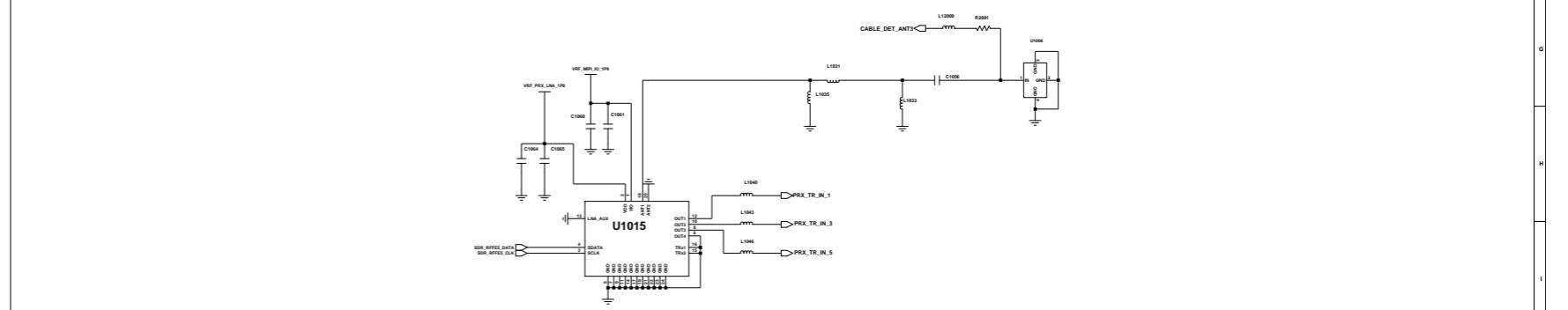
B14



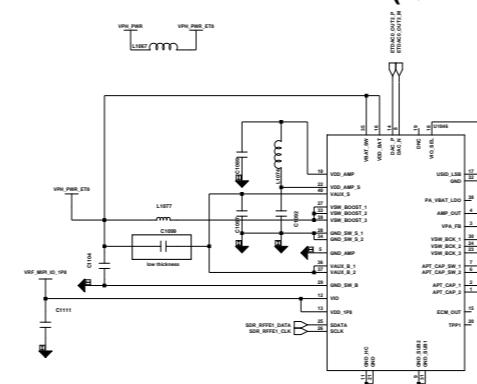
MAIN ANT3 N2_4_41 PRX MIMO



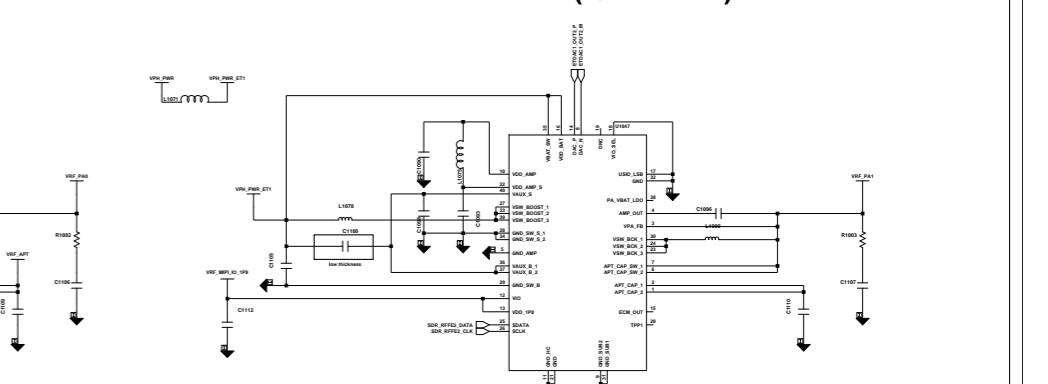
THERMI



ET Modulator(QET5100#0)



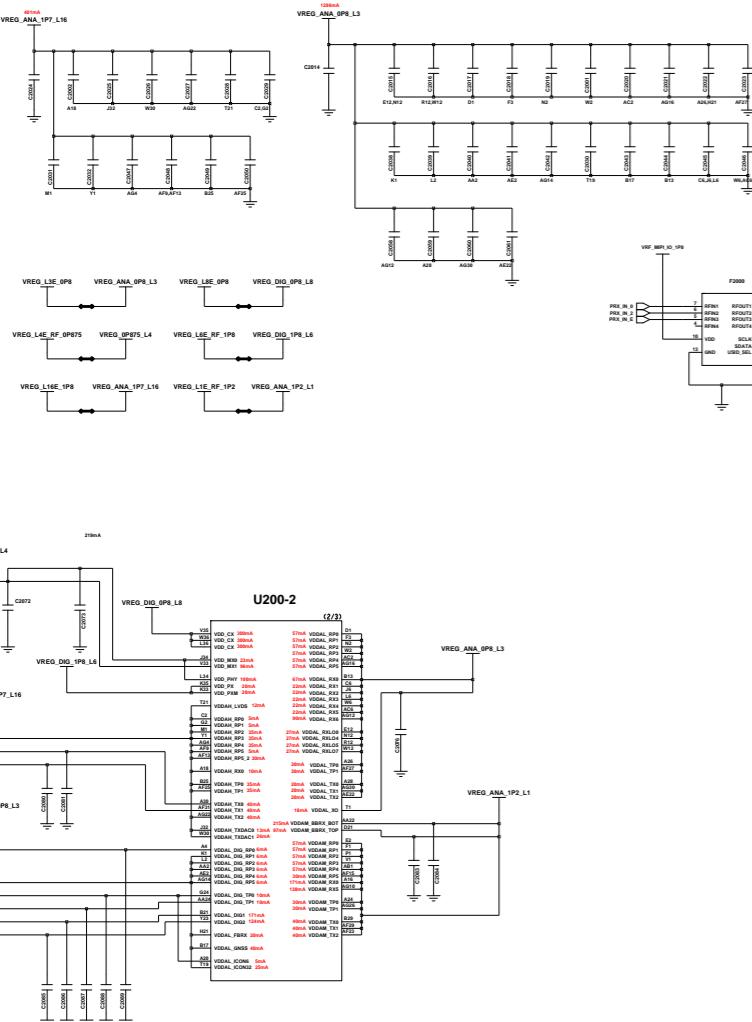
ET Modulator(QET5100#1)



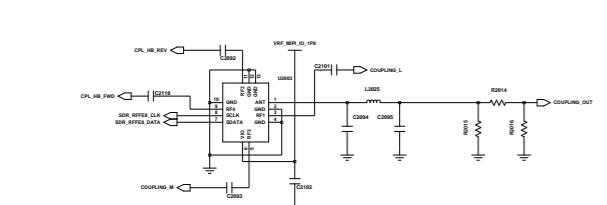
THERMIS



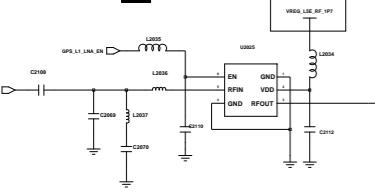
TRANSCEIVER(SDR865)



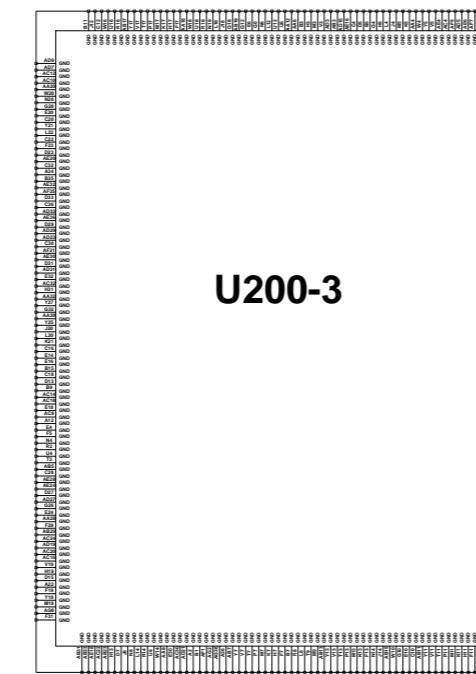
FBRX



GPS_L1



U200-3



SUB ANT SUB ANT1 (LB / N41 DRX MIMO)

DRX_LB
(B5/8/12/13/17/20/26/28_G850/900)

SUB ANT2 (MHB / GPS L1 / N41 / WIFI1 2G)

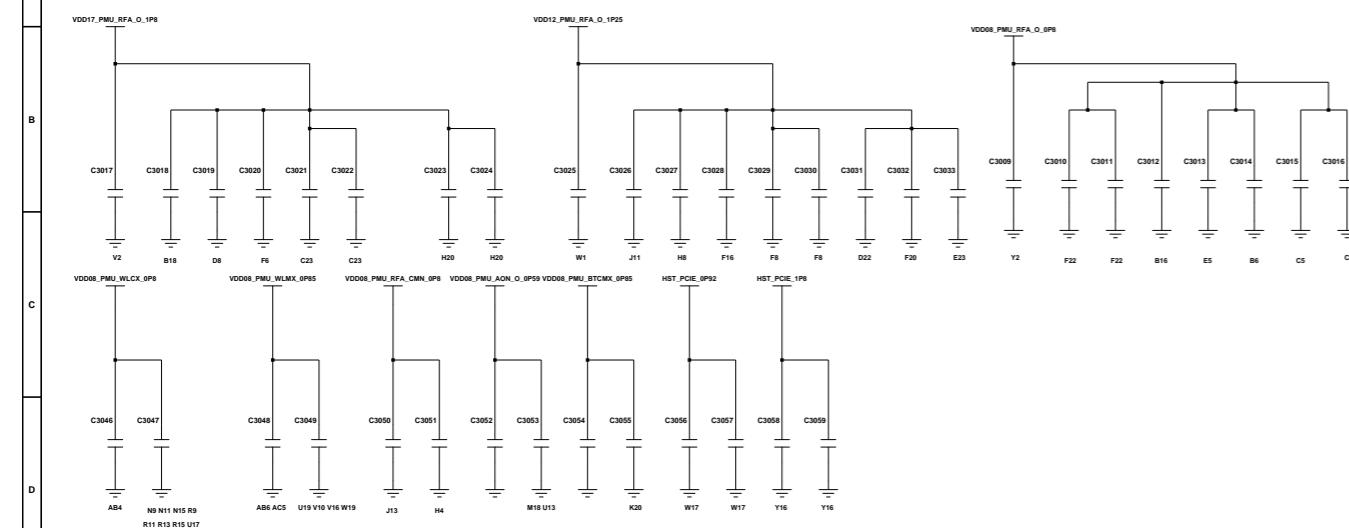
DRX_MHB
(B1/2/3/4/7/38/40/41/66_DCS/PCS)

SUB ANT3

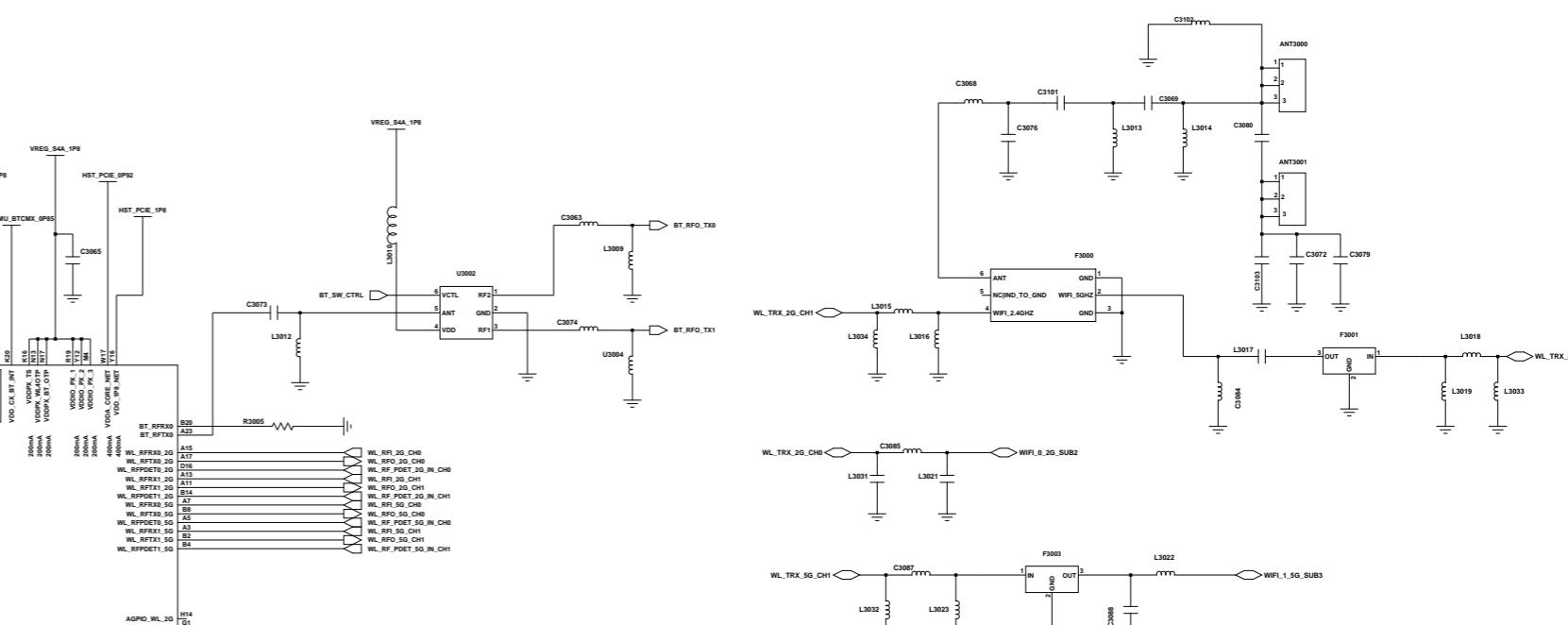
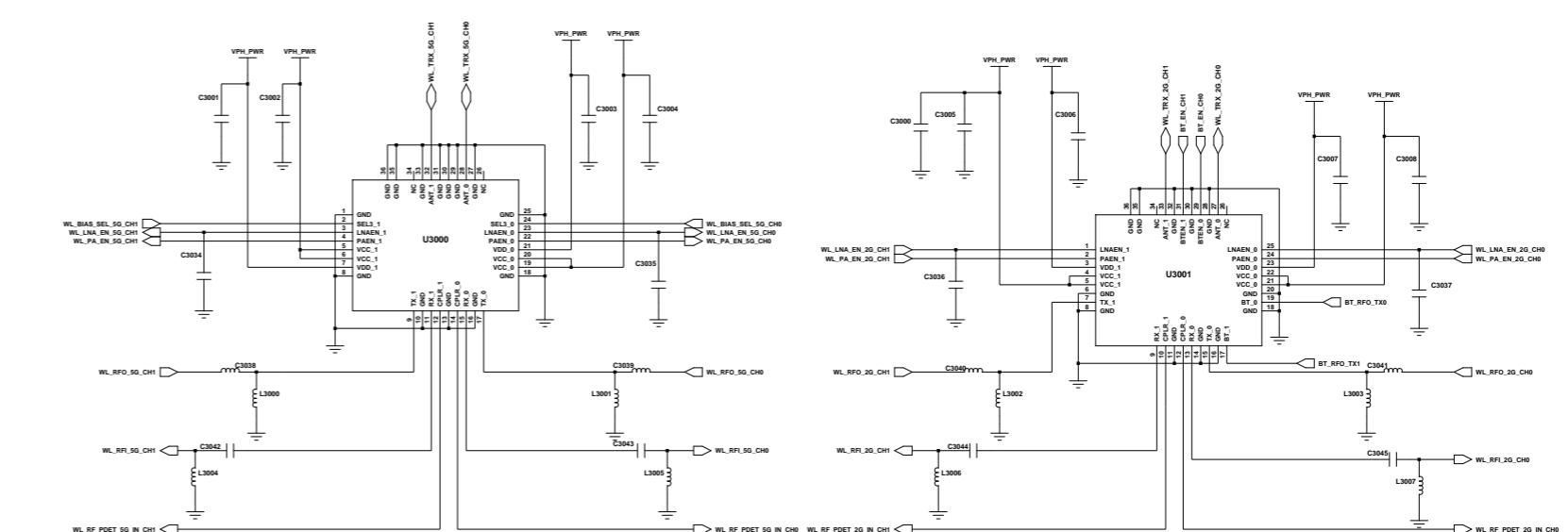
SUB ANT5 (N2_4 DRX MIMO_B46 PRX)

SUB ANT6 (B46 DRX)

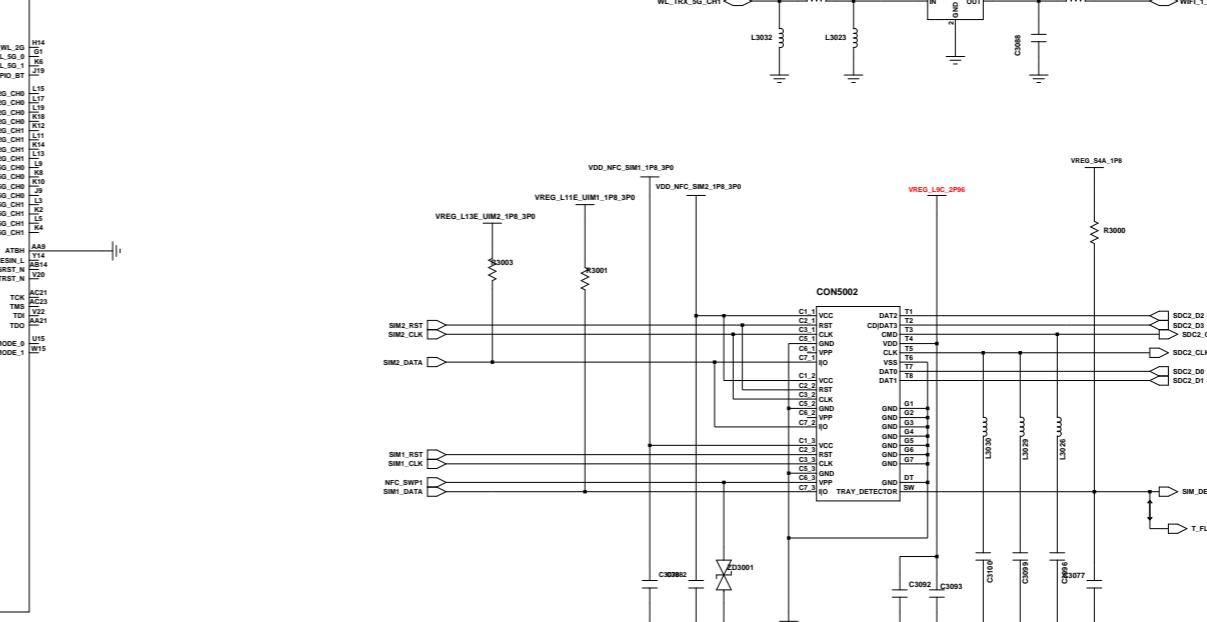
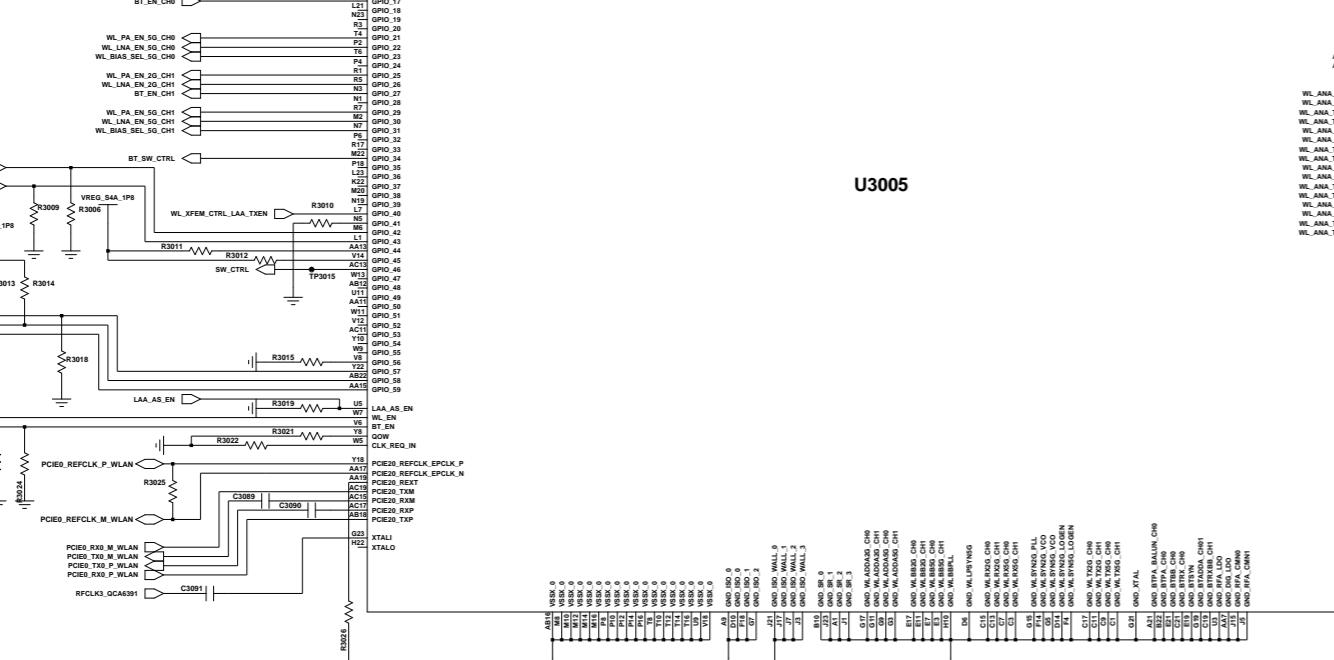
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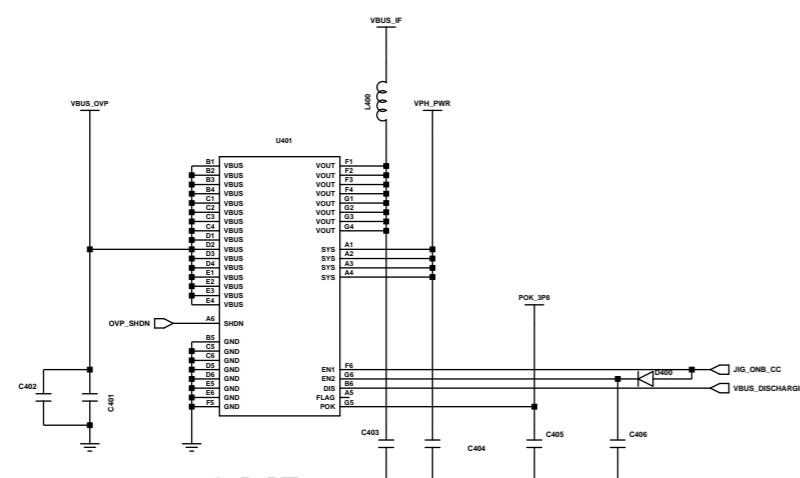
SUB ANT4



11

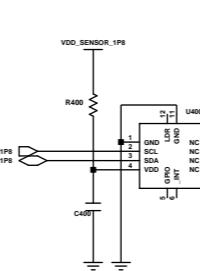


Power

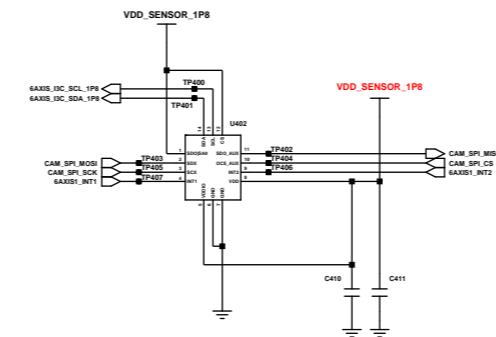


OVP

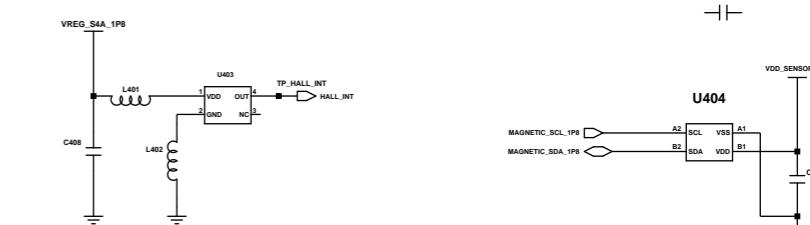
SENSORS



AMBIENT

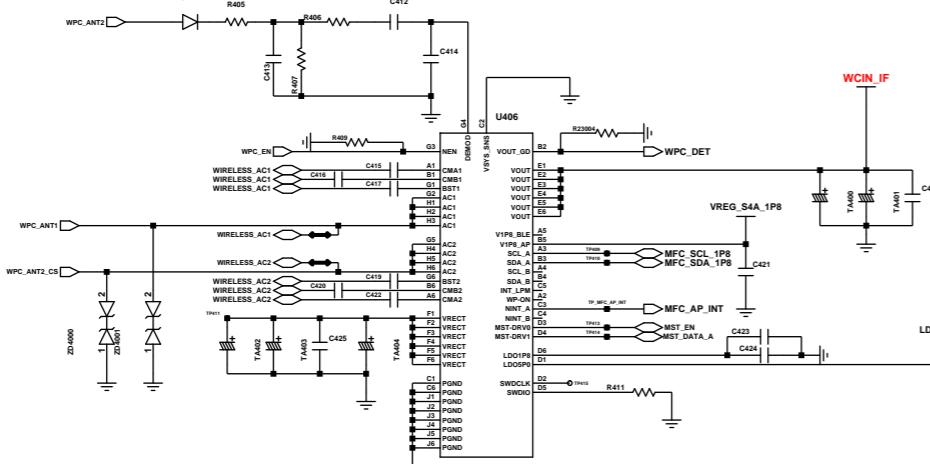


6 AXIS SENSOR
(GYRO,ACCEL)



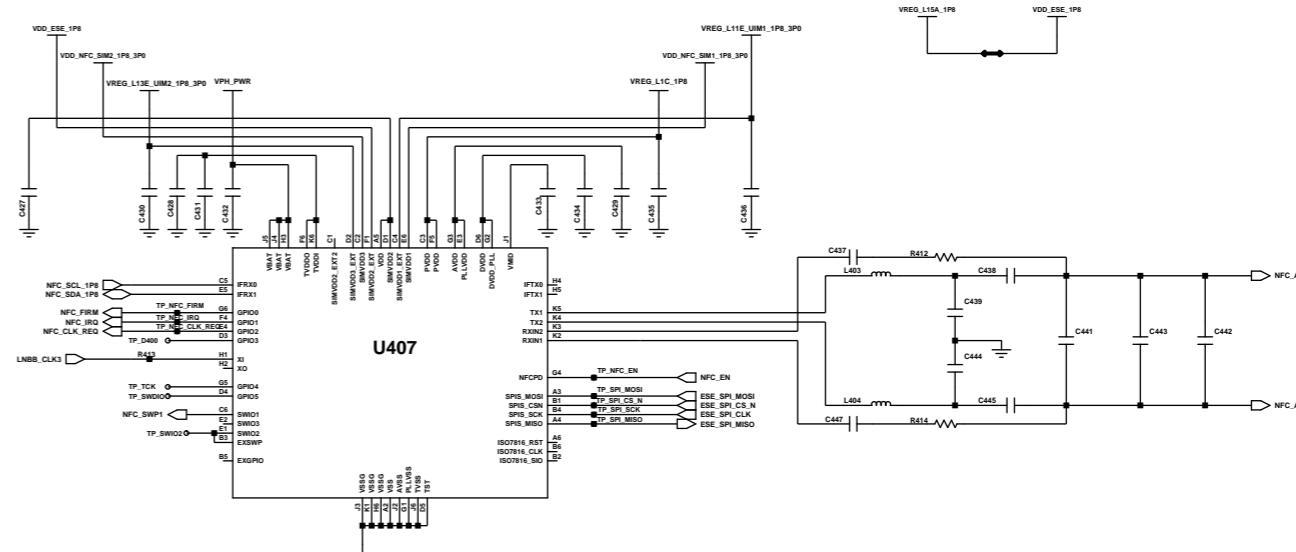
HALL_IC

MAGNETIC SENSOR

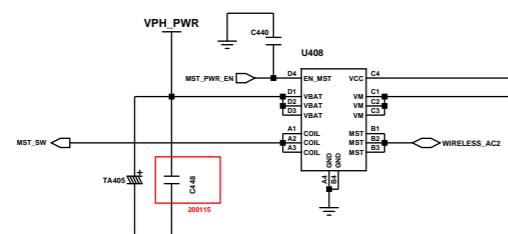


MFC IC(IDT)

NFC



MST Switch

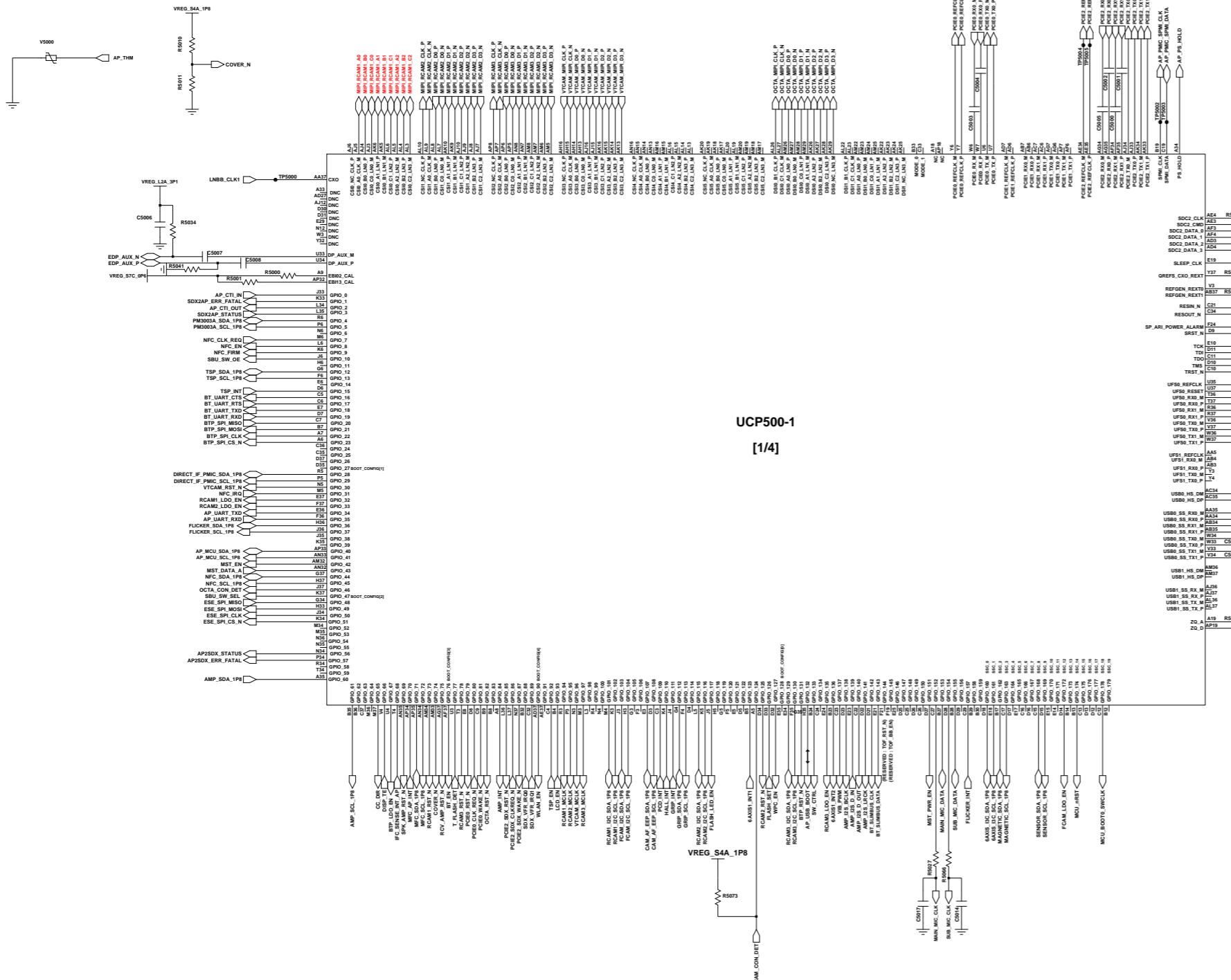


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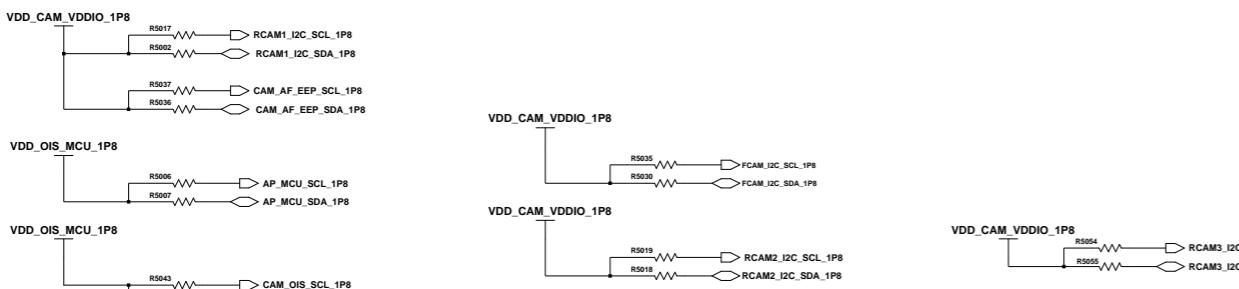
SM8250

(INTERFACE, GPIO, GND)

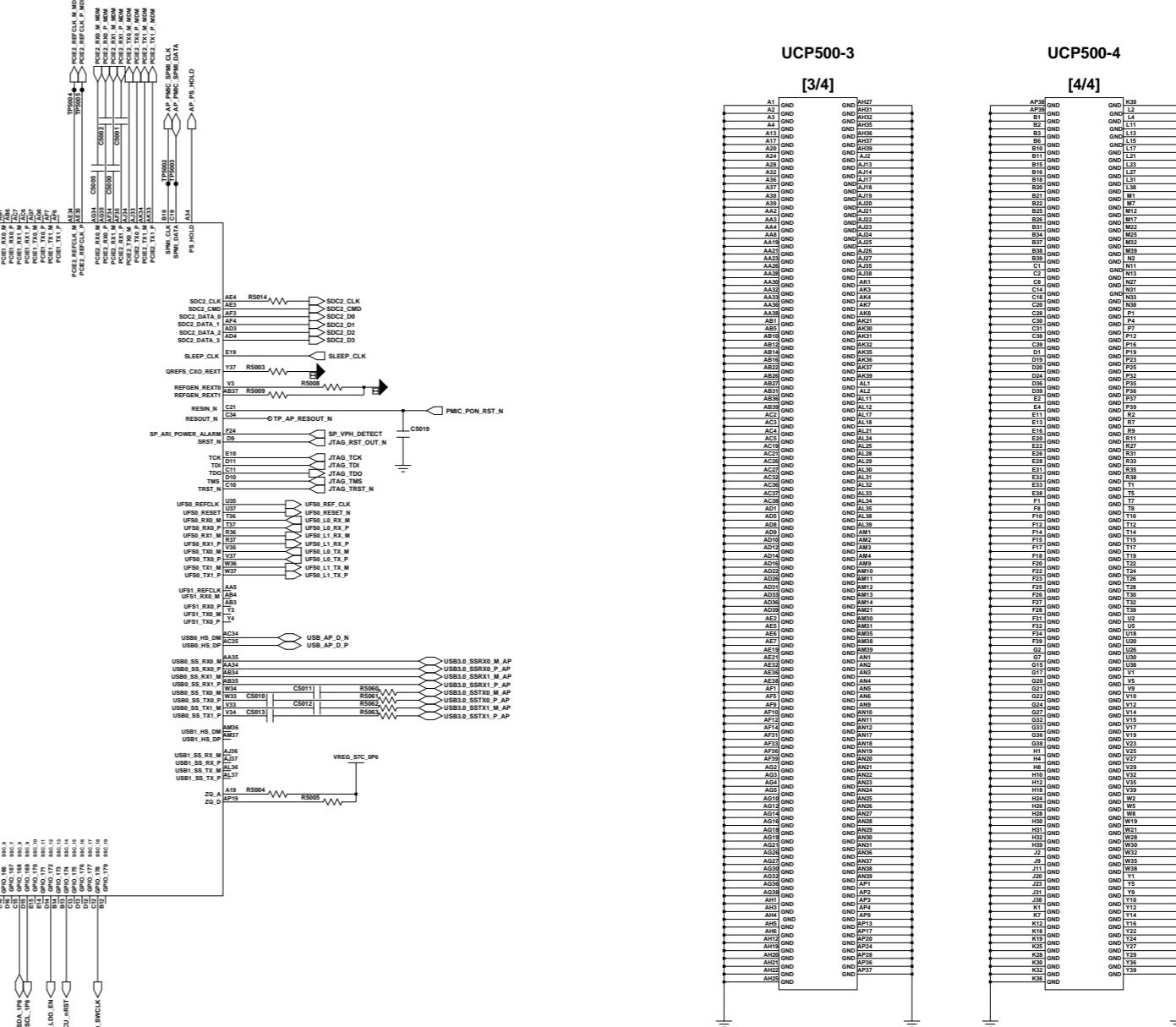
System



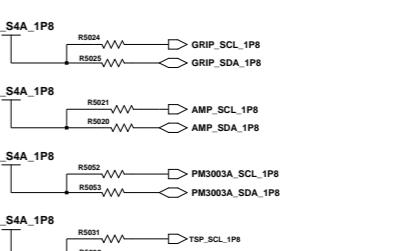
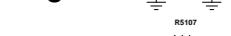
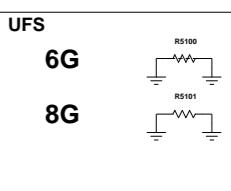
UCP5



I2C PULL U



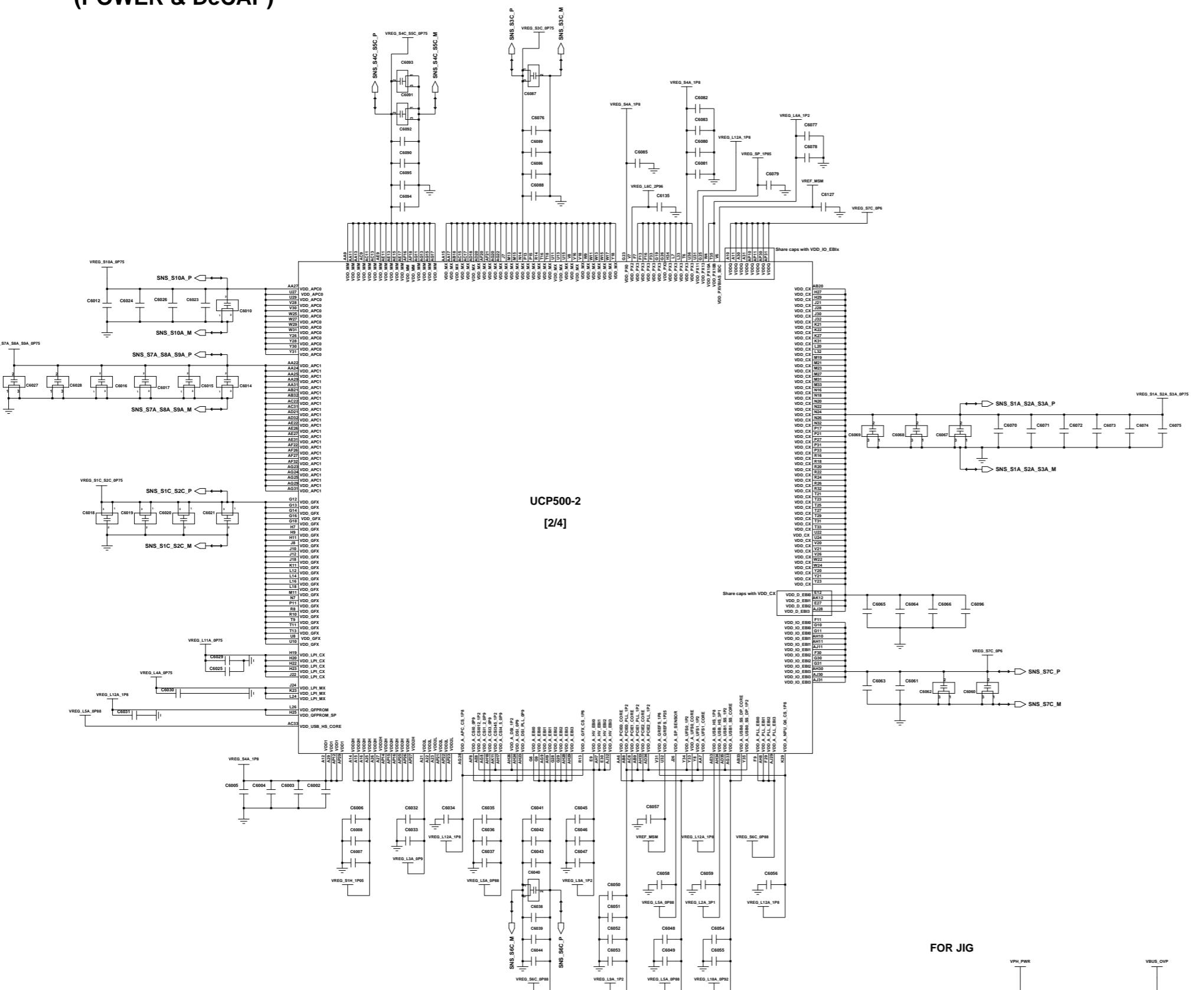
A rectangular label with two barcode symbols. The left barcode is labeled 'CON5000' above it. The right barcode is labeled 'CON5001' above it. Below the barcodes, the text '2D BARCODE' is printed in large, bold, black capital letters.



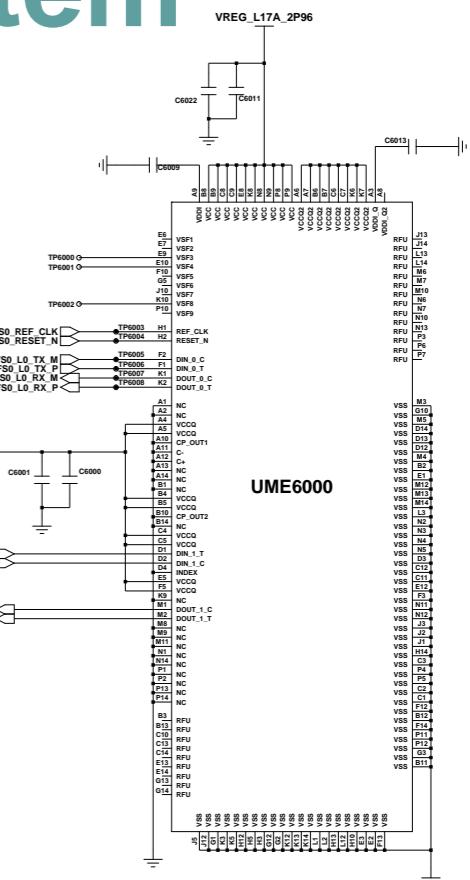
Engineer	SEC	TITLE: SM8250 + SDX55M	Size
Drawn by:	SEC		
R&D CHK:			
DOC CTRL CHK:			
MFG ENGR CHK:			
QA CHK:	Drawing Number		

SM8250

(POWER & DeCAP)

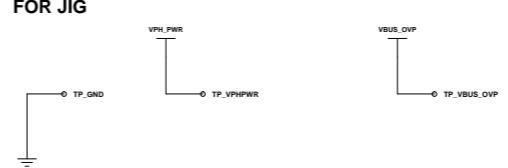
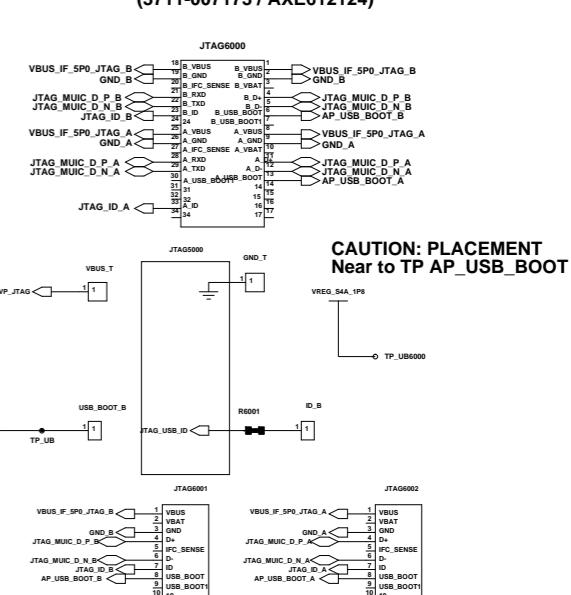


Power System



UFS3.1 128GB / 512GB

AP JTAG CONNECTOR

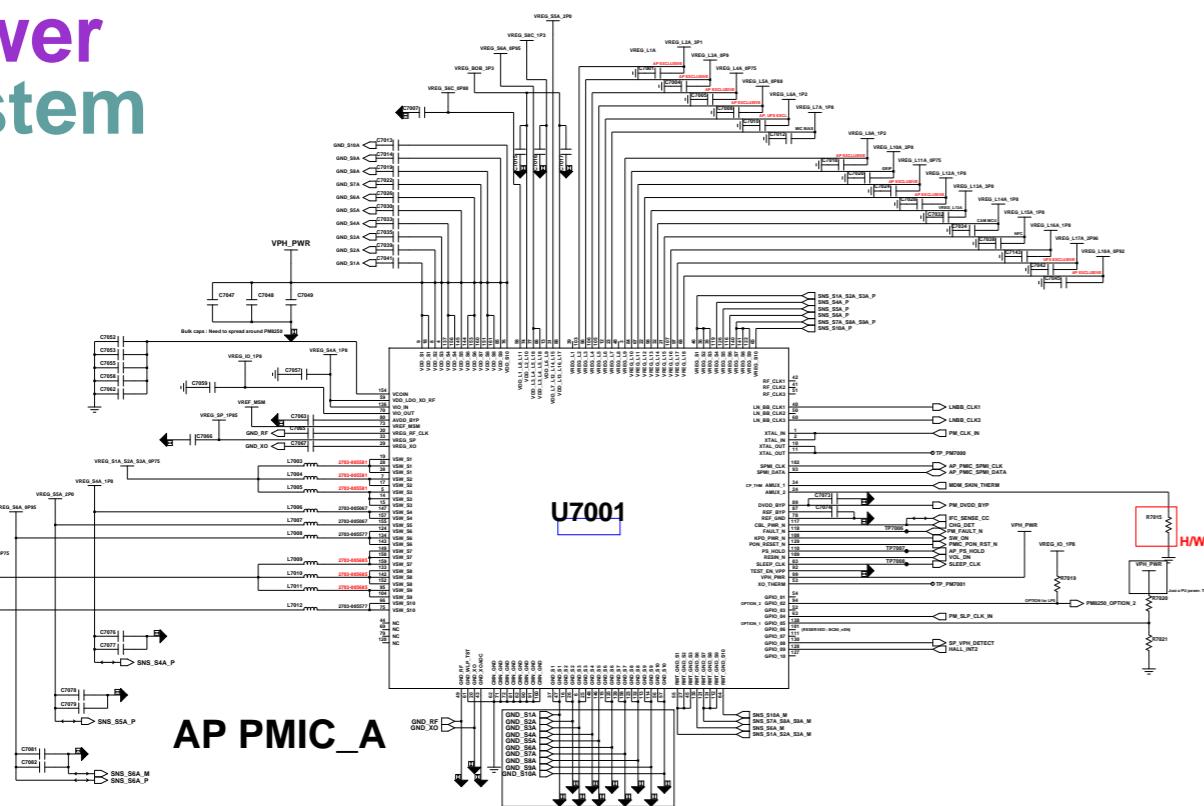


PCB array JTAG

Engineer:	SEC	
Drawn by:	SEC	
R&D CHK:	TITLE: _____	
DOC CTRL CHK:	Size: _____	
MFG ENGR CHK:	SM8250 + SDX55M	

AP PMIC set & CLK Generator

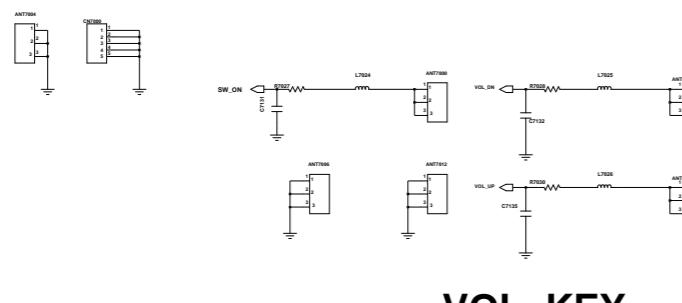
Power System



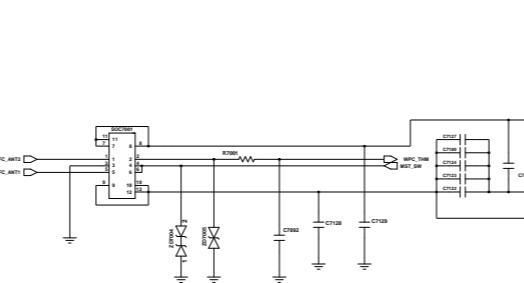
H/W ID table(PM8250 AMUX_2)

HW ID	BOARD REVISION	Value	Mech
00	R8 BRINGUP	6.04K	
01	R8 DV1	9.1K	
02	R8 DV2	12.4K	
03	R8 PV1	18K	
04		22K	
05		30K	
06	R8 PV2	39K	
07		47K	
08		56K	
09		68K	
10		82K	
11		100K	
12		120K	
13		150K	
14		180K	
15		200K	
16		240K	
17		280K	
18		330K	
19		430K	
20		560K	
21		750K	
22		1000K	
23		1500K	
24		3000K	

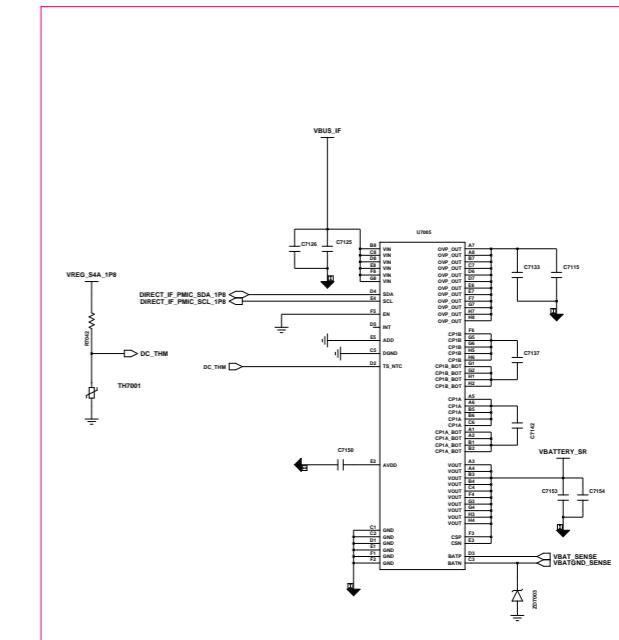
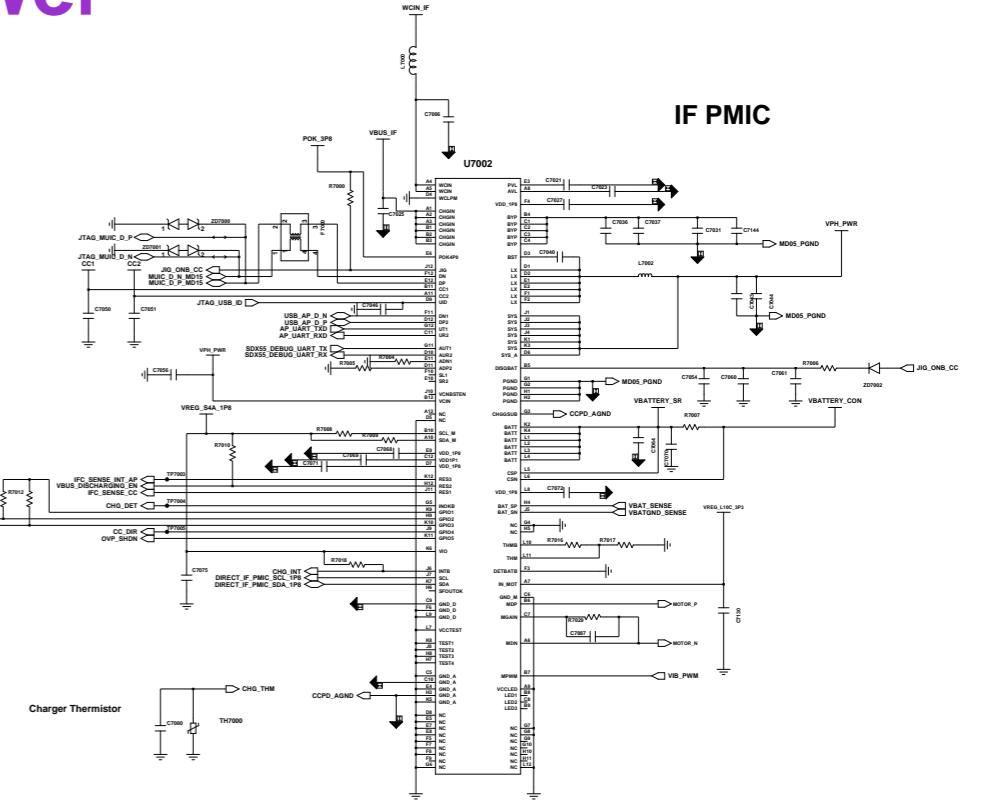
System Radiation



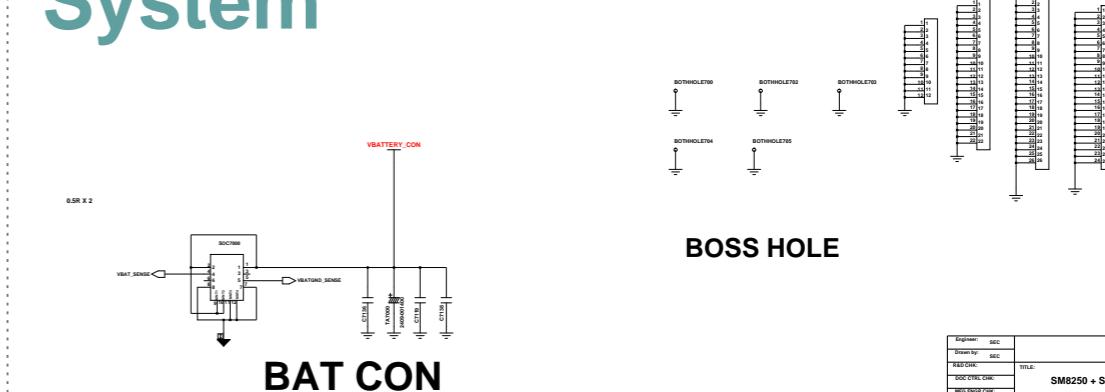
NFC+MST+W/C CON



Power



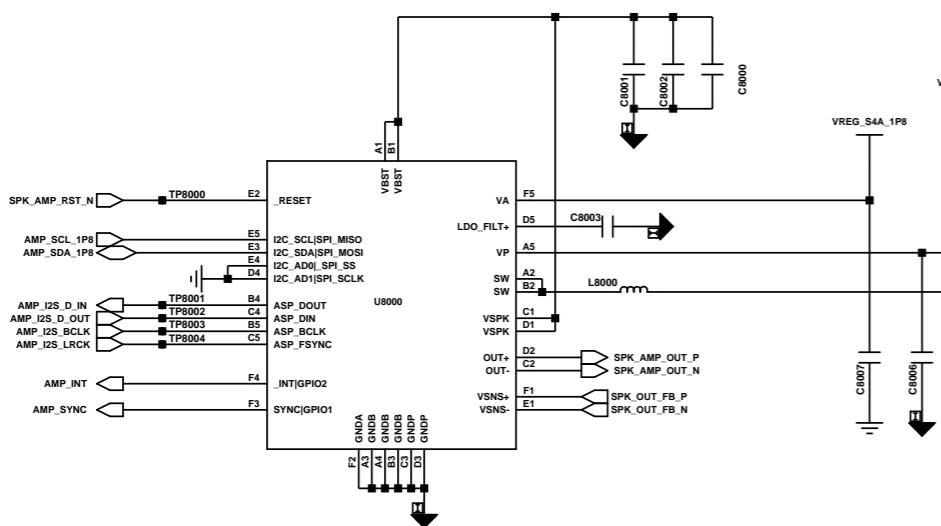
System



AUDIO PART

AUDIO

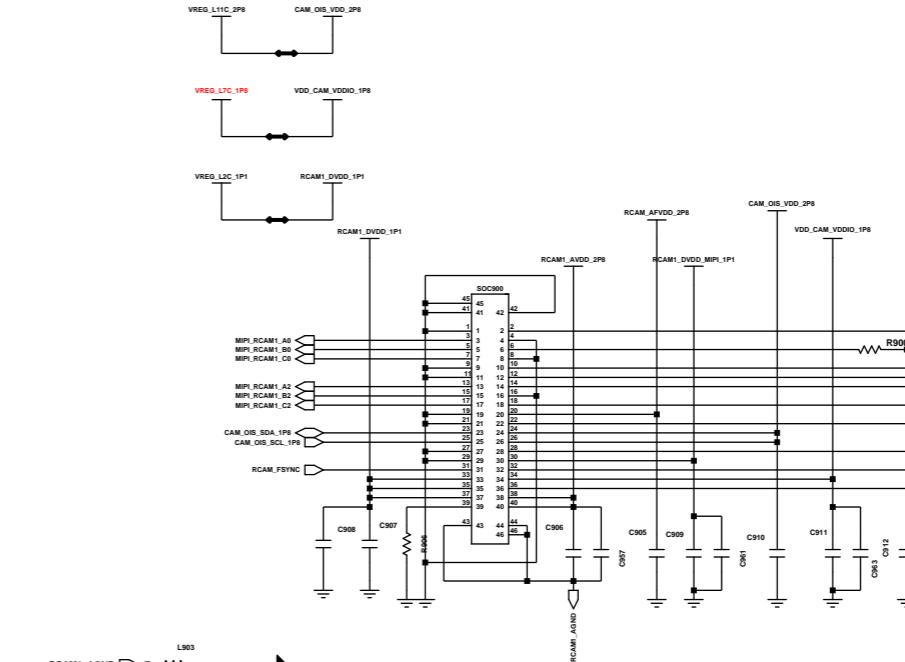
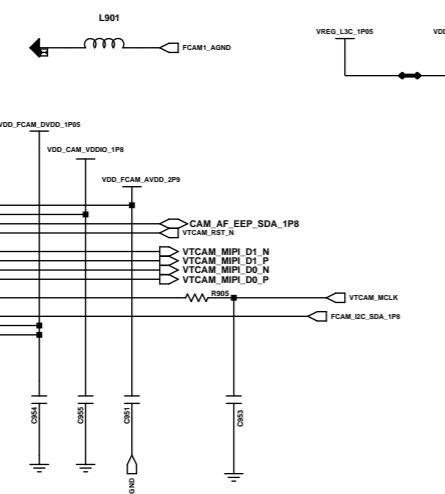
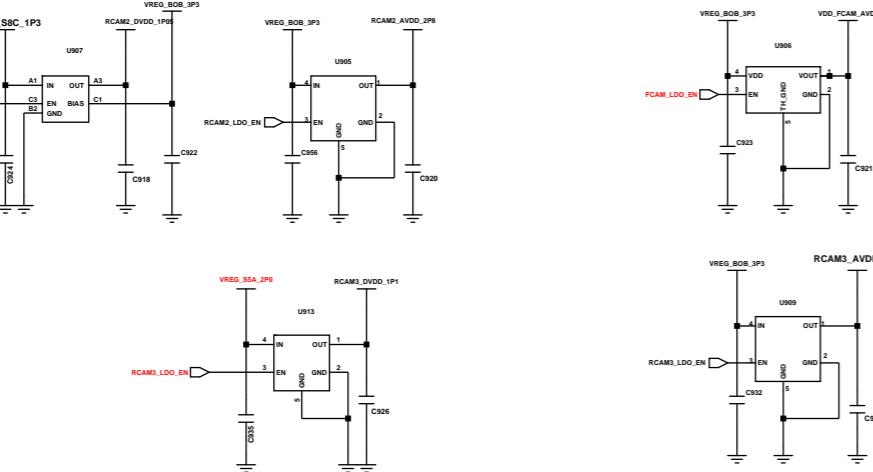
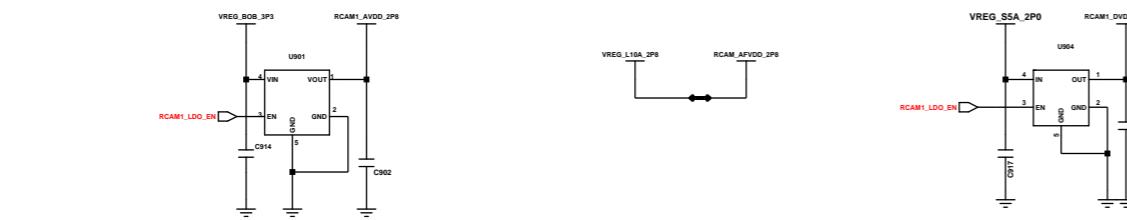
SPK AMP



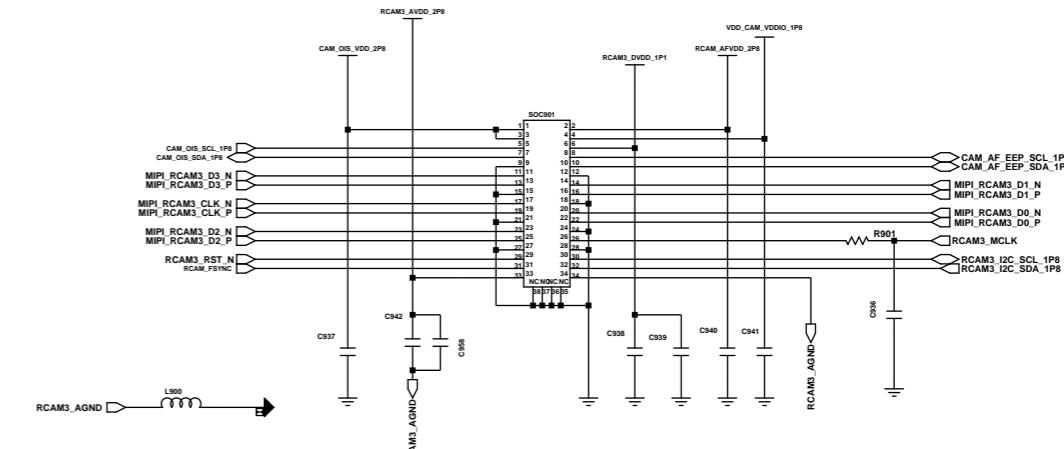
CAMERA

Visual

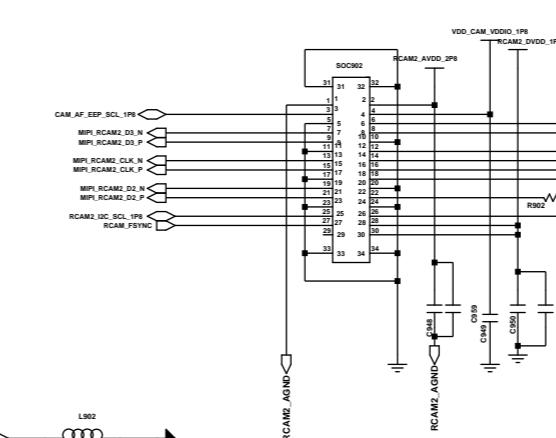
CAM_PMIC



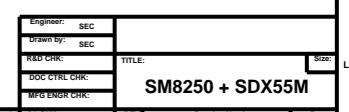
12M 2PD OIS WIDE CAM



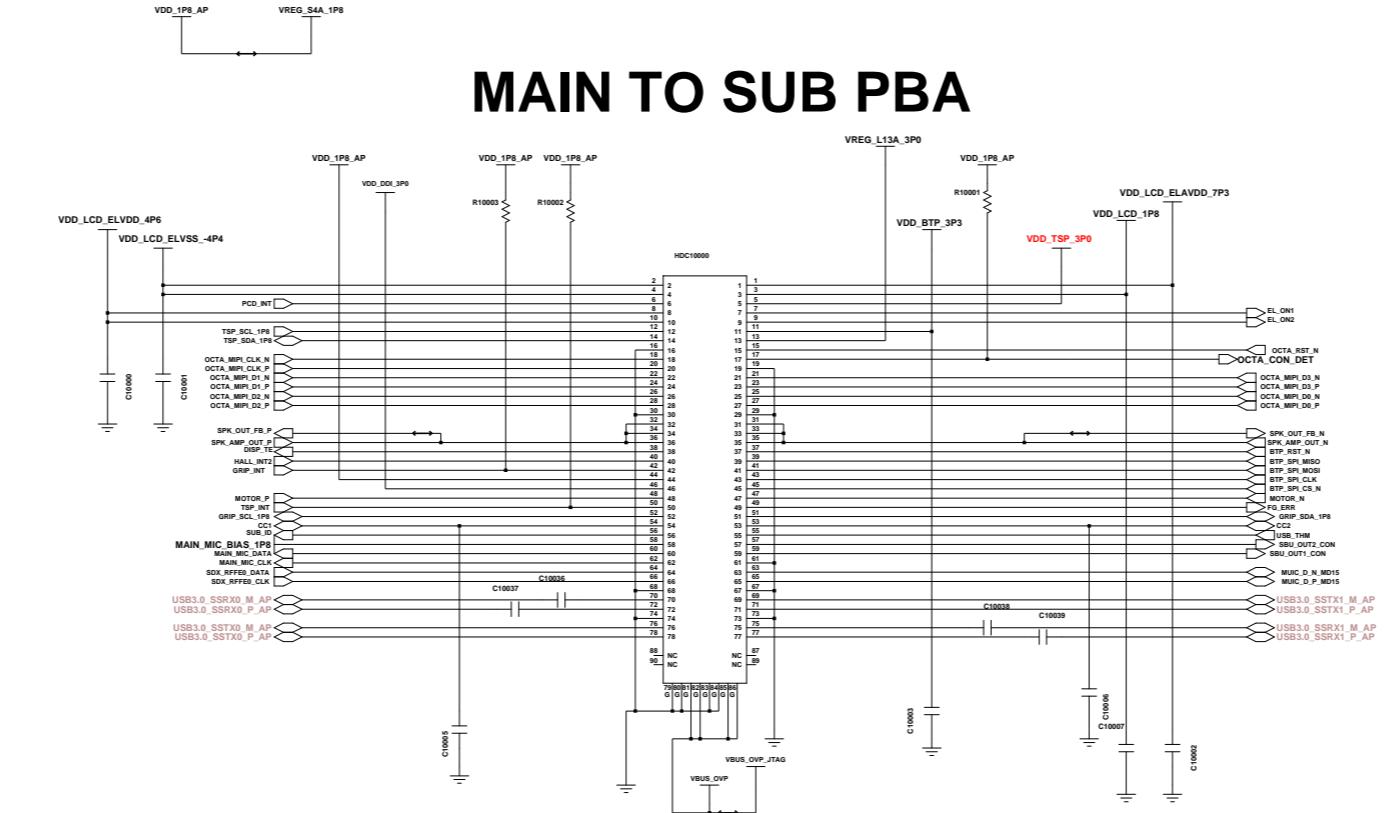
8M TELE CAM



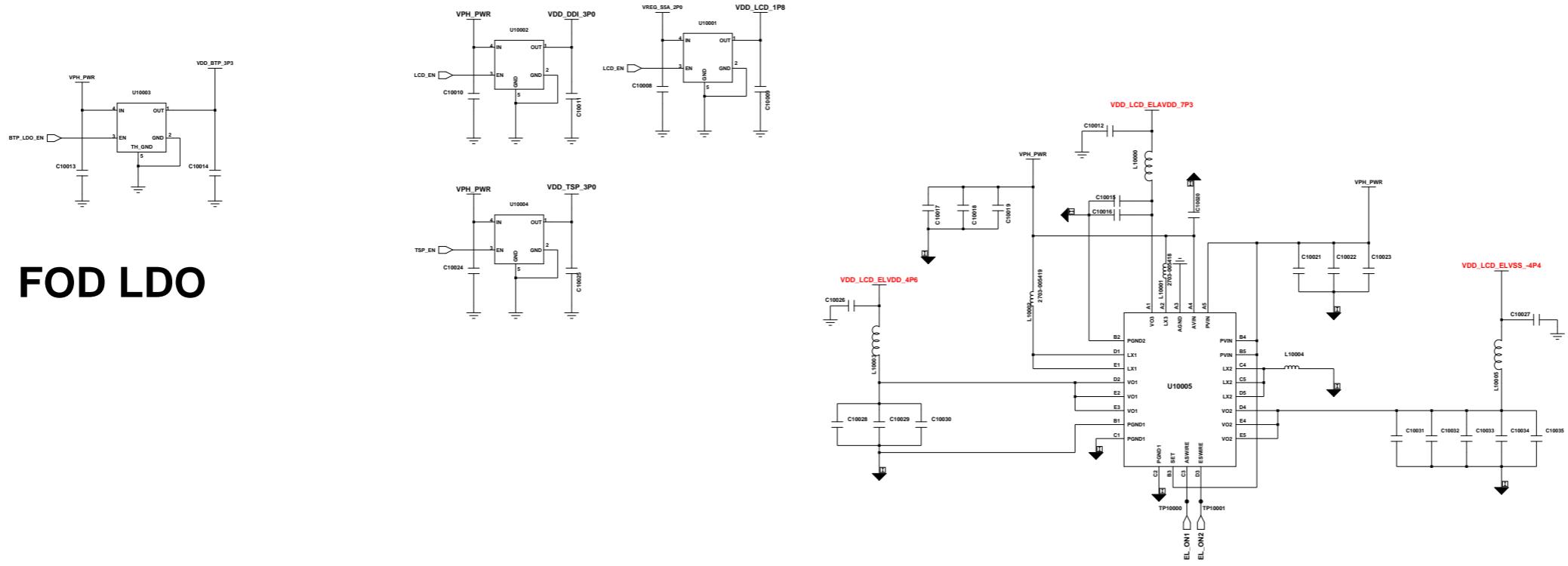
12M SUPER WIDE CAM



DISPLAY



DISPLAY



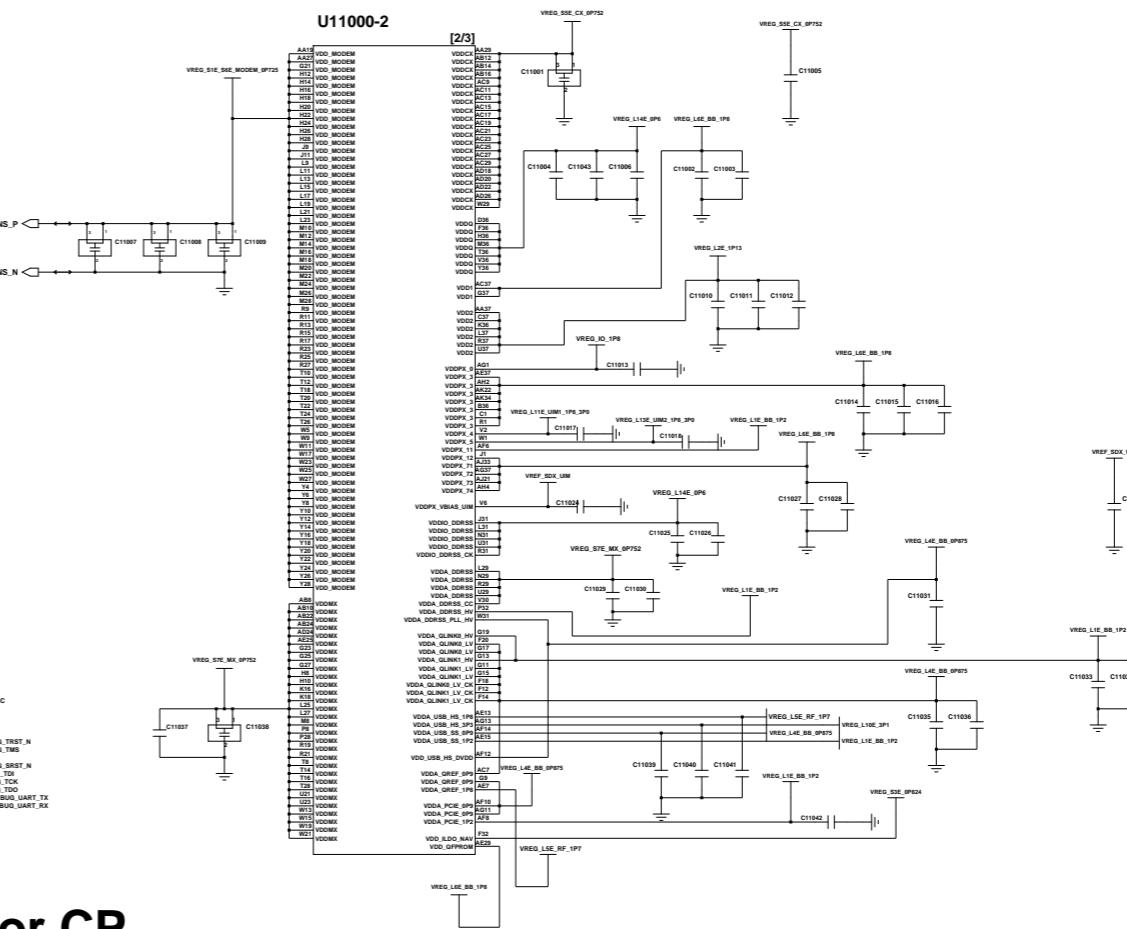
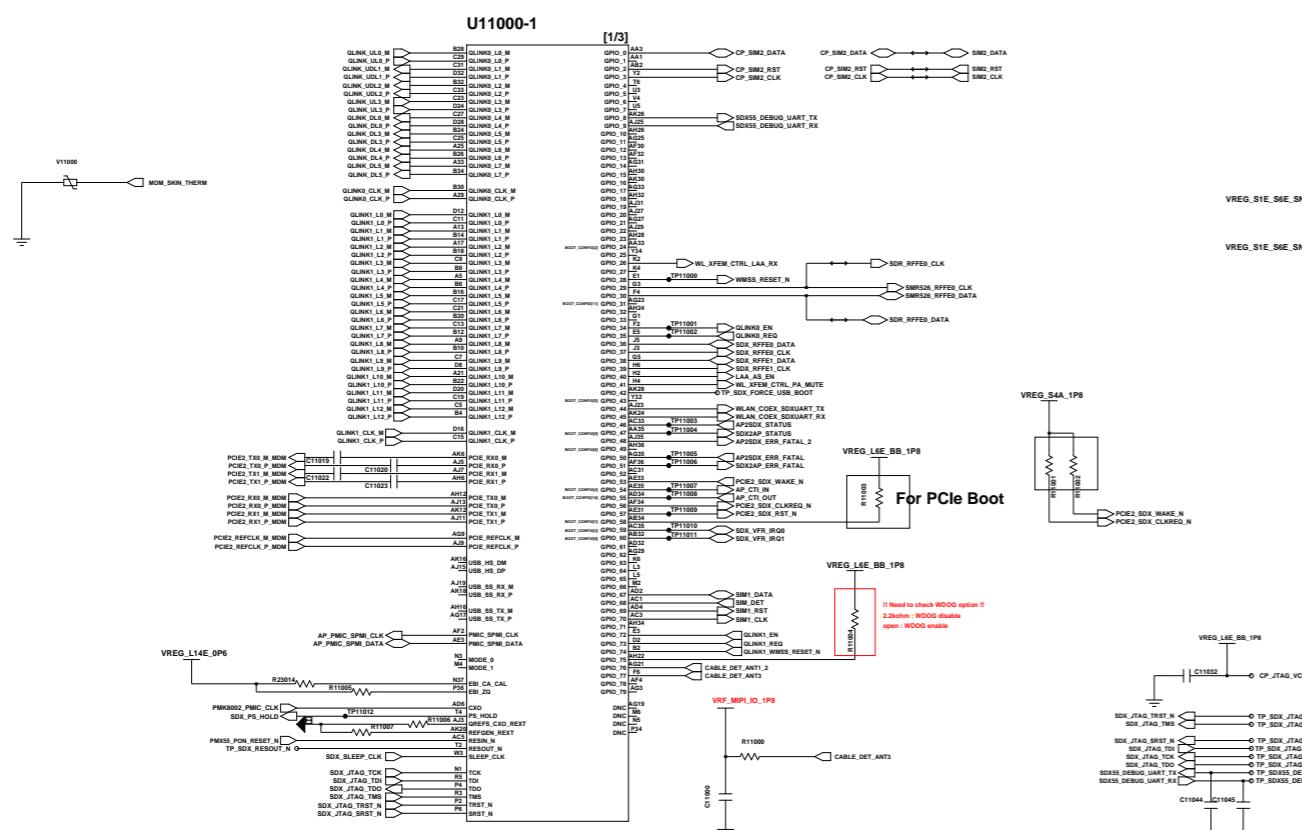
FOD LDO

Visual

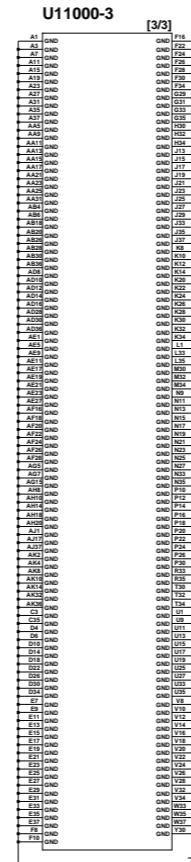
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SDX55M

System



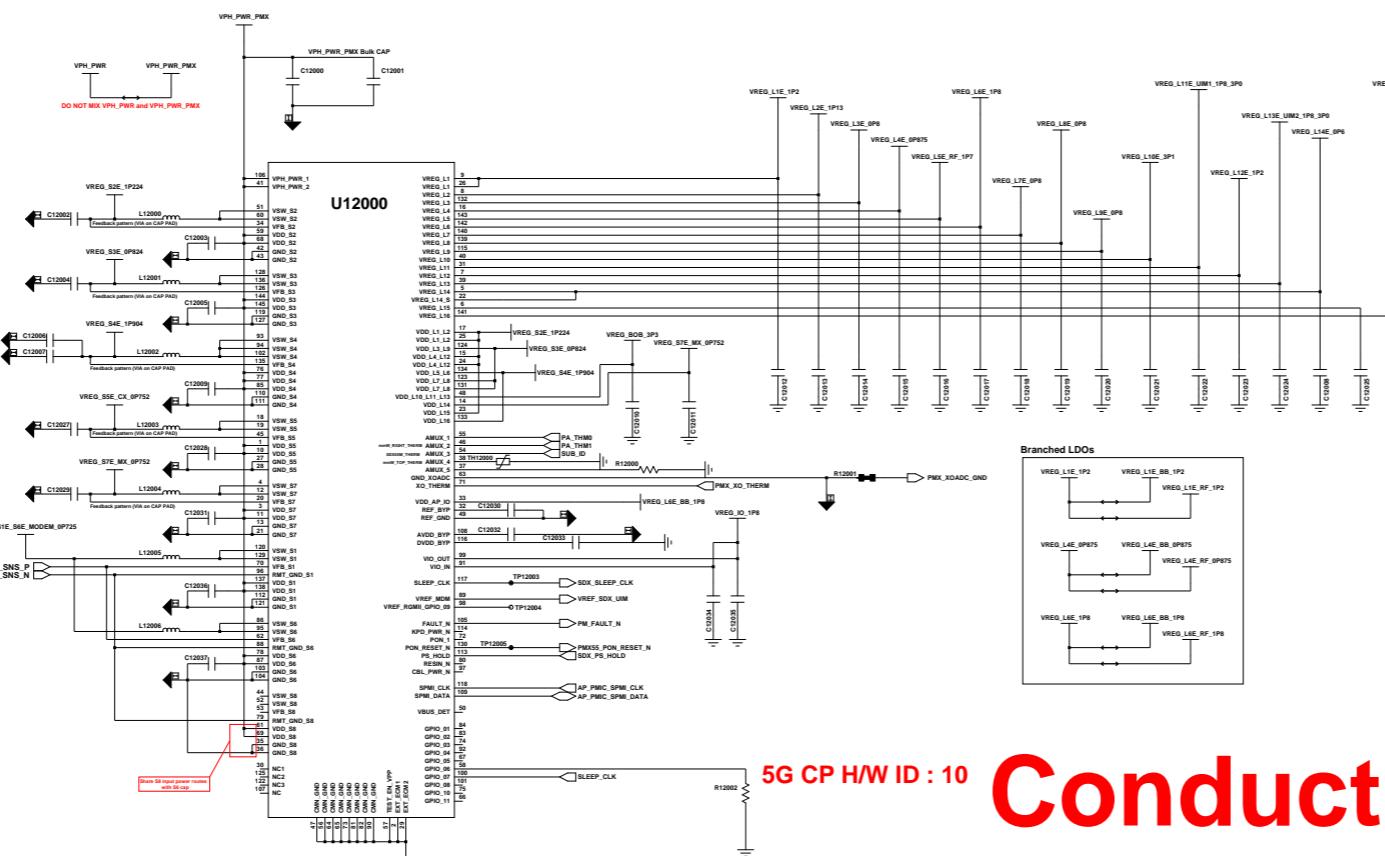
JTAG connector for CP



Engineer:	SEC	SAMSUNG ELECTRONICS
Drawn by:	SEC	
R&D CHK:	TITLE: <input type="text"/>	
DOC CTRL CHK:		
MFG ENGR CHK:		
ed:	QA CHK:	REV: <input type="text"/> Drawing Number: <input type="text"/> Page: <input type="text"/>

CP PMIC

Power



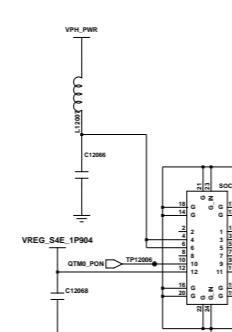
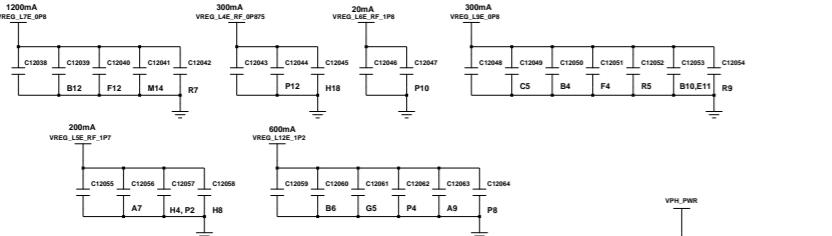
5G CP H/W ID : 10

Conduction

PMX55

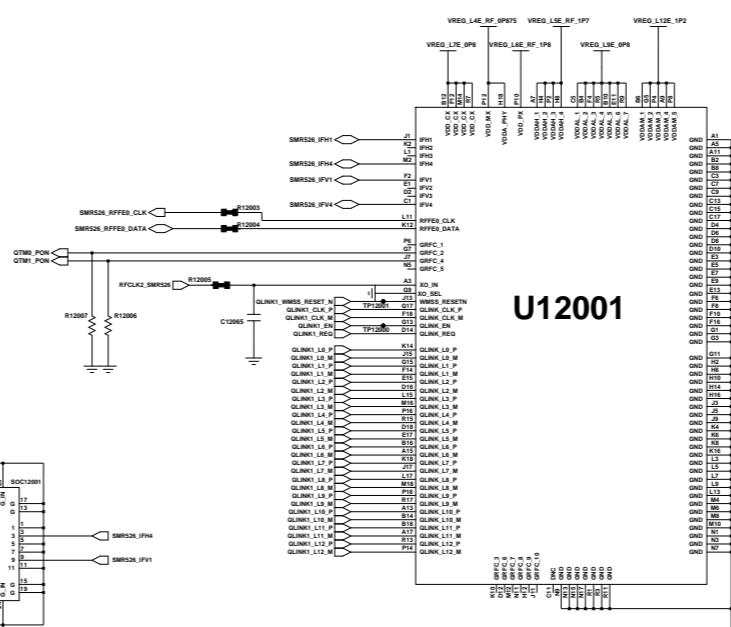
CP H/W ID table (PMX55 GPIO_06)			
HW ID	BOARD REVISION	Value	Mech
00	R8 BRINGUP	6.04K	
01	R8 DV1	9.1K	
02	R8 DV2	12.4K	KI10
03	R8 PV1	18K	KI10
04		22K	KI20
05		30K	
06	SM-G781W_REV03	39K	KI30
07	SM-G781V_REV03	47K	KI30
08	SM-G781U_REV03	56K	KI40
09	SM-G781V_REV03+B46	68K	KI40
10	SM-G781U_REV03+B46	82K	KI40
11		100K	KI50
12		120K	VY60
13		150K	VY60
14		180K	VY70
15		200K	VY70
16		240K	VY75
17		280K	VY75
18		330K	
19		430K	
20		560K	
21		750K	
22		1000K	
23		1500K	
24		3000K	

5G IFIC



mmW ANT CONN (RIGHT)

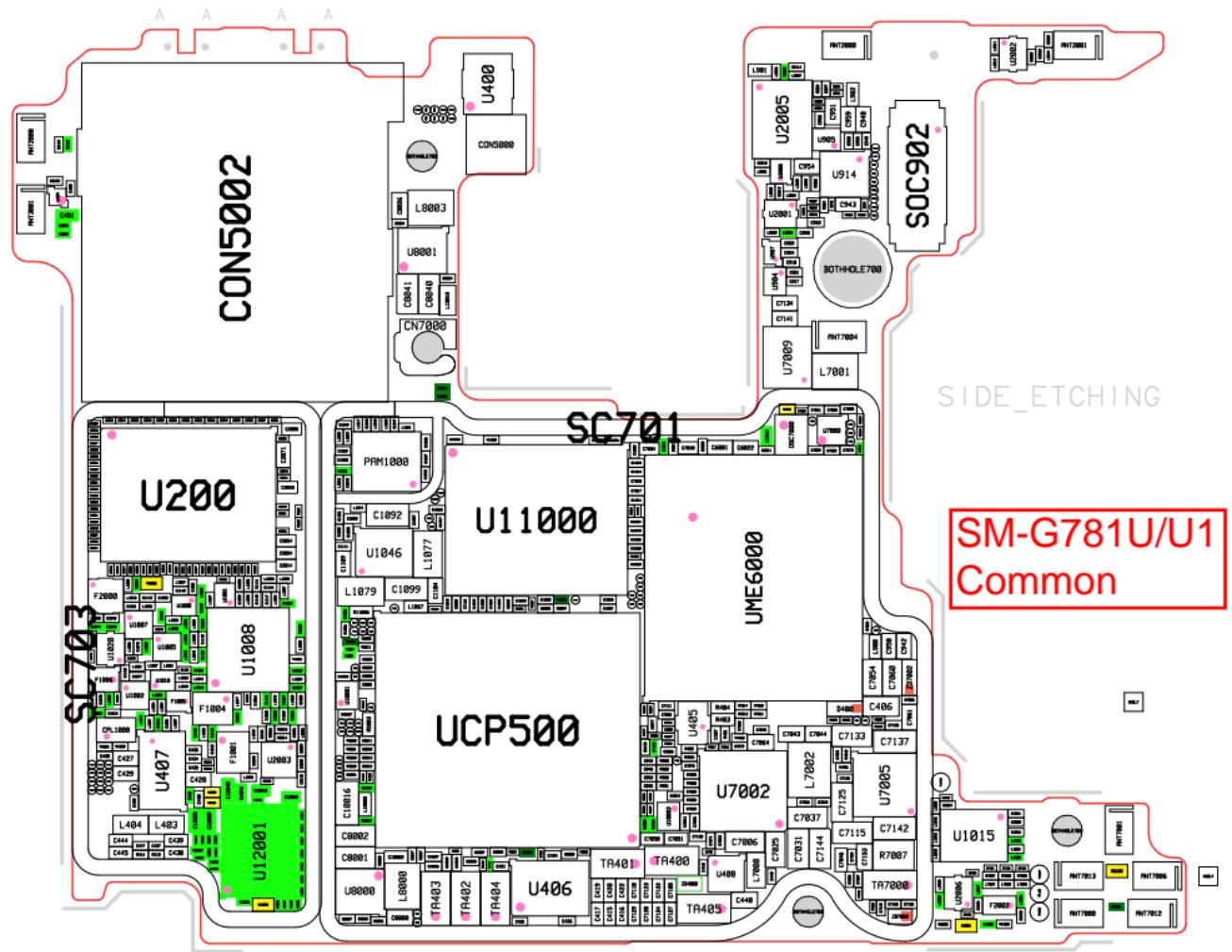
mmW ANT CONN (LEFT)

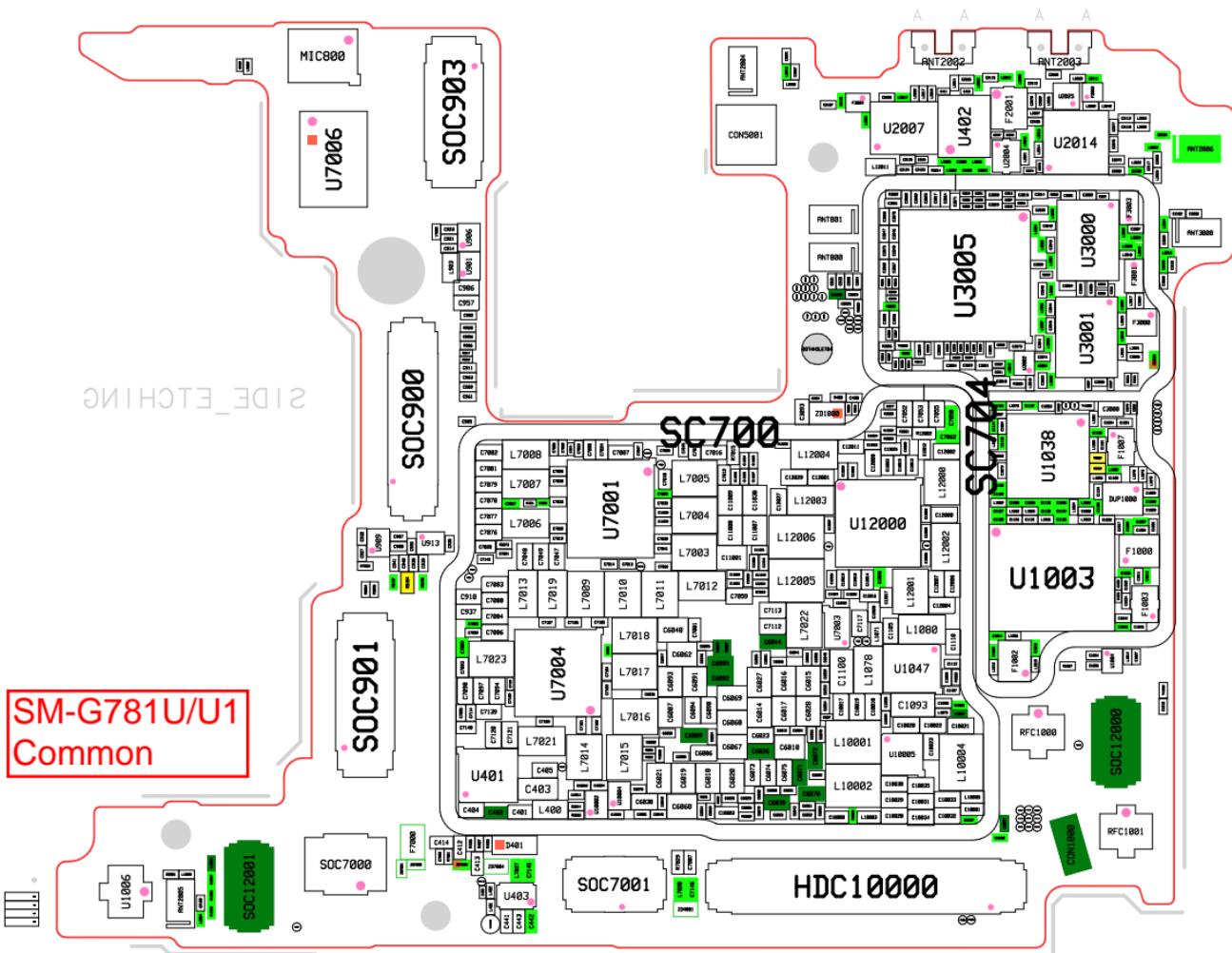


U12001

Radiation

Engineer:	SEC	SAMSUNG ELECTRONICS		
Drawn by:	SEC			
R&D CHK:	TITLE:			Size: <input type="checkbox"/>
DOC CTRL CHK:				
MFG ENGR CHK:				
ged:	QA CHK:	REV:	Drawing Number:	Page: 13





SM-G781K (R8)

2020. 07. 06

sheet01 :

sheet02 : RF (2/2)

sheet03 : BT/WIFI, SIM

sheet04 : OVP LS, NFC , SENSORS

sheet05 : SM8250

sheet06 : SM8250 POWER/GND, JTAG, UFS

sheet07 : PM8250, PM8150C, PMK8002, IF PMIC

sheet08 : AUDIO

sheet09 : CAMERA

sheet10 : DISPLAY

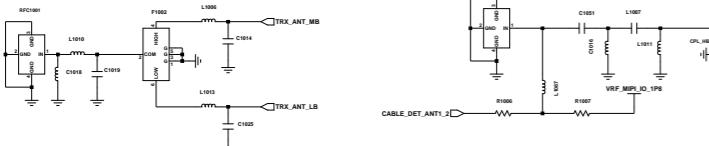
sheet11 : SDX55M(5G MODEM)

sheet12 : PMX55M(5G POWER)

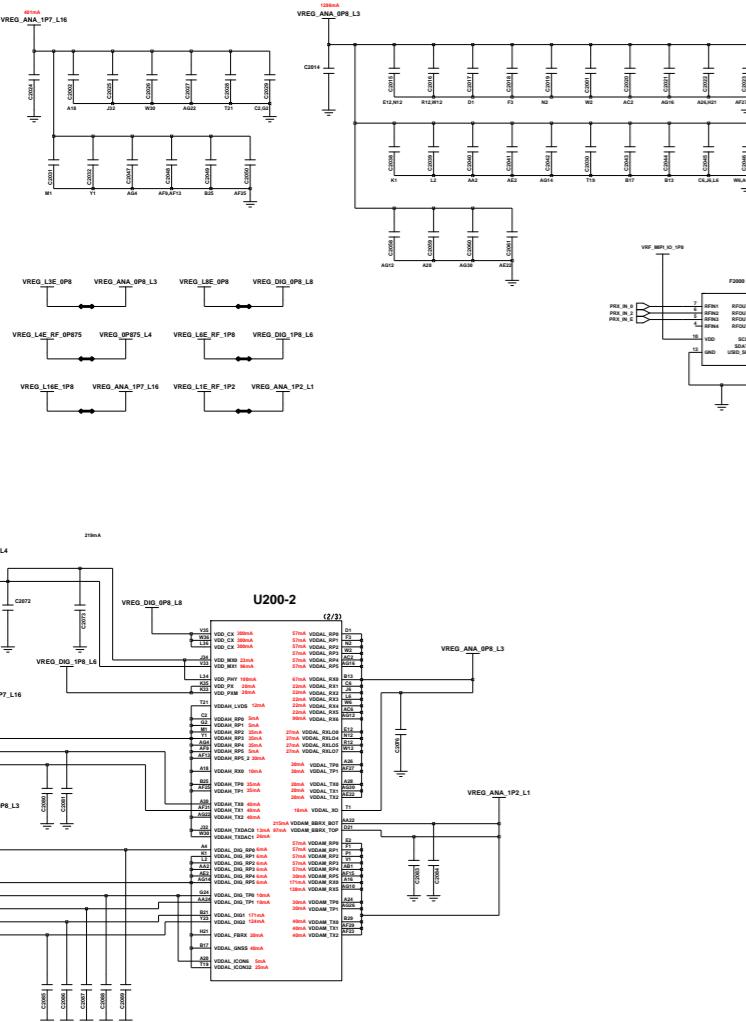
Engineer:	
Drawn by:	
REQ CHK:	
DOC CTRL CHK:	
MPG ENGR CHK:	

RF PART 1

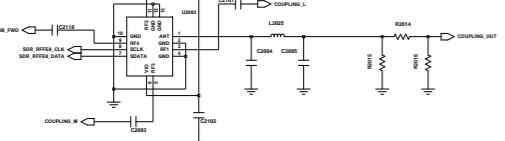
MAIN ANT1 LMB



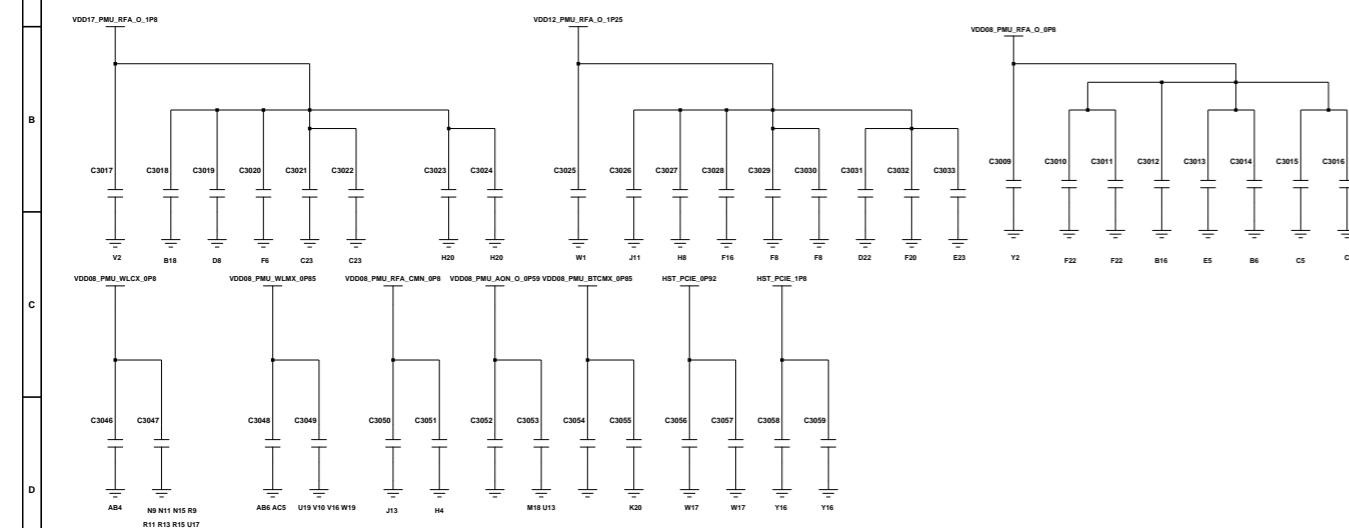
TRANSCEIVER(SDR865)



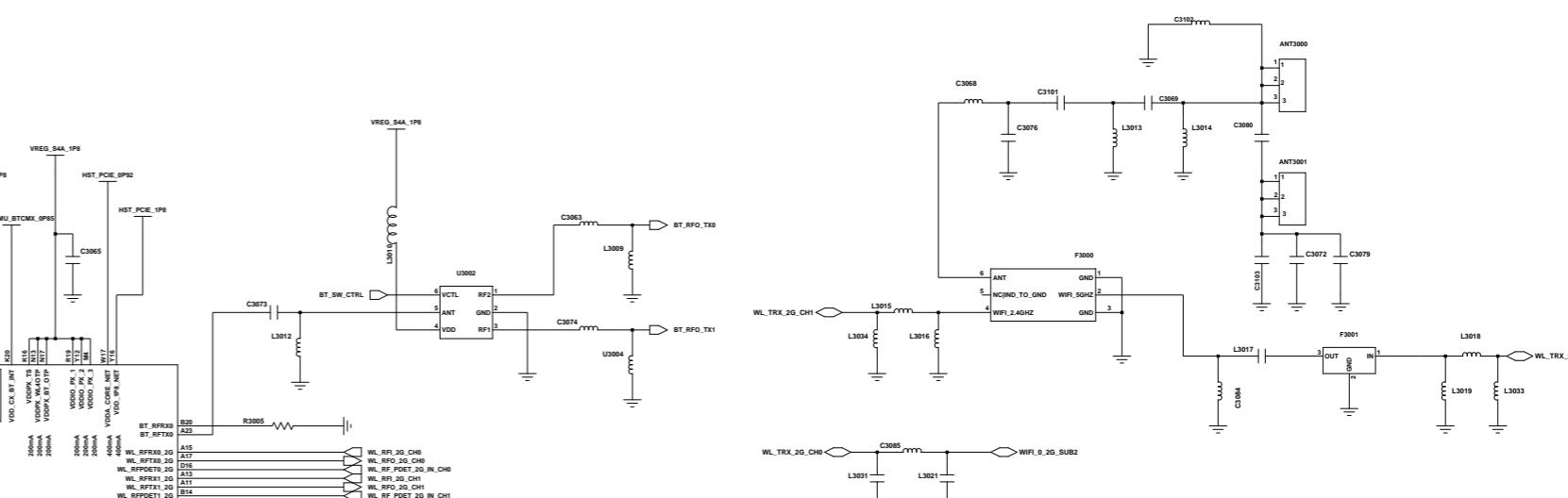
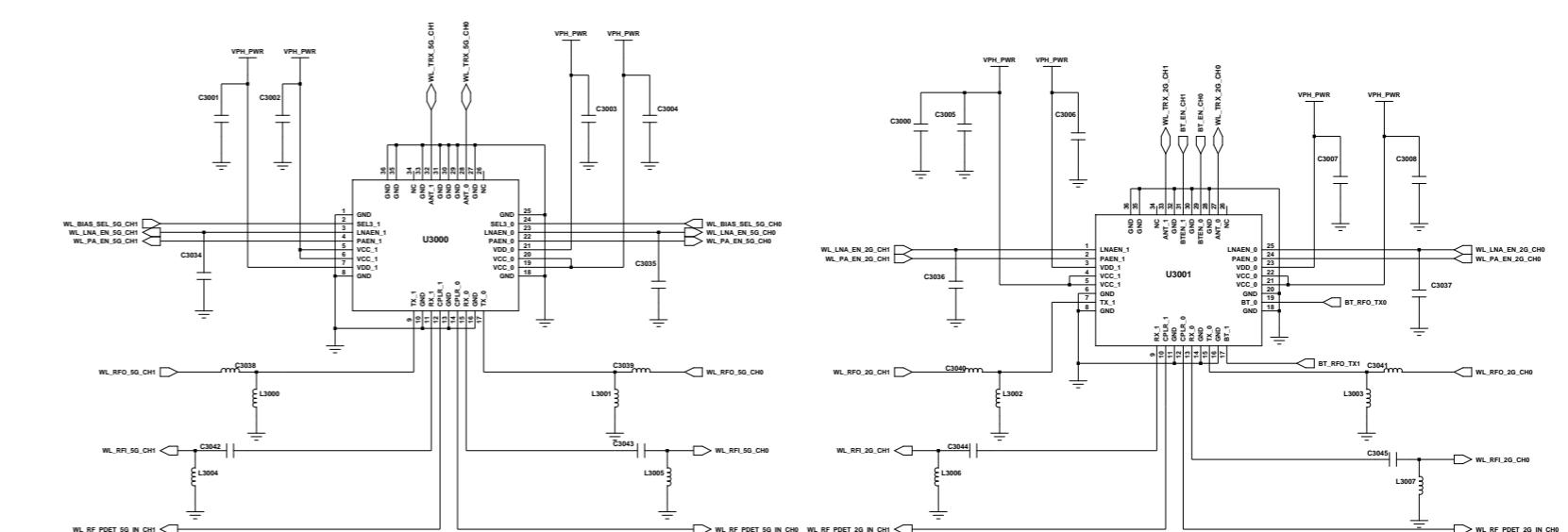
FBRX



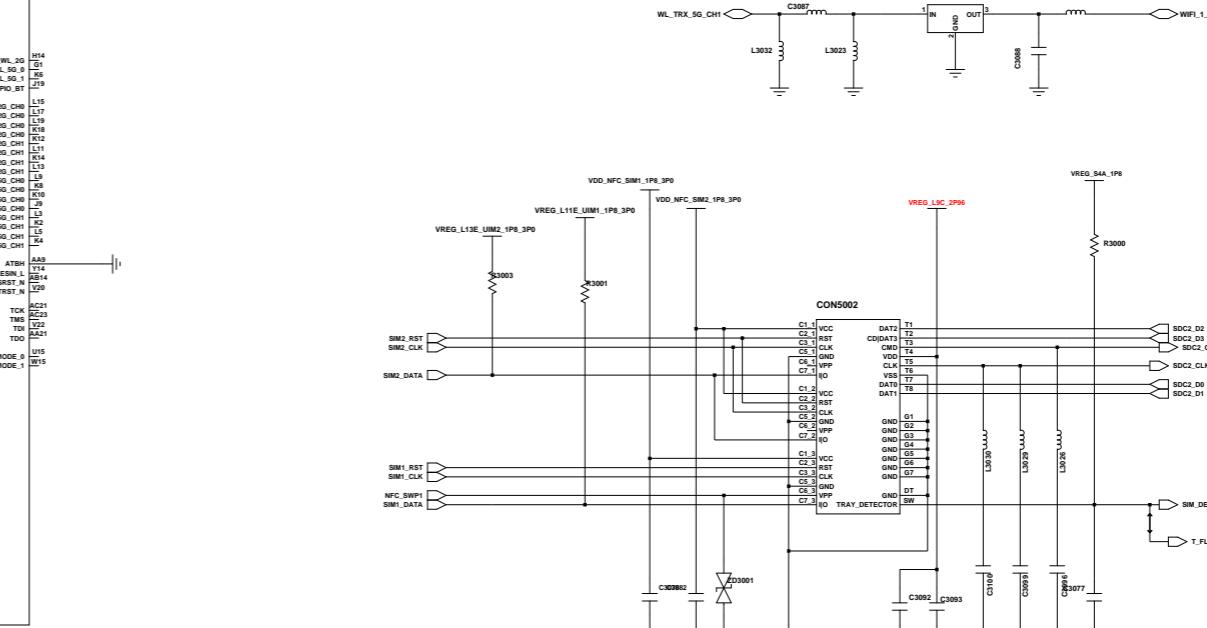
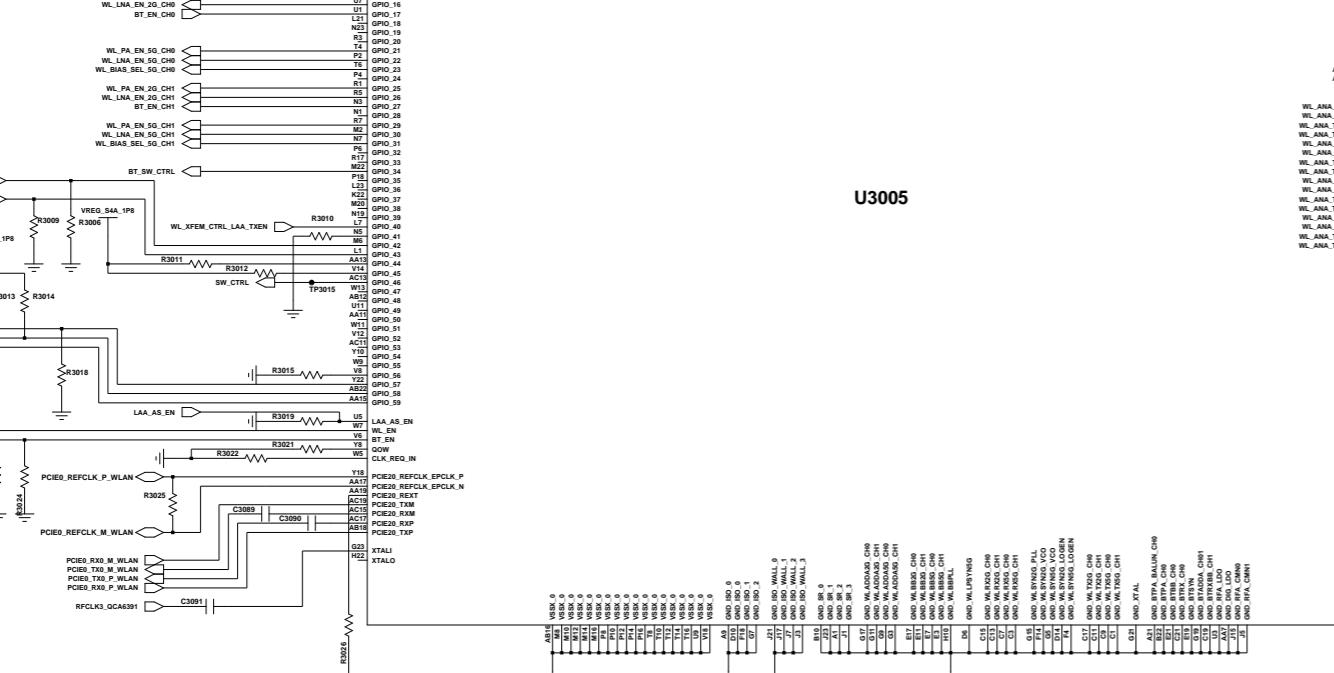
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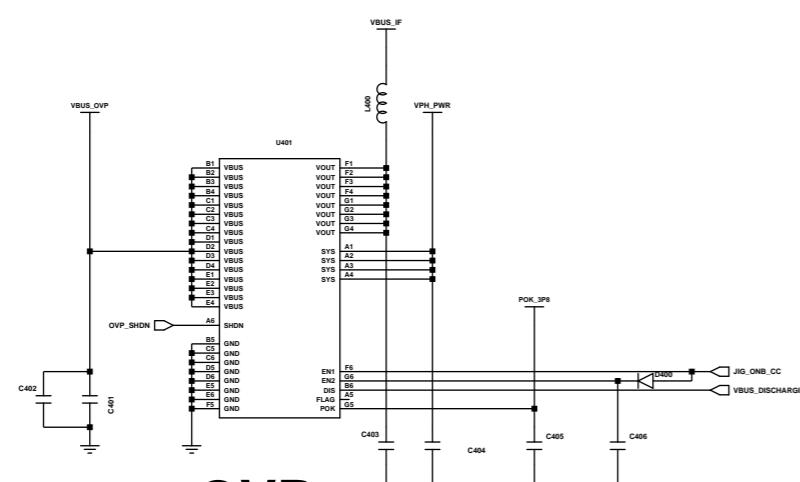
SUB ANT4



11

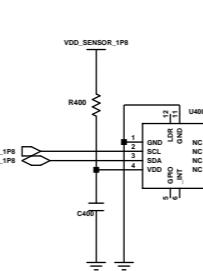


Power

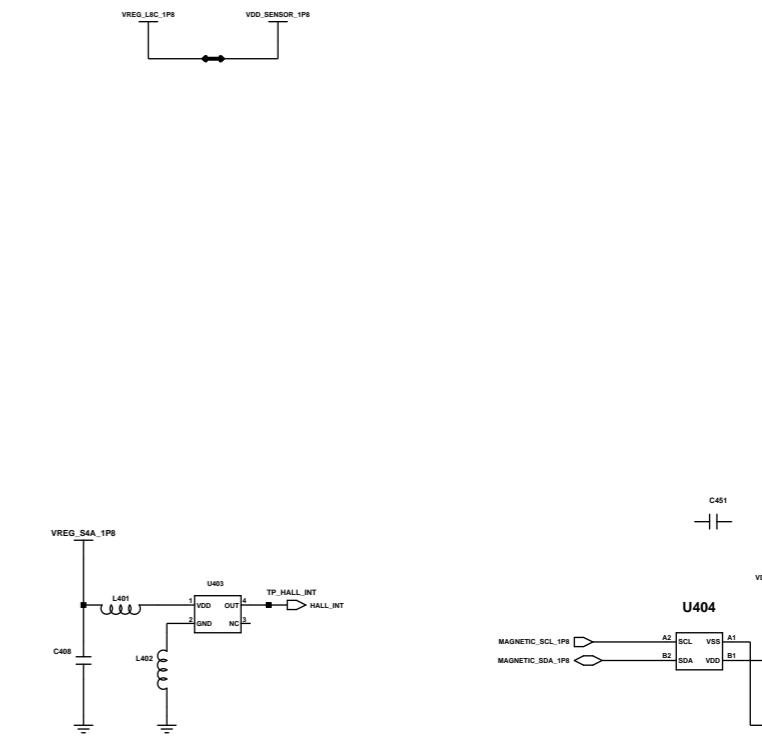


OVP

SENSORS



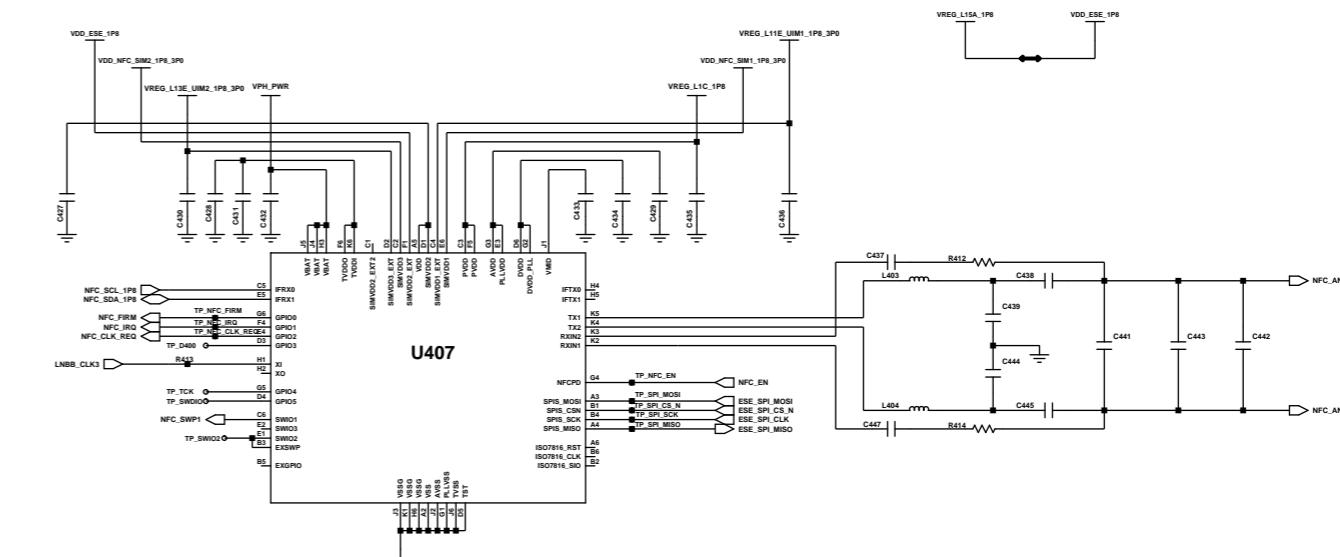
AMBIENT



MAGNETIC SENSOR

6 AXIS SENSOR (GYRO,ACCEL)

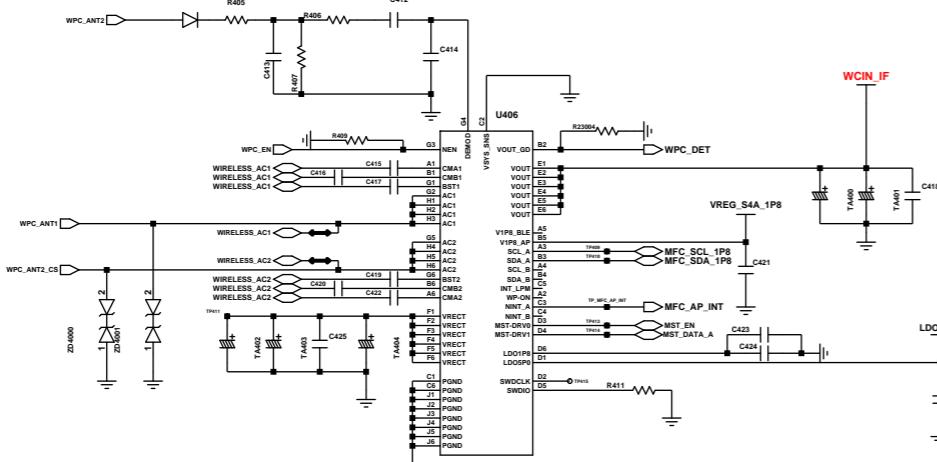
NFC



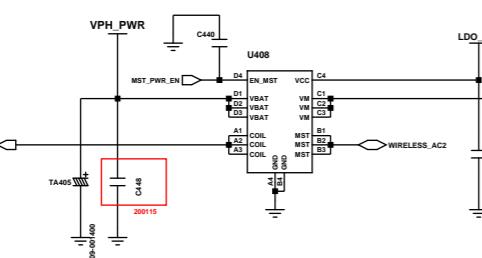
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REV:		Time:	14:00:00
RED CHK:		QA CHK:	
DOC CTRL CHK:		Page:	1
MPG ENGR CHK:			

SM8250 + SDX55M

MFC IC(IDT)



MST Switch

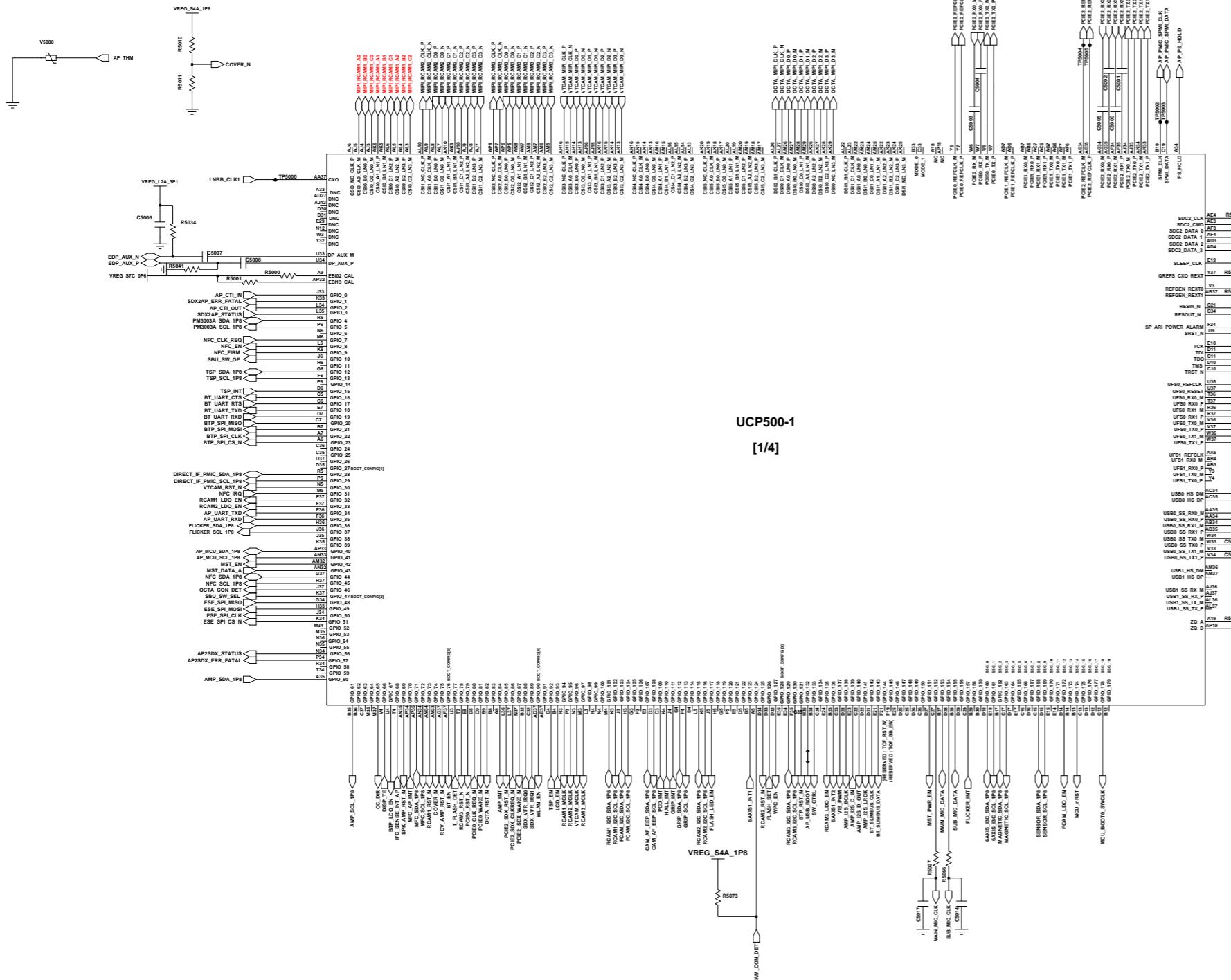


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SM8250

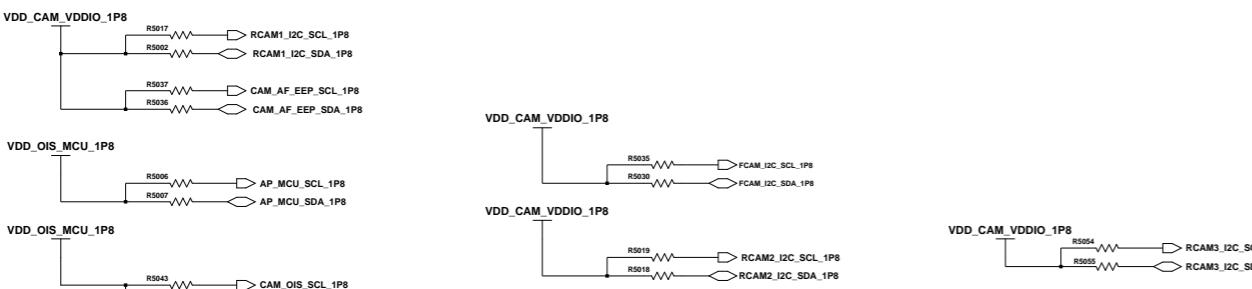
(INTERFACE, GPIO, GND)

System

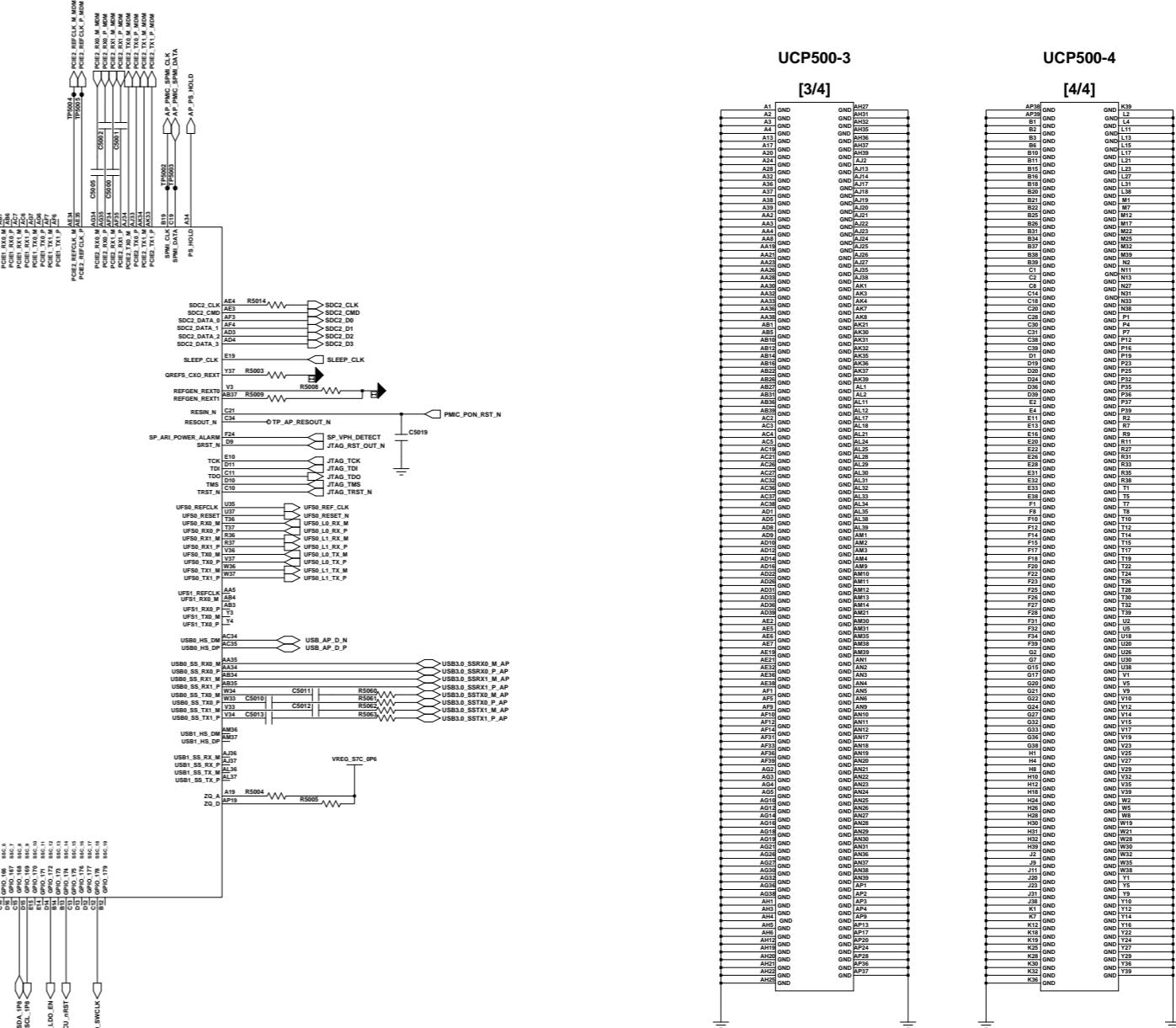


UCP50

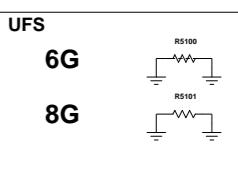
[1]



I2C PULL UP



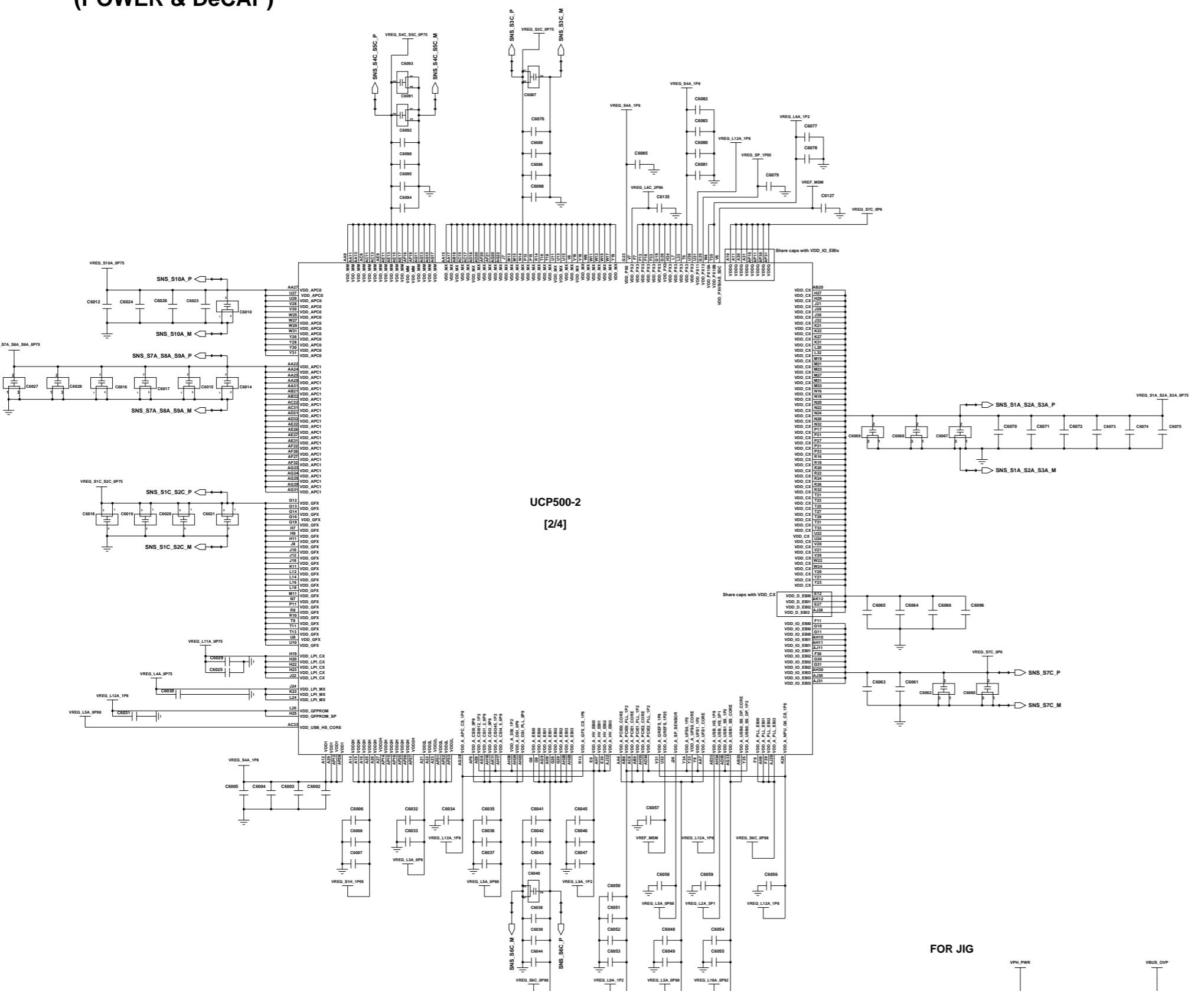
The image shows two rectangular labels, each featuring a barcode and the text 'CON5000' or 'CON5001'. The first label is positioned above the second. Both labels have a small square cutout at the top center.



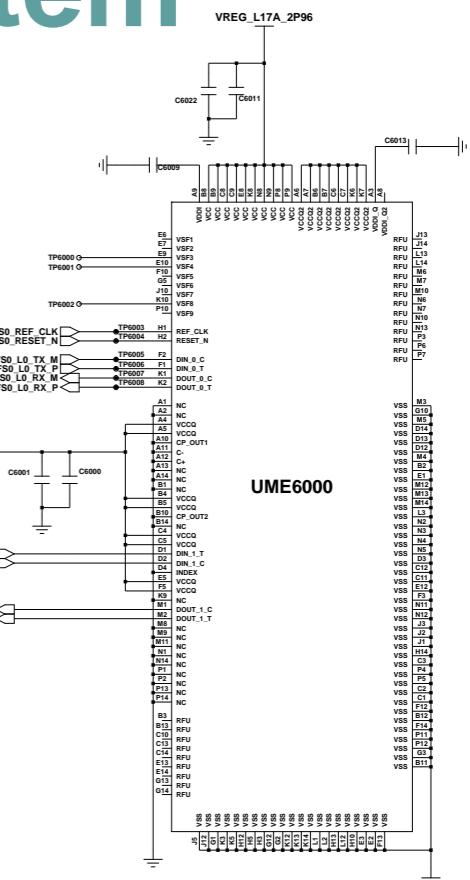
Engineer SEC	
Drawn by: SEC	
R&D CHK:	TITLE: SM8250 + SDX55M
DOC/STR CHK:	
MFG ENGR CHK:	
QC CHK	Drawing Number
gec:	QA CHK

SM8250

(POWER & DeCAP)

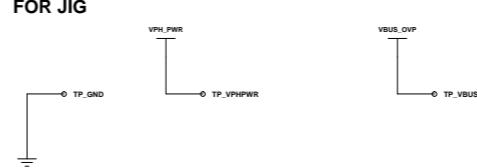
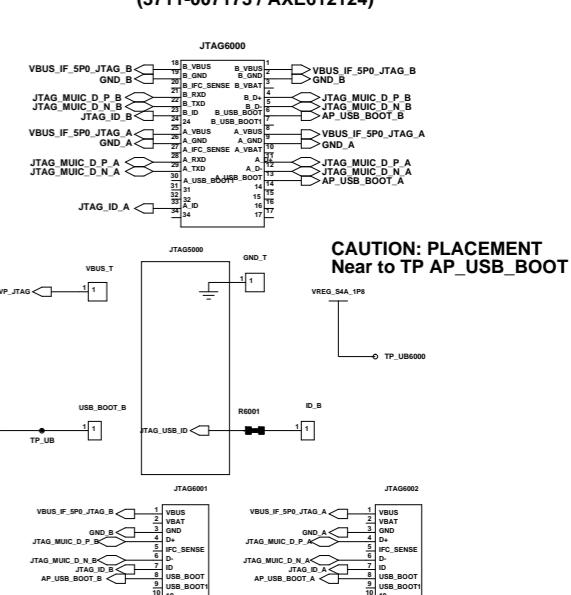


Power System



UFS3.1 128GB / 512GB

AP JTAG CONNECTOR
(2711-007172 / AXE612134)

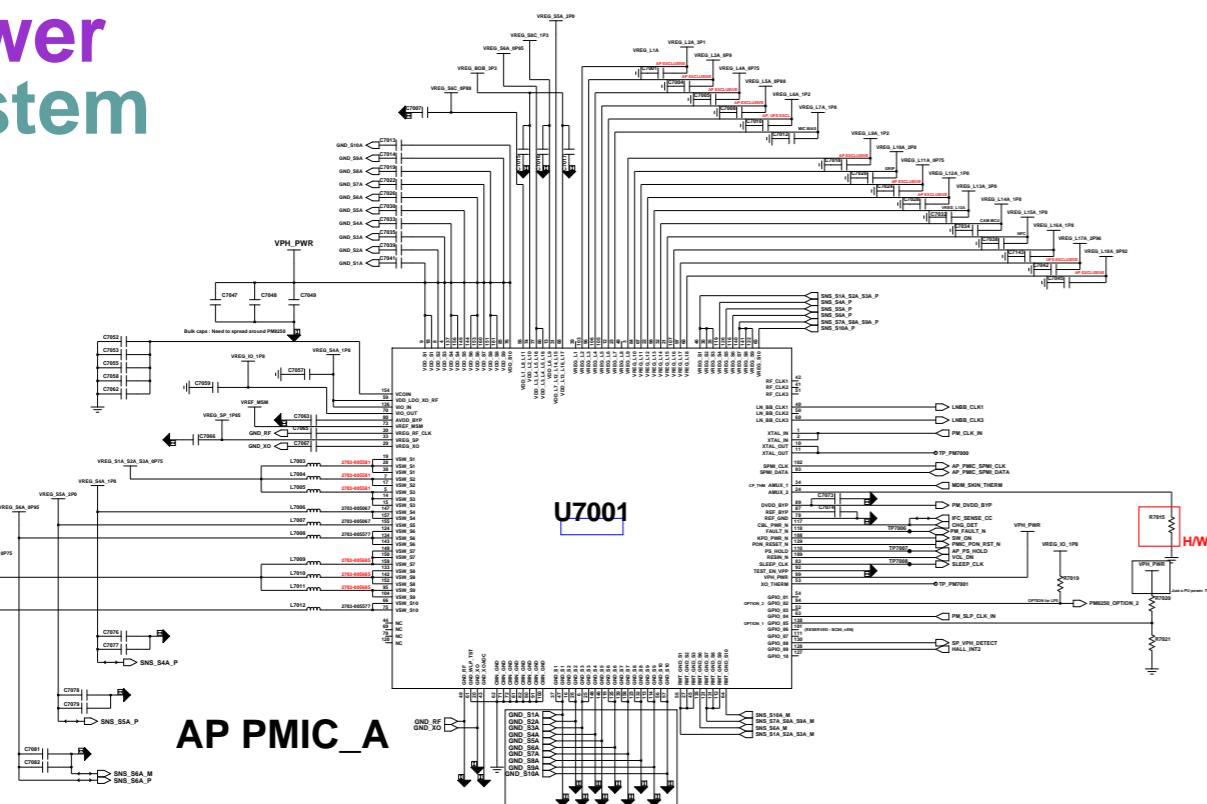


PCB array JTAG

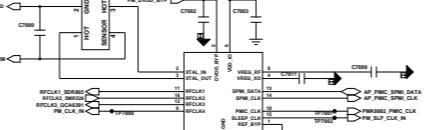
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Drawn by:	SEC	
R&D CHK:	TITLE:	Size:
DOC CTRL CHK:	L	
MFG ENGR CHK:	SM8250 + SDX55M	

AP PMIC set & CLK Generator

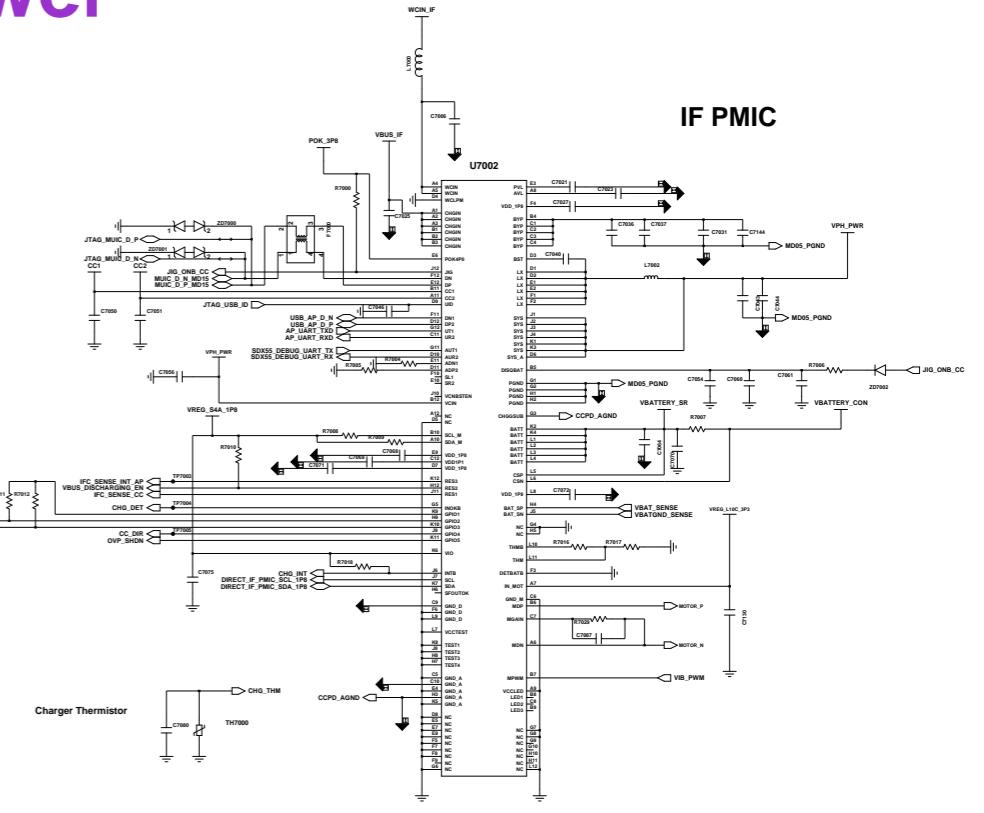
Power System



Clock Generator

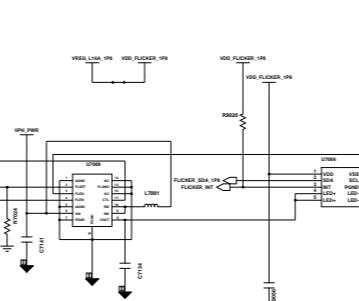


Power



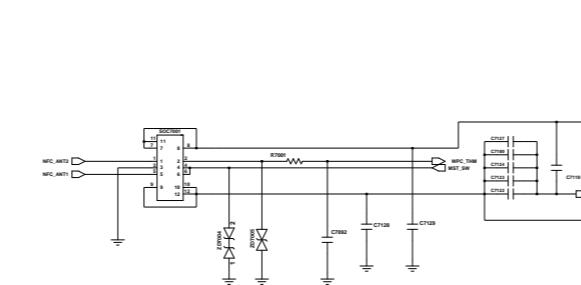
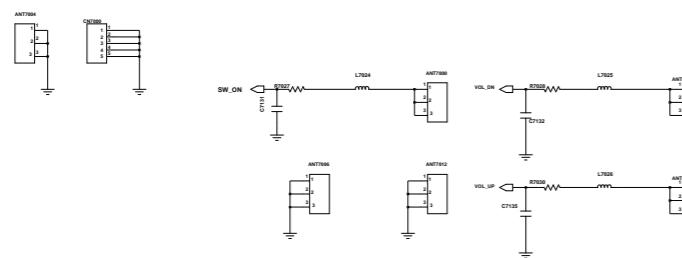
H/W ID table(PM8250 AMUX_2)

HW ID	BOARD REVISION	Value	Mech
00	R8 BRINGUP	6.04K	
01	R8 DV1	9.1K	
02	R8 DV2	12.4K	
03	R8 PV1	18K	
04		22K	
05		30K	
06	R8 PV2	39K	
07		47K	
08		56K	
09		68K	
10		82K	
11		100K	
12		120K	
13		150K	
14		180K	
15		200K	
16		240K	
17		280K	
18		330K	
19		430K	
20		560K	
21		750K	
22		1000K	
23		1500K	
24		3000K	

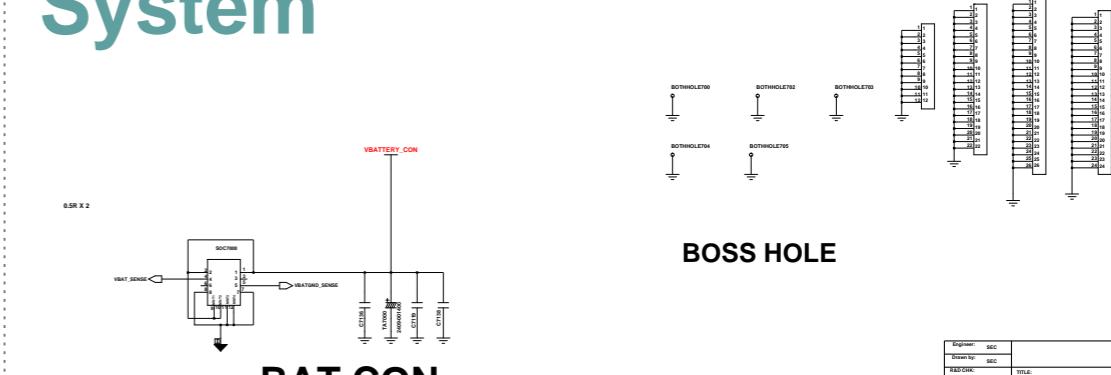


FLASH

System Radiation



System

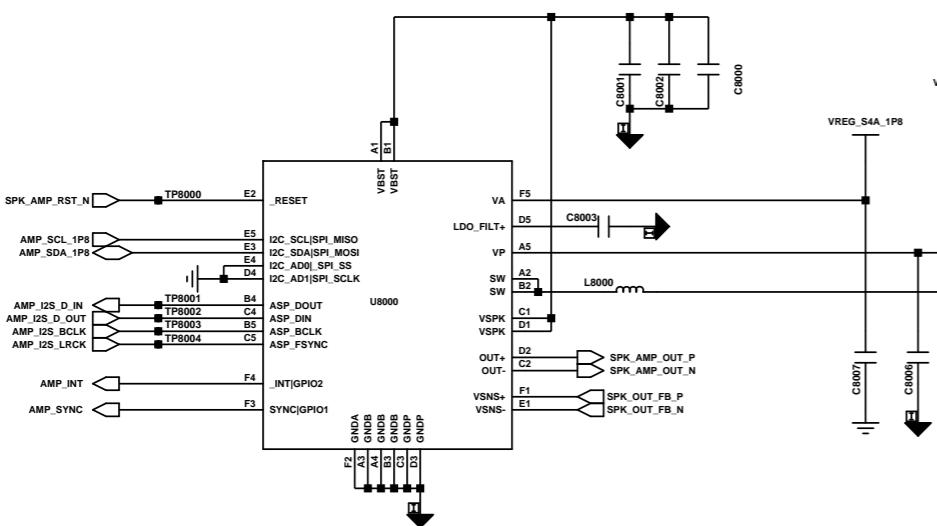


BAT CON

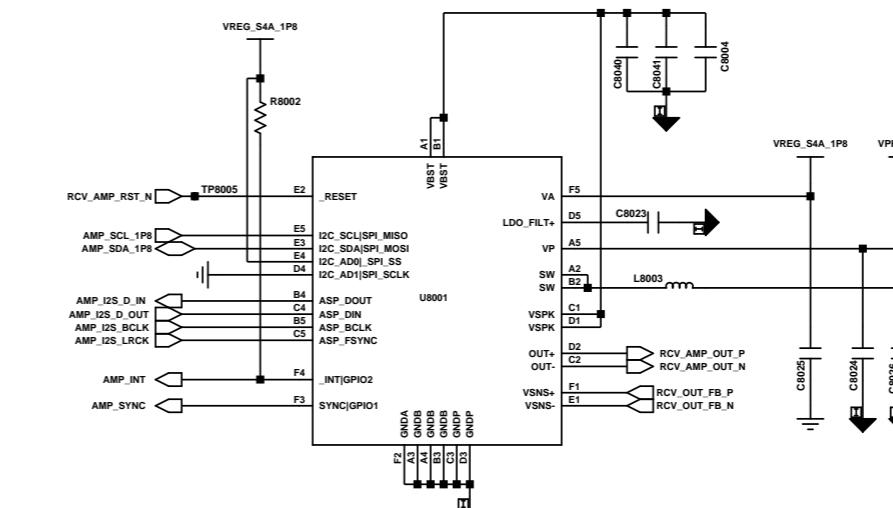
AUDIO PART

AUDIO

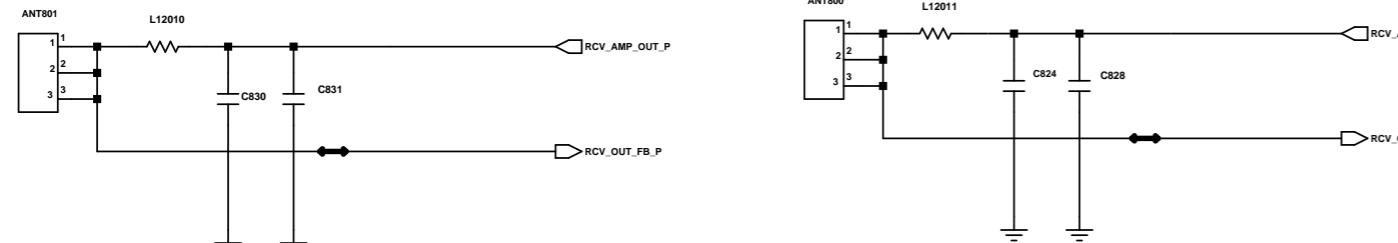
SPK AMP



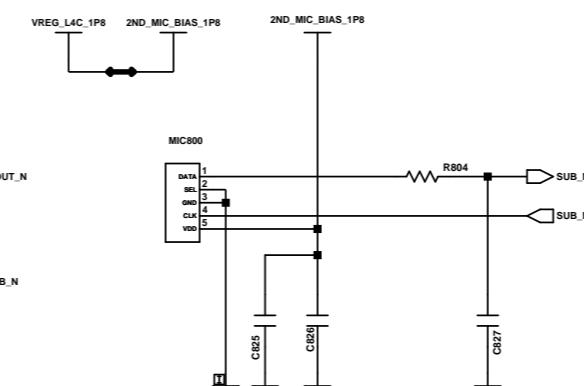
RCV AMP



RCV CONTACT



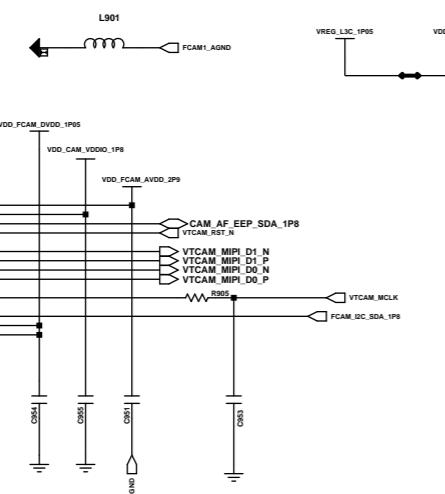
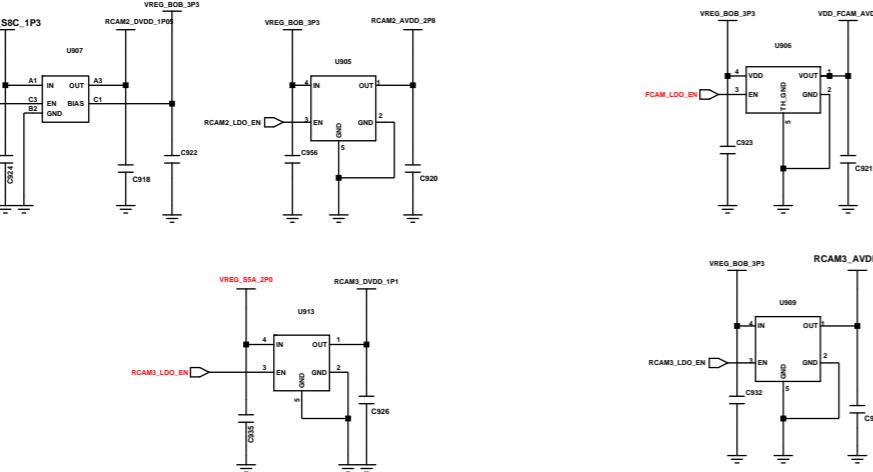
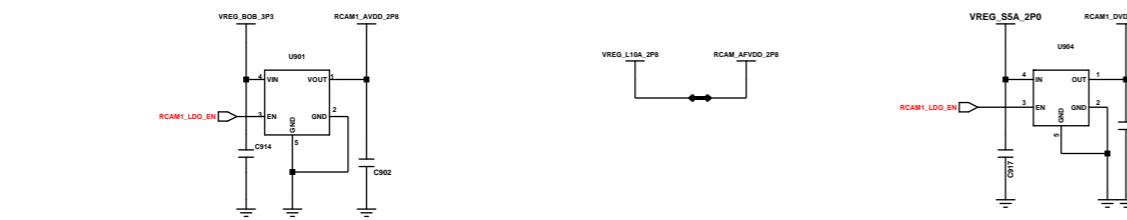
2nd MIC



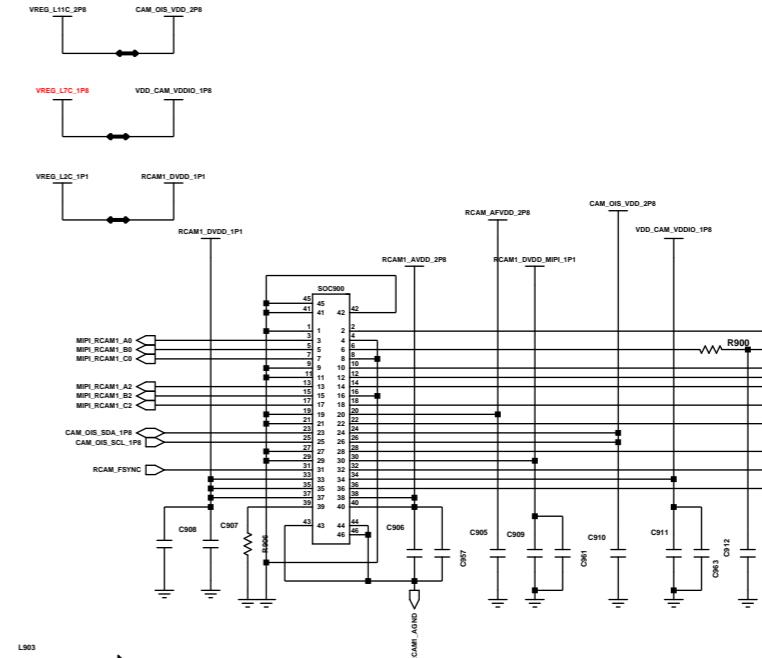
CAMERA

Visual

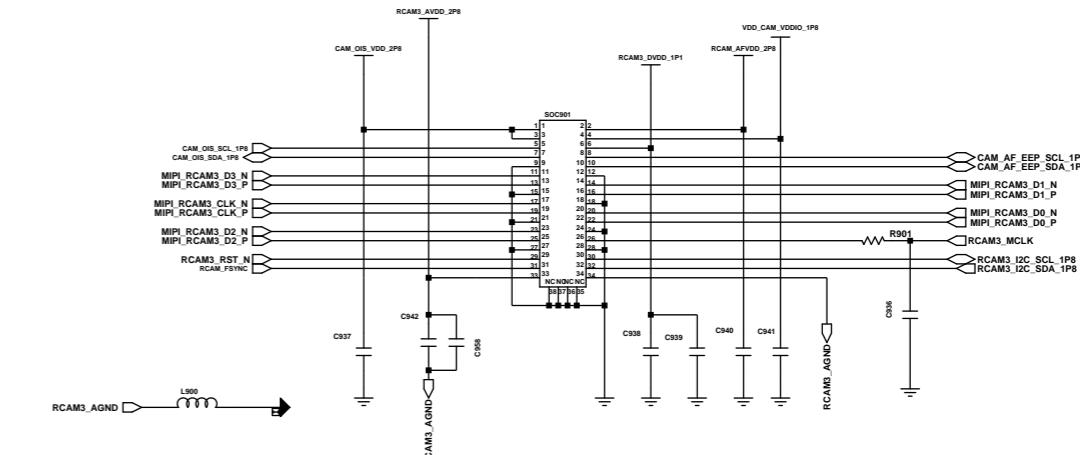
CAM_PMIC



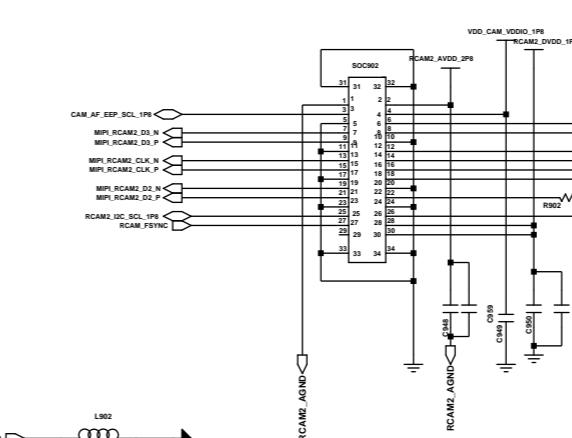
32M FRONT CAM



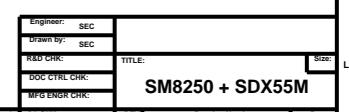
12M 2PD OIS WIDE CAM



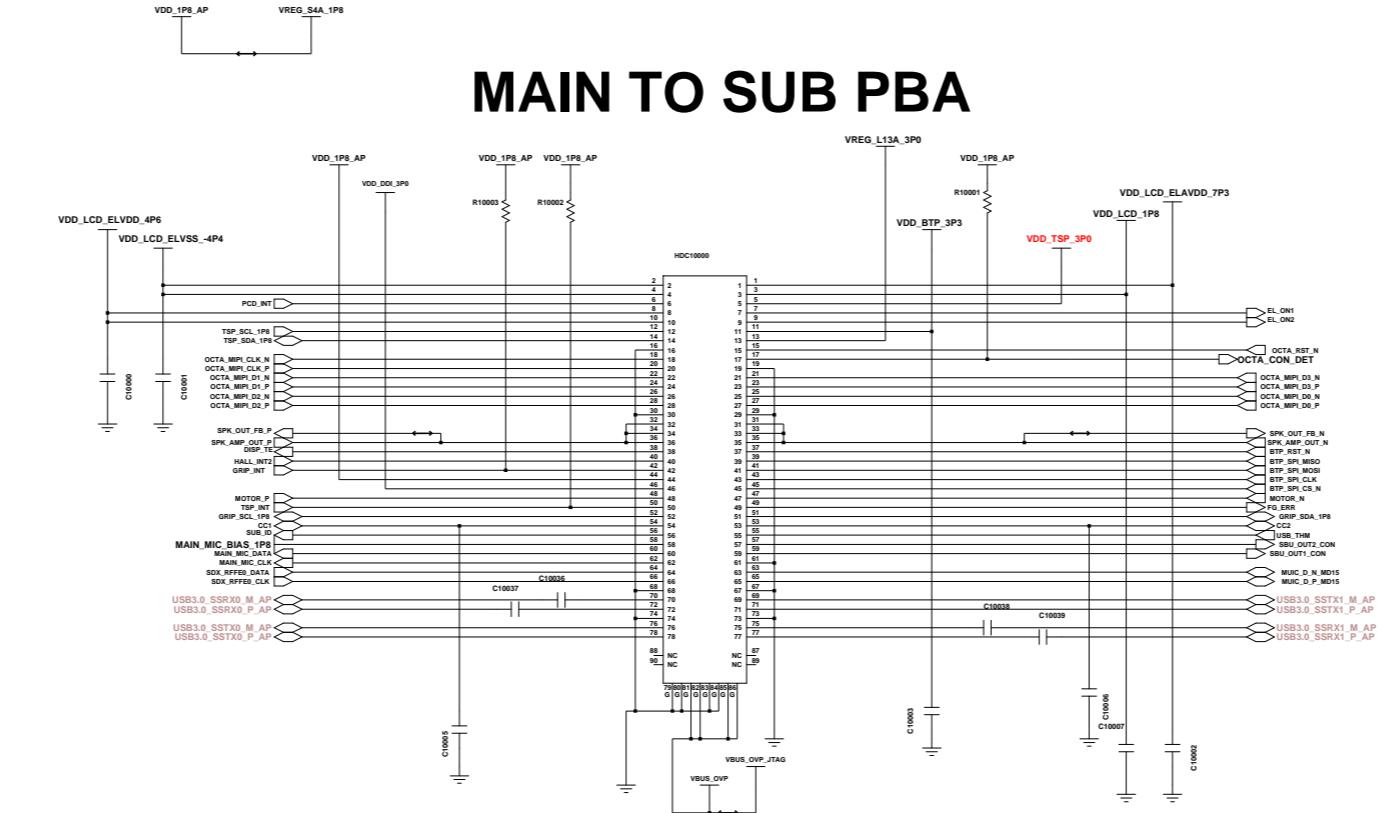
8M TELE CAM



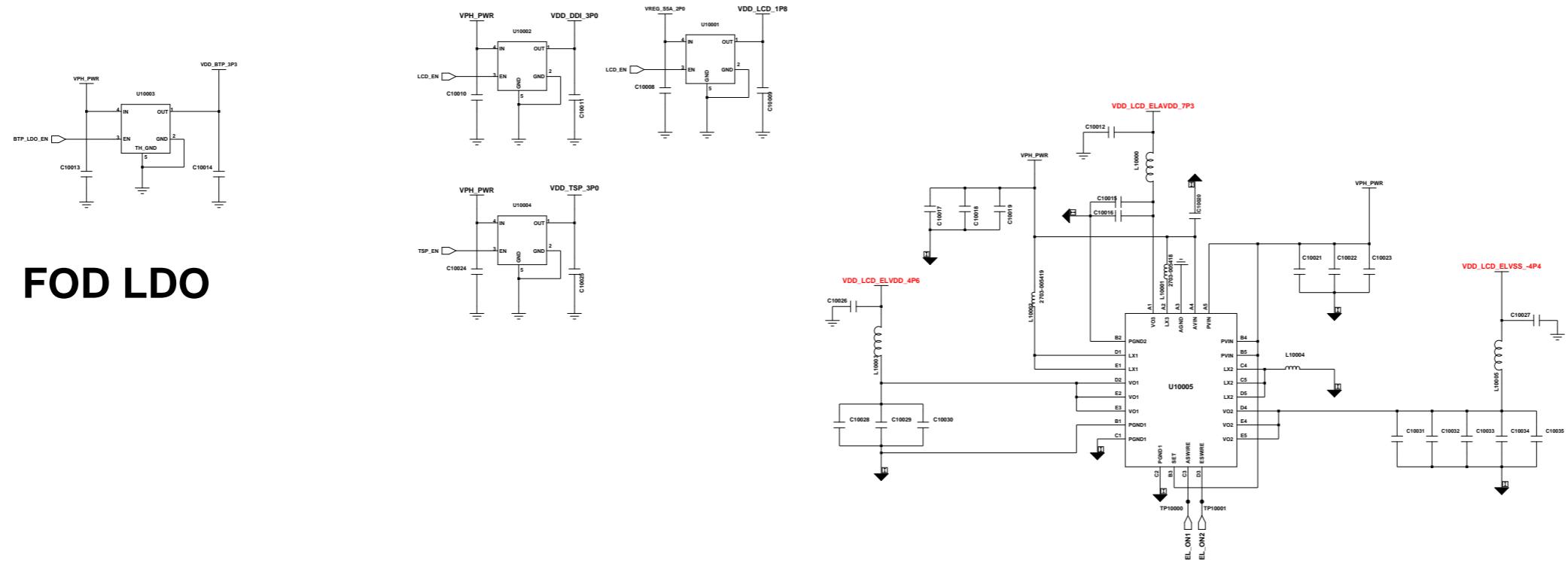
CAM MCU



DISPLAY



DISPLAY

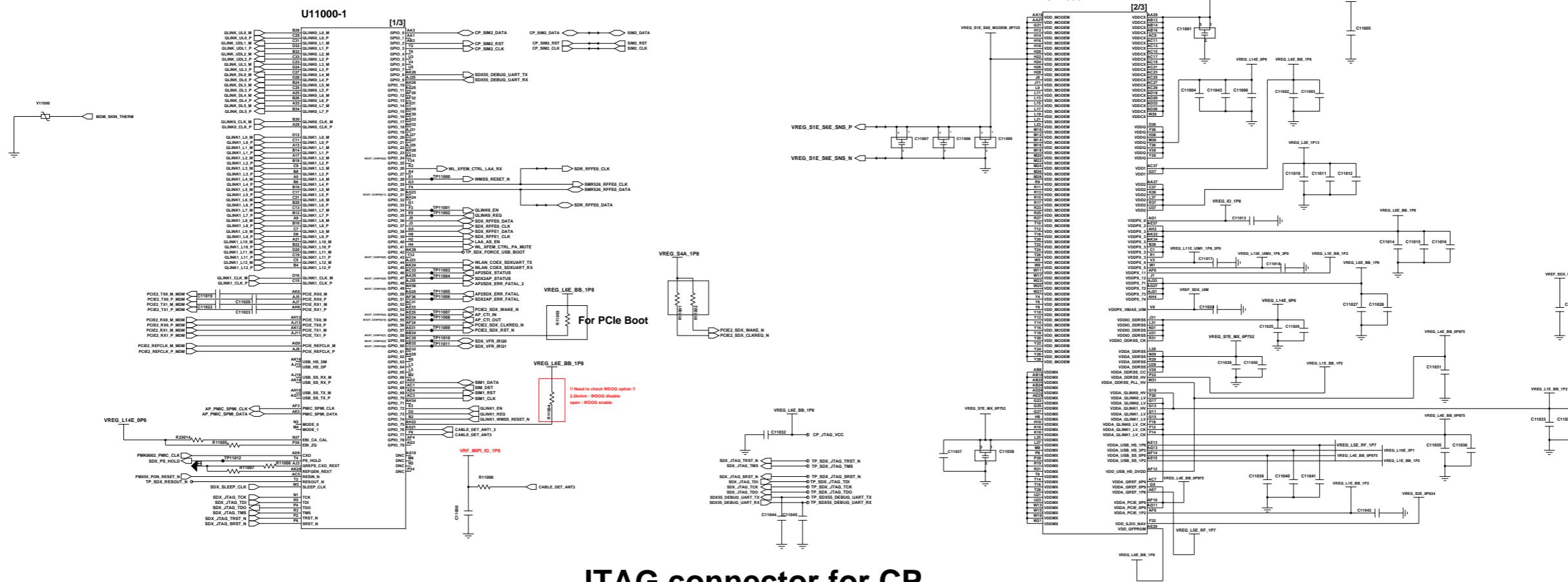


FOD LDO

Visual

SDX55M

System

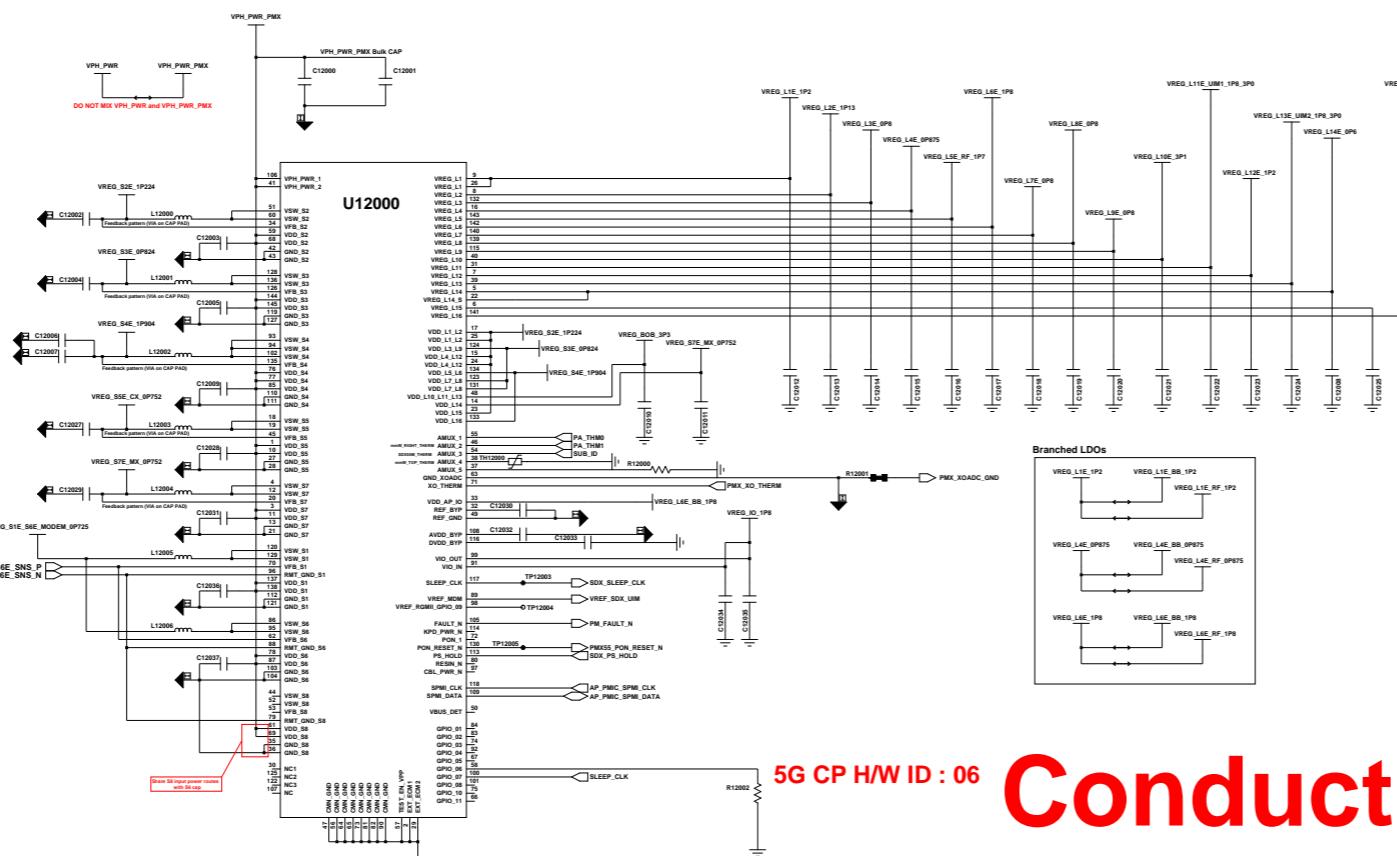


JTAG connector for CP

Engineer:	SEC	SAMSUNG ELECTRONICS	
Drawn by:	SEC		
R&D CHK:		TITLE:	Size:
DOC CTRL CHK:			
MFG ENGR CHK:			
		SM8250 + SDX55M	

CP PMIC

Power



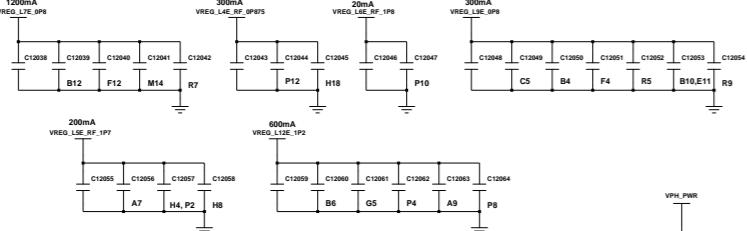
PMX55

CP H/W ID table (PMX55 GPIO_06)

HW ID	BOARD REVISION	Value	Mech
00	R8 BRINGUP	6.04K	
01	R8 DV1	9.1K	
02	R8 DV2	12.4K	KI10
03	R8 PV1	18K	KI10
04		22K	KI20
05		30K	
06	SM-G781W_REV03	39K	KI30
07	SM-G781V_REV03	47K	KI30
08	SM-G781U_REV03	56K	KI40
09	SM-G781U_REV03+B46	68K	KI40
10	SM-G781U_REV03+B46	82K	KI40
11		100K	KI50
12		120K	VY60
13		150K	VY60
14		180K	VY70
15		200K	VY70
16		240K	VY75
17		280K	VY75
18		330K	
19		430K	
20		560K	
21		750K	
22		1000K	
23		1500K	
24		3000K	

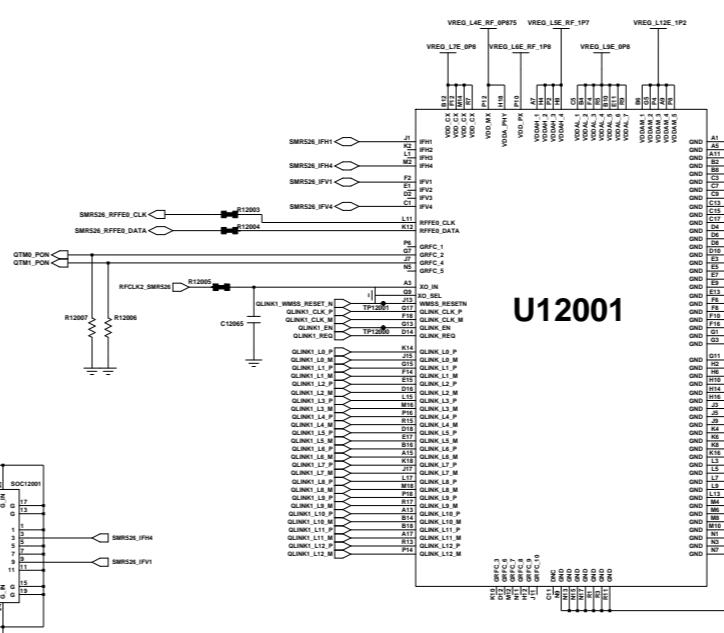
5G IFIC

Radiation

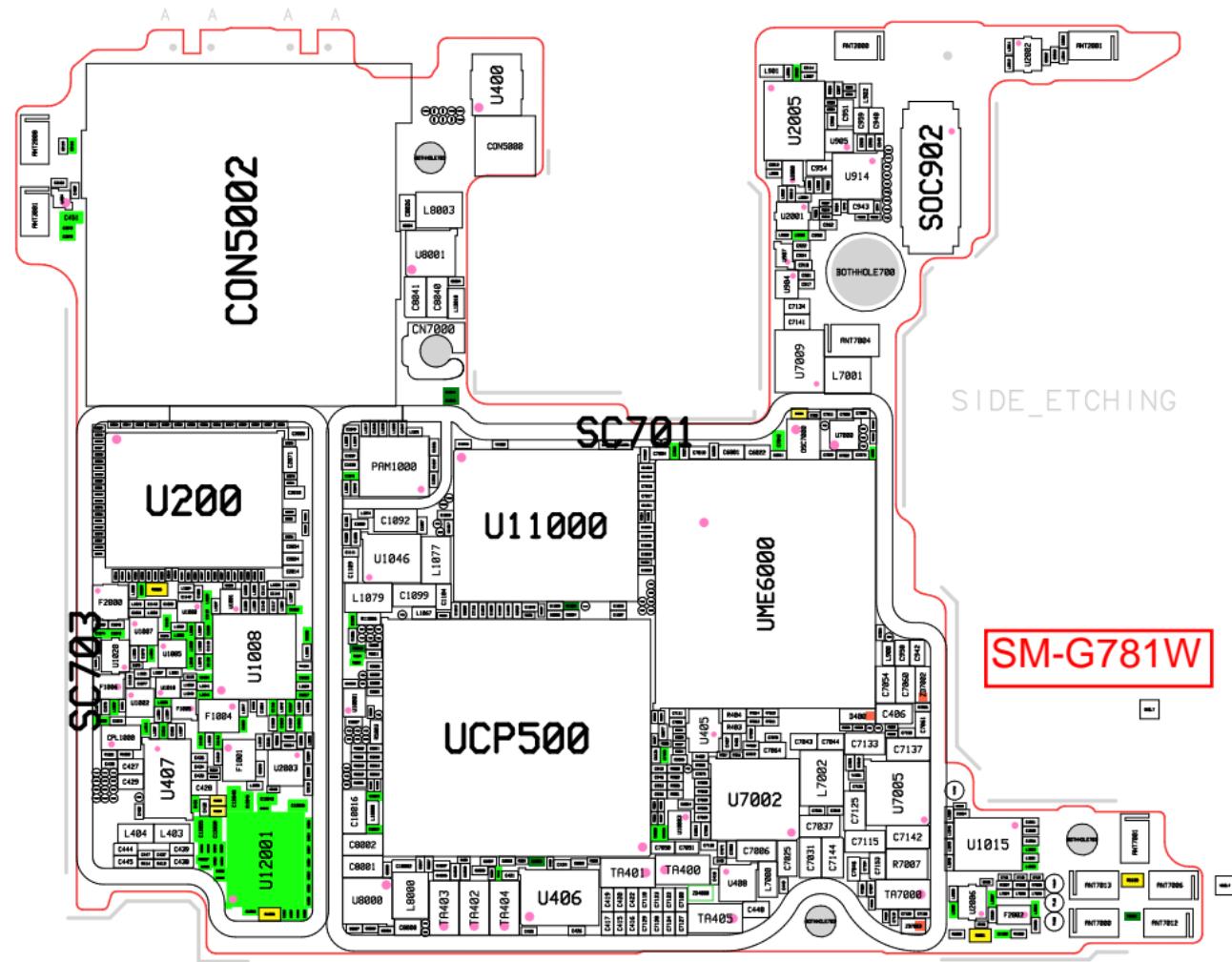


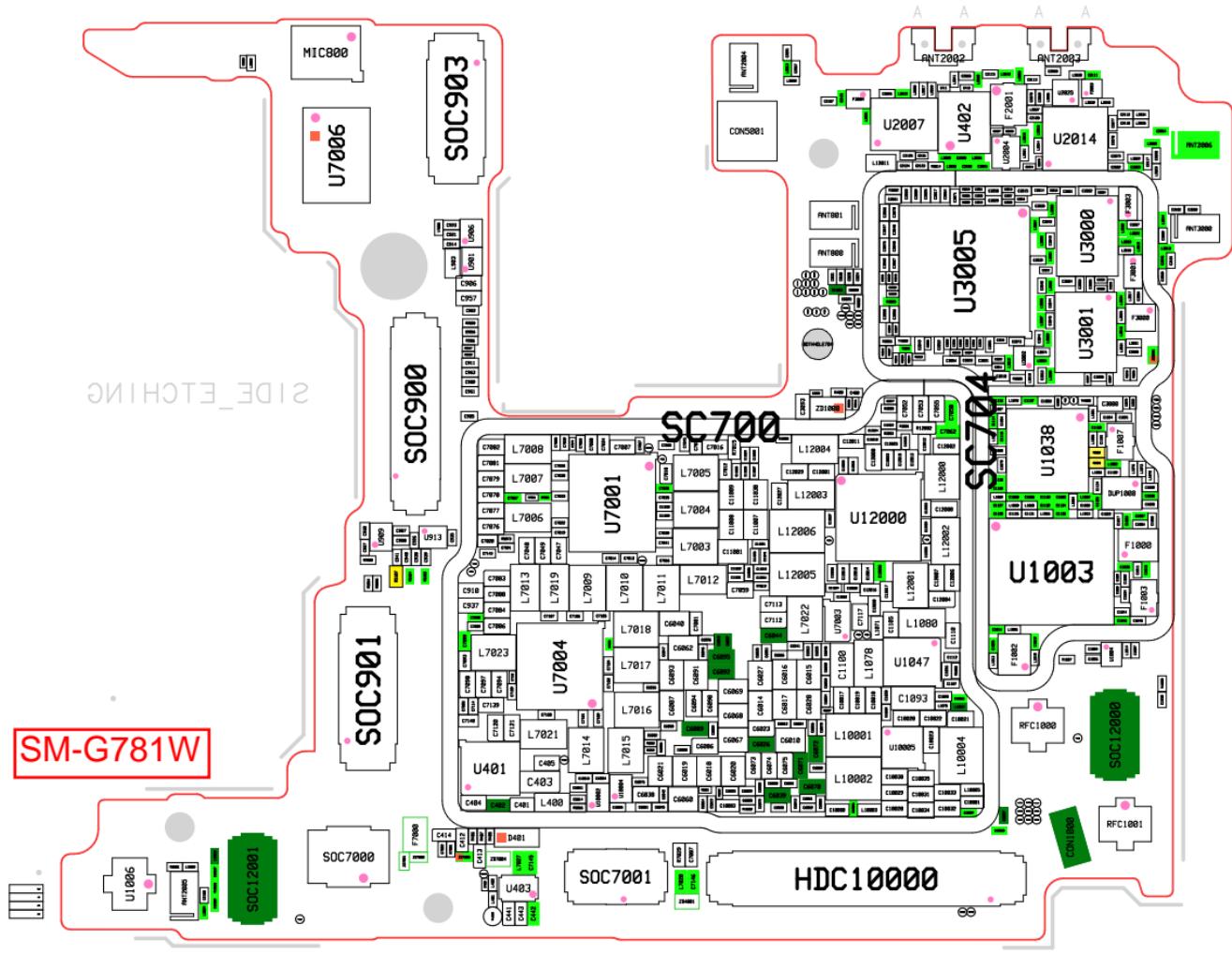
mmW_ANT_CONN (RIGHT)

mmW_ANT_CONN (LEFT)

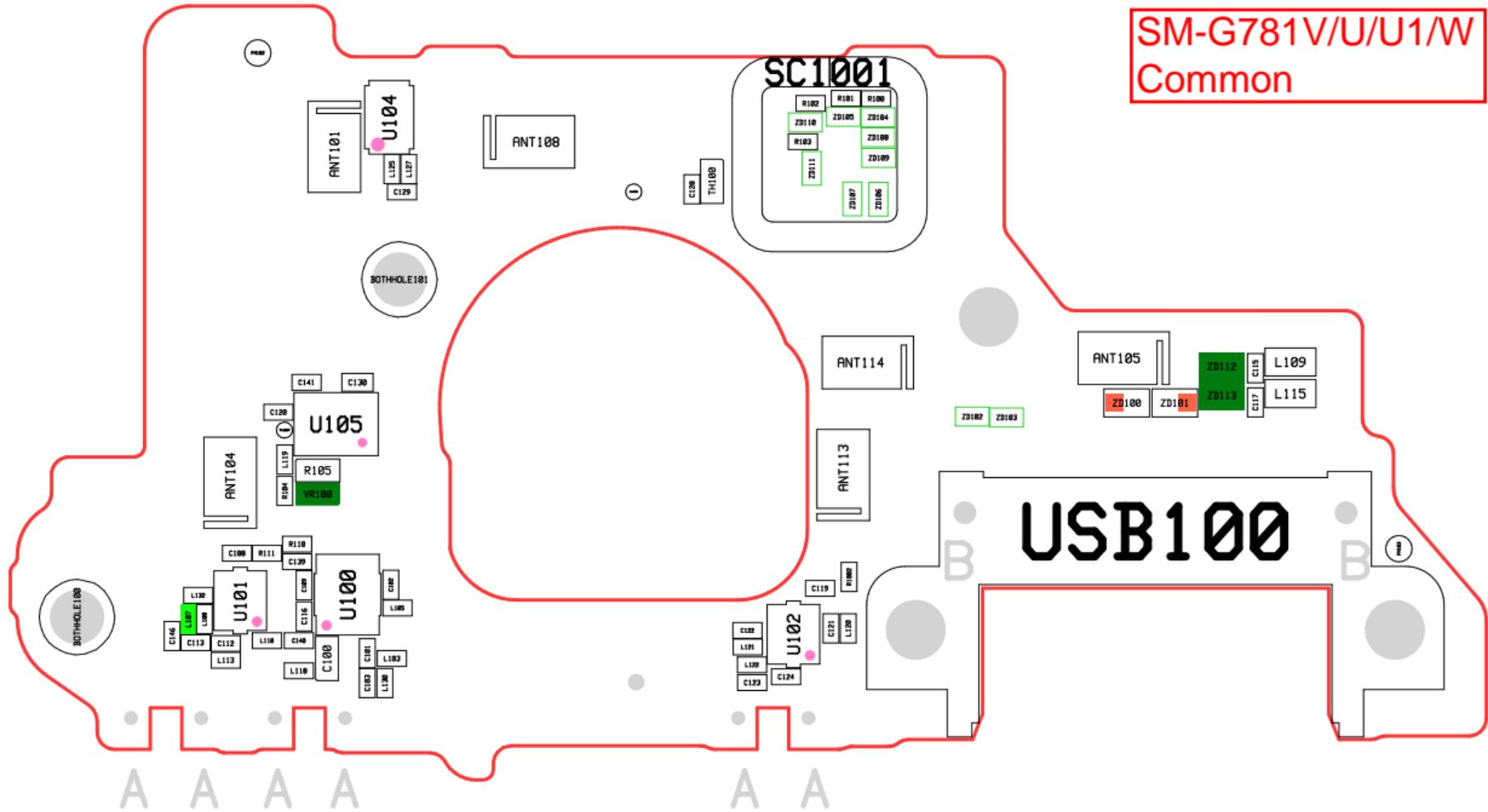


Engineer:	SEC	SAMSUNG ELECTRONICS	
Drawn by:	SEC		
R&D CHK:	TITLE:		
DOC CTRL CHK:	Size:		
MFG ENGR CHK:	SM8250 + SDX55M		
Changed by:	Date Changed:	Time Changed:	Drawing Number:
cad	Thursday, December 1, 2016	3:17:21 pm	Page: 13





SM-G781V/U/U1/W
Common



SM-G781V/U/U1/W

Common

HDC100

SOC101

SUS101

SOC100

ANT102

ANT106

R115
R116

C114 C111

C166
C165
C164
C163
C162
C161

R106
R107
R109
C124

C135
C136

E106
E107
E108

RFS101

CLIP100

L131

RFS100

ANT111

U103

ANT100

ANT103

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